MC9S12XDP512 Device User Guide V02.05

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MC9S12XD-Family

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MC9S12XA-Family

Original Release Date: June 2nd, 2003 Revised: November 18th 2004 Motorola, Inc.

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Revision History

Version Number	Revision Date	Effective Date	Author	Description of Changes
				• 32K SRAM
				Changed COP Configuration Table 15-1Table 15-2
				Added XGATE Address Mapping Figure 1-3
V02.00	21 May 2004			Added Access source signals ACC[2:0]
	2001			Added reduced Threshold for EWAIT pin
				Changed Register Map Table 1-1
				Updated detailed Register Map
				Removed ETEA bit from DBGSR Register
V02.01	8 Jun 2004			DIRECT register moved to address \$0011
				Added Mode description to Section 4.1 Overview
	9 Jul			System STOP/WAIT description
V02.02	9 Jul 2004			Updated Detailed Register Map
				Added Spec Change Summary
V02.03	27 Jul 2004			Updated Spec Change Summary
				Added Thermal Package Characteristics Table A-5
V02.04	13 Oct			Updated Appendix B SPI Electrical Specifications
	2004			Added B.2 External Bus Timing and B.2 External Tag Trigger Timing
				Added Oscillator and PLL electrical characteristics to Table A-18 and Table A-19
V02.05	18 Nov 2004			Added Table 0-1 Derivative Differences
	2001			Added Section 1.5.2 Memory Map Differences MC9S12XDP512 vs MC9S12XDT512/DT384

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Derivative Differences

Table 0-1 shows the MC9S12XD-Family members

Table 0-1 MC9S12XD-Family members¹

Device	Package	Flash	RAM	EEPROM	XGATE	CAN	SCI	SPI	IIC	A/D ²	PWM	I/O ³
0040VDD5404	144LQFP		32K			5	6	3	2	2/24	8	119
9S12XDP512 ⁴	112LQFP		32N			5	4	3	1	2/16	8	91
	144LQFP	512K				3	6	3	1	2/24	8	119
9S12XDT512 ⁵	112LQFP		20K			3	4	3	1	2/16	8	91
	80QFP					3	2	2	1	1/8	7	59
	144LQFP					3	3	3	1	2/24	8	119
9S12XDT384	112LQFP	384K	20K	4K -	yes	3	3	3	1	2/16	8	91
	80QFP					3	3	3	1	1/8	7	59
	144LQFP	256K	16K			3	3	3	1	2/24	8	119
9S12XDT256	112LQFP					3	3	3	1	2/16	8	91
	80QFP					3	3	3	1	1/8	7	59
	144LQFP	200K				1	2	2	1	2/24	8	119
9S12XD256	112LQFP		14K			1	2	2	1	2/16	8	91
	80QFP					1	2	2	1	1/8	7	59
9S12XDG128	112LQFP		10K			2	2	2	1	2/16	8	91
	80QFP	128K	IUK	21/		2	2	2	1	1/8	7	59
0040\\D400	112LQFP	IZON	01/	2K		1	2	2	1	2/16	8	91
9S12XD128	80QFP		8K			1	2	2	1	1/8	7	59
9S12XD64	80QFP	64K	4K	1K		1	2	2	1	1/8	7	59

NOTES:

- 1. All devices will be available in M, V and C temperature options
- 2. A/D is the number of modules/total number of A/D channels.
- 3. I/O is the sum of ports capable to act as digital input or output.
- 4. PC9S12XDP512MFVE and PC9S12XDP512MPVE samples are available to order. Please contact Local sales office. All other derivate parts and temperature variations will be available following MC Qualification (Q2'05).
- 5. PC9S12XDT512MFUE samples are available to order. Please contact Local sales office. All other derivate parts and temperature variations will be available following MC Qualification in (Q2'05).

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Table 0-2 MC9S12XA-Family members

Device	Package	Flash	RAM	EEPROM	XGATE	SCI	SPI	IIC	A/D ¹	PWM	I/O ²	
9S12XA512 ³	144LQFP			- 4K		6	3	2	2/24	8	119	
	112LQFP	512K	32K			4	3	1	2/16	8	91	
	80QFP				412	11/		2	2	1	1/8	7
9S12XA256 ⁴	144LQFP		K 16K		1/00	4	3	1	2/24	8	119	
	112LQFP	256K				yes	4	3	1	2/16	8	91
	80QFP					2	2	1	1/8	7	59	
9S12XA128 ⁵	112LQFP	128K	10K	2K		3	3	1	2/16	8	91	
	80QFP	1201	TUR			2	2	1	1/8	7	59	

NOTES:

- 1. A/D is the number of modules/total number of A/D channels.
- 2. I/O is the sum of ports capable to act as digital input or output.
- 3. MC9S12XA512 samples will be available following MC Qualification (Q2'05), temperature option C and V
- 4. MC9S12XA256 samples will be available following MC Qualification (Q2'05), temperature option C and V
- 5. MC9S12XA128 samples will be available following MC Qualification (Q2'05), temperature option C and V

Pin out explanations:

- 144 Pin Packages
 - Port A = 8, B = 8, C=8, D=8, E = 6 + 2 input only, H = 8, J = 7, K = 8, M = 8, P = 8, S = 8, T = 8, PAD = 24
 - 25 inputs provide Interrupt capability (H = 8, P = 8, J = 7, IRQ, XIRQ)
- 112 Pin Packages
 - Port A = 8, B = 8, E = 6 + 2 input only, H = 8, J = 4, K = 7, M = 8, P = 8, S = 8, T = 8, PAD = 16
 - 22 inputs provide Interrupt capability (H = 8, P = 8, J = 4, IRQ, XIRQ)
- 80 Pin Packages
 - Port A = 8, B = 8, E = 6 + 2 input only, J = 2, M = 6, P = 7, S = 4, T = 8, PAD = 8
 - 11 inputs provide Interrupt capability (P=7, J=2, IRQ, XIRQ)
- CANO can be routed under software control from PM1:0 to pins PM3:2 or PM5:4 or PJ7:6.
- CAN4 pins are shared between IIC0 pins.
- CAN4 can be routed under software control from PJ7:6 to pins PM5:4 or PM7:6.
- Versions with 5 CAN modules will have CAN0, CAN1, CAN2, CAN3 and CAN4
- Versions with 4 CAN modules will have CAN0, CAN1, CAN2 and CAN4.
- Versions with 3 CAN modules will have CAN0, CAN1 and CAN4.
- Versions with 2 SPI modules will have SPI0 and SPI1.
- Versions with 3 SCI modules will have SCI0, SCI1 and SCI2.
- Versions with 4 SCI modules will have SCI0, SCI1, SCI2 and SCI4.

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- Versions with 1 IIC module will have IIC0.
- SPI0 can be routed to either Ports PS7:4 or PM5:2.
- SPI1 pins are shared with PWM3:0; In 144 and 112 pin versions SPI1 can be routed under software control to PH3:0.
- SPI2 pins are shared with PWM7:4; In 144 and 112 pin versions SPI2 can be routed under software control to PH7:4. In 80 pin packages SS-signal of SPI2 is not bonded out!

Ordering Information

The following figure provides an ordering number example for the MC9S12XD-Family devices.

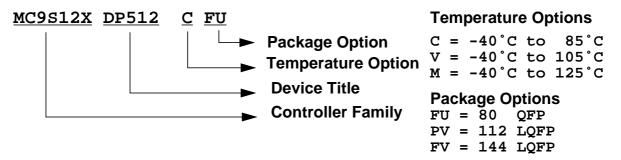


Figure 0-1 Order Part Number Example

Document References

The Device Guide provides information about the MC9S12XDP512 device made up of standard HCS12 blocks and the S12X processor core

This document is part of the customer documentation. A complete set of device manuals includes all the individual Block Guides of the implemented modules. In an effort to reduce redundancy all module specific information is located only in the respective Block Guide. If applicable, special implementation details of the module are given in the block description sections of this document. See **Table 0-3** for names and versions of the referenced documents throughout the Device User Guide.

Table 0-3 Document References¹

rable of Bodament Reference		
User Guide	Version	Document Order Number
S12XCPU Reference Manual	V01	S12XCPUV1/D
External Bus Interface (S12X_EBI) Block Guide	V02	S12XEBIV2/D
Module Mapping Control (S12X_MMC) Block Guide	V02	S12XMMCV2/D
Interrupt (S12X_INT) Block Guide	V01	S12XINTV1/D
Background Debug (S12X_BDM) Block Guide	V02	S12XBDMV2/D
Debug (S12X_DBG) Block Guide	V02	S12XDBGV2/D
Security (S12X9SEC) Block Guide	V02	S12X9SECV2/D
Clock and Reset Generator (CRG) Block User Guide	V06	S12CRGV6/D
Enhanced Capture Timer (ECT_16B8C) Block User Guide	V02	S12ECT16B8CV2/D
Analog to Digital Converter 10 Bit 16 Channel (ATD_10B16C) Block UserGuide	V04	S12ATD10B16CV4/D
Analog to Digital Converter 10 Bit 8 Channels (ATD_10B8C) Block User Guide	V03	S12ATD10B8CV3/D
Inter IC Bus (IIC) Block User Guide	V02	S12IICV2/D
Asynchronous Serial Interface (SCI) Block User Guide	V05	S12SCIV5/D
Serial Peripheral Interface (SPI) Block User Guide	V04	S12SPIV4/D
Pulse Width Modulator 8 Bit 8 Channel (PWM_8B8C) Block User Guide	V01	S12PWM8B8CV1/D
512 K Byte Flash (FTX512K4) Block User Guide	V02	S12XFTX512K4V2/D
4K Byte EEPROM (EETX4K) Block User Guide	V02	S12XEETX4KV2/D
XGATE Block User Guide	V02	S12XGATEV2/D
Motorola Scalable CAN (MSCAN) Block User Guide	V03	S12MSCANV3/D
Voltage Regulator (VREG_3V3) Block User Guide	V05	S12VREG_3V3V5/D
Port Integration Module (PIM_9XD512) Block User Guide	V02	S12XDP512PIMV2/D
Oscillator (OSC_LCP) Block Guide	V01	S12OSCLCPV1/D
Periodic Interrupt Timer (PIT_24B4C) Block Guide	V01	S12PIT24B4CV1/D

NOTES:

1. Specification changes are shown in bold (Maskset L40V vs L15Y)



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Specification Change Summary Maskset L40V vs L15Y

The following section lists all hardware and documentation changes. Hardware changes represent all functional changes on maskset L15Y vs L40V. (i.e. register movements)

XSRAM

- Hardware Changes
 - RAM size increased from 20K to 32K
- Documentation Changes
 - RAM write protection register moved to S12XMMC
 - MC9S12XDP512V2 documentation doesn't include SRAM block guide

XGATE

- Hardware Changes
 - XGVBR became a 16-bit register
 - Layout change of XGMCTL register:

XGMCTL is now a 16-bit register

Added XGFACT bit, when set MCU will never enter System Stop Mode

Added mask bits for all control bits

XGSS is now readable

- New instruction: TFR RD,PC
- Added XGSWEIFM bit to XGMCTL register
- Documentation Changes
 - XGATE Memory map and Software Error conditions described in S12x_mmc

S12X_BDM

- Hardware Changes
 - Debugging XGATE while CPU in STOP/WAIT mode via BDM HW-commands possible
 - Added reserved register at address \$7F_FF0A and \$7F_FF0B.
- Documentation Change
 - Modified command delay information for BDM commands

S12X9SEC

Hardware Change

 Internal visibility available in Emulation Modes if MCU is secured but internal Flash and EEPROM accesses are blocked

PIM

Hardware Changes

- Replaced NOACC with ACC[2:0]
- Added ECLKCTL register at address \$001C
- Added CS3 output

S12X MMC

Hardware Changes

- Changed DIRECT address from \$0012 to \$0011
- Moved MODE register (\$000A) from S12X_EBI
- Renamed register EIFCTL to MEMCTL0 (\$000B).
- Renamed register MISC to MEMCTL1 (\$0013).
- Reorganization of MEMCTL0 bits to allow integrating new features (from [7:5] to [2:0]).
- Reorganization of MEMCTL1 bits to EROMON, ROMHM and ROMON only ([2:0]).
- Added CS3E in MEMCTL0 register (position 3)
- Added third chip select (CS3), and redefined CS2
- XGATE read access to a secured Flash in expanded modes results in XGATE software error
- EROMON bit in register MMCCTL1 is (write never) instead of write once.

Documentation Changes

- Moved write protection features from XSRAM
- Moved features 'chip selects' and 'Chip operating mode control' from S12X_EBI
- Moved 'Modes of Operation' description from S12X_EBI.
- Moved (EIFCTL->MEMCTL0) register (\$000B) from S12X_EBI

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S12X_EBI

Hardware Changes

- Added EBISIZ register for scalable external address bus width (ASIZ[4:0]) and 8-bit data bus option (HDBE)
- Added EXSTR[2:0] bits to MODE register
- Added stretch functionality in Special Test Mode
- Made ECLKX2 available in all modes
- Added EBICTL register at \$000E
- Moved EIFCTL bits NECLK, EDIVx, EWAITE to PIM
- Moved EIFCTL register bit EWAITE to EBICTL
- Moved MODE register bits ITHRS, IVIS to EBICTL
- Removed internal visibility feature in Special Test Mode (along with IVIS register bit)

• Documentation Changes

- Moved addresses \$000A (EIFCTL->MEMCTL0) and \$000B (MODE) to \$12X_MMC Block Guide
- Moved Modes of Operation description to S12X_MMC
- Moved features chip selects and Chip operating mode control to S12X_MMC
- Moved feature Free-running clock outputs to PIM

CRG

Hardware Changes

- Added REFDV5 and REFDV4 bits to REFDV register
- Removed CWAI bit/feature
- Removed ROAWAI bit/feature
- Specification of Oscillator configuration via XCLKS pin has changed
- COP Watchdog Rate CR[2:0] and Mode WCOP specification changed

SPI

Hardware Change

Modified functionality of data reception

VREG3V3

Hardware Changes

- New API rate low register VREGAPIRL at address \$02F5
- New API rate high register VREGAPIRH at address \$02F4
- More precise API divider

DBG

Hardware Changes

- Allows writing COMRV whilst armed
- Changed DBGCNT reset specification
- Changed Trace Buffer pointer specification
- Added Trace Buffer Read Unlock specification
- Added BRK bit specification
- Added Detail Mode trace buffer databus entry alignment
- XGATE Detail Mode trace buffer format changed
- Changed DBGSR[7] specification
- Removed ETEA bit. External tags now always end aligned
- Aligned Detailed Mode Data/Address trace buffer entries
- Simplified comparator access considerations

Table of Contents

Secti	ion 1 Introduction
1.1	Overview
1.2	Features
1.3	Modes of Operation
1.4	Block Diagram
1.5	Device Memory Map
1.5.1	Device Register Memory Map32
1.5.2	MC9S12XDP512/MC9S12XA512 Local to Global Address Mapping34
1.5.3	Logical Address Maps of S12XD and S12XA Family Devices
1.5.4	Detailed Register Map
1.6	Part ID Assignments76
Secti	ion 2 Signal Description
2.1	Device Pinout
2.2	Signal Properties Summary
2.3	Detailed Signal Descriptions
2.3.1	EXTAL, XTAL — Oscillator Pins84
2.3.2	RESET — External Reset Pin
2.3.3	TEST — Test Pin
2.3.4	VREGEN — Voltage Regulator Enable Pin
2.3.5	XFC — PLL Loop Filter Pin
2.3.6	BKGD / MODC — Background Debug and Mode Pin
2.3.7	PAD[23:08] / AN[23:8] — Port AD Input Pin of ATD1
2.3.8	PAD[07:00] / AN[7:0] — Port AD Input Pins of ATD0
2.3.9	PA[7:0] / ADDR[15:8] / IVD[15:8] — Port A I/O Pins
2.3.10	
2.3.11	
2.3.12	PC[7:0] / DATA [15:8] — Port C I/O Pins
2.3.13	
2.3.14	
2.3.15	
2.3.16	
2.3.17	PE4 / ECLK — Port E I/O Pin 4

MC9S12XDP512 Device User diffeescale Semiconductor, Inc.

2.3.18	PE3 / LSTRB / LDS / EROMCTL— Port E I/O Pin 3	88
2.3.19	PE2 / R/W / WE— Port E I/O Pin 2	88
2.3.20	PE1 / IRQ — Port E Input Pin 1	88
2.3.21	PE0 / XIRQ — Port E Input Pin 0	
2.3.22	PH7 / KWH7 / SS2 / TXD5 — Port H I/O Pin 7	89
2.3.23	PH6 / KWH6 / SCK2 / RXD5 — Port H I/O Pin 6	89
2.3.24	PH5 / KWH5 / MOSI2 / TXD4 — Port H I/O Pin 5	89
2.3.25	PH4 / KWH4 / MISO2 / RXD4 — Port H I/O Pin 2	89
2.3.26	PH3 / KWH3 / SS1 — Port H I/O Pin 3	89
2.3.27	PH2 / KWH2 / SCK1 — Port H I/O Pin 2	89
2.3.28	PH1 / KWH1 / MOSI1 — Port H I/O Pin 1	90
2.3.29	PH0 / KWH0 / MISO1 — Port H I/O Pin 0	90
2.3.30	PJ7 / KWJ7 / TXCAN4 / SCL0 / TXCAN0— PORT J I/O Pin 7	90
2.3.31	PJ6 / KWJ6 / RXCAN4 / SDA0 / RXCAN0 — PORT J I/O Pin 6	90
2.3.32	PJ5 / KWJ5 / SCL1 / CS2 — PORT J I/O Pin 5	90
2.3.33	PJ4 / KWJ4 / SDA1 / CS0 — PORT J I/O Pin 4	90
2.3.34	PJ2 / KWJ2 / CS1 — PORT J I/O Pin 2	90
2.3.35	PJ1 / KWJ1 / TXD2 — PORT J I/O Pin 1	91
2.3.36	PJ0 / KWJ0 / RXD2 / CS3 — PORT J I/O Pin 0	91
2.3.37	PK7 / EWAIT / ROMCTL — Port K I/O Pin 7	91
2.3.38	PK[6:4] / ADDR[22:20] / ACC[2:0] — Port K I/O Pin [6:4]	91
2.3.39	PK[3:0] / ADDR[19:16] / IQSTAT[3:0] — Port K I/O Pins [3:0]	91
2.3.40	PM7 / TXCAN3 / TXCAN4 / TXD3 — Port M I/O Pin 7	91
2.3.41	PM6 / RXCAN3 / RXCAN4 / RXD3 — Port M I/O Pin 6	92
2.3.42	PM5 / TXCAN0 / TXCAN2 / TXCAN4 / SCK0 — Port M I/O Pin 5	92
2.3.43	PM4 / RXCAN0 / RXCAN2 / RXCAN4 / MOSI0 — Port M I/O Pin 4	92
2.3.44	PM3 / TXCAN1 / TXCAN0 / SS0 — Port M I/O Pin 3	92
2.3.45	PM2 / RXCAN1 / RXCAN0 / MISO0 — Port M I/O Pin 2	92
2.3.46	PM1 / TXCAN0 — Port M I/O Pin 1	92
2.3.47	PM0 / RXCAN0 — Port M I/O Pin 0	92
2.3.48	PP7 / KWP7 / PWM7 / SCK2 — Port P I/O Pin 7	93
2.3.49	PP6 / KWP6 / PWM6 / SS2 — Port P I/O Pin 6	93
2.3.50	PP5 / KWP5 / PWM5 / MOSI2 — Port P I/O Pin 5	93
2.3.51	PP4 / KWP4 / PWM4 / MISO2 — Port P I/O Pin 4	93
2.3.52	PP3 / KWP3 / PWM3 / SS1 — Port P I/O Pin 3	93
2 3 53	PP2 / KWP2 / PWM2 / SCK1 — Port P I/O Pin 2	93

16

Freescale: Semiconductor, ilpc. 9S12XDP512DGV2/D V02.05

2.3.54	PP1 / KWP1 / PWM1 / MOSI1 — Port P I/O Pin 1	93
2.3.55	PP0 / KWP0 / PWM0 / MISO1 — Port P I/O Pin 0	94
2.3.56	PS7 / SS0 — Port S I/O Pin 7	94
2.3.57	PS6 / SCK0 — Port S I/O Pin 6	94
2.3.58	PS5 / MOSI0 — Port S I/O Pin 5	94
2.3.59	PS4 / MISO0 — Port S I/O Pin 4	94
2.3.60	PS3 / TXD1 — Port S I/O Pin 3	94
2.3.61	PS2 / RXD1 — Port S I/O Pin 2	94
2.3.62	PS1 / TXD0 — Port S I/O Pin 1	94
2.3.63	PS0 / RXD0 — Port S I/O Pin 0	95
2.3.64	PT[7:0] / IOC[7:0] — Port T I/O Pins [7:0]	95
2.4 P	ower Supply Pins	95
2.4.1	VDDX1, VDDX2, VSSX1,VSSX2 — Power & Ground Pins for I/O Drivers	95
2.4.2 Voltage	VDDR1, VDDR2, VSSR1, VSSR2 — Power & Ground Pins for I/O Drivers & for Interr Regulator95	nal
2.4.3	VDD1, VDD2, VSS1, VSS2 — Core Power Pins	95
2.4.4	VDDA, VSSA — Power Supply Pins for ATD and VREG	95
2.4.5	VRH, VRL — ATD Reference Voltage Input Pins	96
2.4.6	VDDPLL, VSSPLL — Power Supply Pins for PLL	96
2.4.7	VREGEN — On Chip Voltage Regulator Enable	97
Sectio	n 3 System Clock Description	
3.1 C	Overview	99
Sectio	n 4 Modes of Operation	
4.1 C)verview	01
4.2 U	lser Modes	01
4.2.1	Normal Expanded Mode	
4.2.2	Normal Single-Chip Mode	01
4.2.3	Special Single-Chip Mode	
4.2.4	Emulation of Expanded Mode	
4.2.5	Emulation of Single-Chip Mode	02
4.2.6	Special Test Mode	
4.3 L	ow Power Modes	
4.3.1	System Stop Modes	02
4.3.2	System Wait Mode	02
433	Run Mode	03

MC9S12XDP512 Device User of the escale Semiconductor, Inc.
4.4 Freeze Mode .103 4.5 Chip Configuration Summary .103 4.5.1 Mode Selection .103 4.5.2 ROMON and EROMON Configuration .103 4.5.3 Oscillator Configuration .104 4.5.4 Voltage Regulator Control .104 4.6 Security. .104
Section 5 Resets and Interrupts
5.1 Overview. 105 5.2 Vectors. 105 5.2.1 Vector Table. 105 5.3 Effects of Reset 107 5.3.1 I/O pins. 108 5.3.2 Memory. 108
Section 6 S12X_CPU Block Description
Section 7 S12X_MMC Block Description
Section 8 S12_XEBI Block Description
Section 9 S12_XINT Block Description
Section 10 S12X_DBG Block Description
Section 11 S12X_BDM Block Description
Section 12 XGATE Block Description
Section 13 Periodic Interrupt Timer (PIT) Block Description
Section 14 Oscillator (OSC_LCP) Block
Section 15 Clock and Reset Generator (CRG) Block Description

Section 16 Enhanced Capture Timer (ECT) Block Description

A.1

Section 17 10 Bit 8 channel Analog to Digital Converter (ATD0) Block Do	e -
scription	

Section 18 10 Bit 16 Channel	Analog to Digital	Converter	(ATD1) Bloc	k De-
scription				

Section	19 Inter-IC	Bus (IIC)) Block	Description
---------	-------------	-----------	---------	--------------------

Section 20 Serial Communications Interface (S	SCI)	Block Descrip	ption
---	------	----------------------	-------

Section 21 Serial Peripheral Interface (SPI) Block Description
--

Section 22 Pulse Width Modulator (PWM) Block Description
--

Section 23 Flash EEPROM 512K Block Description

Section 24 EEPROM 4K Block Description

Section 25 MSCAN Block Description

Section 26 Port Integration Module (PIM) Block Description

Section 27 Voltage Regulator (VREG_3V3) Block Description

27.1	Recommended PCB Layout	11	13	3

Appendix A Electrical Characteristics

A.1.1	Parameter Classification	
A.1.2	Power Supply	
A.1.3	Pins	
A.1.4	Current Injection	
A.1.5	Absolute Maximum Ratings	
A.1.6	ESD Protection and Latch-up Immunity	
A.1.7	Operating Conditions	
A.1.8	Power Dissipation and Thermal Characteristics	
A.1.9	I/O Characteristics	126
A.1.10	Supply Currents	
۸ ۵	ATD Characteristics	101

MC9S12XDP512 Device User of the escale Semiconductor, Inc.

A.2.1	ATD Operating Characteristics1	131
A.2.2	Factors influencing accuracy	132
A.2.3	ATD accuracy1	133
A.3	NVM, Flash and EEPROM	137
A.3.1	NVM timing	137
A.3.2	NVM Reliability1	139
A.4	Voltage Regulator	141
A.5	Reset, Oscillator and PLL	143
A.5.1	Startup	143
A.5.2	Oscillator	144
A.5.3	Phase Locked Loop	146
A.6	MSCAN	151
Appe	endix B Electrical Specifications	
B.1	SPI Timing	153
B.1.1	Master Mode	153
B.1.2	Slave Mode1	155
B.2	External Bus Timing	157
B.2.1	Normal Expanded Mode (external wait feature disabled)	158
B.2.2	Normal Expanded Mode (external wait feature enabled)	160
B.2.3	Emulation Single-Chip Mode (without wait states)	164
B.2.4	Emulation Expanded Mode (with optional access stretching)	166
B.3	External Tag Trigger Timing1	169
Appe	endix C Package Information	
C.1	General	171
C.2	144-pin LQFP1	172

C.2	144-pin LQFP	172
C.3	112-pin LQFP package	173
C.4	80-pin QFP package	174

List of Figures

Figure 0-1	Order Part Number Example	8
Figure 1-1	MC9S12XDP512 Block Diagram	30
Figure 1-2	Local to Global Address Mapping S12X_CPU/S12X_BDM	34
Figure 1-3	Local to Global Address Mapping XGATE	35
Figure 1-4	MC9S12XDP512/MC9S12XDT512/MC9S12XA512 Memory Map	36
Figure 1-5	MC9S12XDT384 Memory Map	37
Figure 1-6	MC9S12XDT256/MC9S12XD256/MC9S12XA256 Memory Map	38
Figure 1-7	MC9S12XD128/MC9S12XDG128/MC9S12XA128 Memory Map	39
Figure 1-8	MC9S12XD64 Memory Map	40
Figure 2-1	MC9S12XD-Family Pin Assignment 144 LQFP Package	77
Figure 2-2	MC9S12XDP512 Pin assignments 112 LQFP Package	79
Figure 2-3	MC9S12XDP512 Pin assignments 80 QFP Package	
Figure 2-4	PLL Loop Filter Connections	85
Figure 2-5	Loop Controlled Pierce Oscillator Connections (PE7=1)	87
Figure 2-6	Full Swing Pierce Oscillator Connections (PE7=0)	87
Figure 2-7	External Clock Connections (PE7=0)	87
Figure 3-1	Clock Connections	99
Figure 27-1	LQFP144 recommended PCB layout	115
Figure 27-2	LQFP112 recommended PCB layout	116
Figure 27-3	QFP80 recommended PCB layout	117
Figure A-1	ATD Accuracy Definitions	135
Figure A-2	Basic PLL functional diagram	146
Figure A-3	Jitter Definitions	148
Figure A-4	Maximum bus clock jitter approximation	148
Figure B-1	SPI Master Timing (CPHA=0)	153
Figure B-2	SPI Master Timing (CPHA=1)	154
Figure B-3	SPI Slave Timing (CPHA=0)	155
Figure B-4	SPI Slave Timing (CPHA=1)	156
Figure B-5	Example 1a: Normal Expanded Mode - Read Followed by Write{statement	nt} . 158
Figure B-6	Example 1b: Normal Expanded Mode - Stretched Read Access	160
Figure B-7	Example 1b: Normal Expanded Mode - Stretched Write Access	161
Figure B-8	Example 2a: Emulation Single-Chip Mode - Read Followed by Write	164
Figure B-9	Example 2b: Emulation Expanded Mode - Read with 1 Stretch Cycle	166

MC9S12XDP512 Device User of the escale Semiconductor, Inc.

Figure B-10	Example 2b: Emulation Expanded Mode - Write with 1 Stretch Cycle	167
Figure B-11	External Trigger Timing	169
Figure 27-4	144-pin LQFP Mechanical Dimensions (case no. 918-03	172
Figure C-1	112-pin LQFP mechanical dimensions (case no. 987)	173
Figure C-2	80-pin QFP Mechanical Dimensions (case no. 841B)	174

List of Tables

Table 0-1	MC9S12XD-Family members	5
Table 0-2	MC9S12XA-Family members	6
Table 0-3	Document References	9
Table 1-1	Device Register Memory Map	32
Table 1-2	Assigned Part ID Numbers	76
Table 2-1	Signal Properties Summary	81
Table 2-2	MC9S12XDP512 Power and Ground Connection Summary	96
Table 4-1	Mode selection	.103
Table 4-2	Clock Selection Based on PE7	.104
Table 4-3	Voltage Regulator VREGEN	.104
Table 5-1	Interrupt Vector Locations	.105
Table 15-1	Initial COP Rate Configuration	.110
Table 15-2	Initial WCOP Configuration	.110
Table 17-1	ATD0 External Trigger Sources	.111
Table 18-1	ATD1 External Trigger Sources	.112
Table 27-1	Recommended decoupling capacitor choice	.114
Table A-1	Absolute Maximum Ratings	.121
Table A-2	ESD and Latch-up Test Conditions	.122
Table A-3	ESD and Latch-Up Protection Characteristics	.122
Table A-4	Operating Conditions	.123
Table A-5	Thermal Package Characteristics	.125
Table A-6	3.3V I/O Characteristics	.126
Table A-7	5V I/O Characteristics	.127
Table A-8	I/O Characteristics for Port C, D, PE5, PE6 and PK7 for reduced input voltage	400
thresholds	Comple Compant Characteristics	
	Supply Current Characteristics	
	ATD Operating Characteristics 5V	
	ATD Operating Characteristics 3.3V	
	ATD Conversion Portermones 51/	
	ATD Conversion Performance 5V	
	ATD Conversion Performance 3.3V	
	NVM Timing Characteristics	
rable A-16	NVM Reliability Characteristics	. 139

MC9S12XDP512 Device User of the escale Semiconductor, Inc.

Table 27-2	Voltage Regulator Electrical Characteristics
Table A-17	Startup Characteristics143
Table A-18	Oscillator Characteristics
Table A-19	PLL Characteristics
Table A-20	MSCAN Wake-up Pulse Characteristics151
Table B-1	Measurement Conditions
Table B-2	SPI Master Mode Timing Characteristics
Table B-3	SPI Slave Mode Timing Characteristics
Table B-4	Example 1a: Normal Expanded Mode Timing VDD35=5.0V (EWAITE = 0) 159
Table B-5 All values: 1	Example 1a: Normal Expanded Mode Timing VDD35=3.0V (EWAITE = 0) To Be Defined!
Table B-6	Example 1b: Normal Expanded Mode Timing VDD35=5.0V (EWAITE = 1) 162
Table B-7 All values: 1	Example 1b: Normal Expanded Mode Timing VDD35=3.0V (EWAITE = 1) To Be Defined!
Table B-8	Example 2a: Emulation Single-Chip Mode Timing VDD35=5.0V (EWAITE = 0).165
Table B-9	Example 2b: Emulation Expanded Mode Timing VDD35=5.0V (EWAITE = 0)168
Table B-10	External Tag Trigger Timing VDD35=5.0V

Section 1 Introduction

1.1 Overview

The MC9S12XD family will retain the low cost, power consumption, EMC and code-size efficiency advantages currently enjoyed by users of Motorola's existing 16-Bit MC9S12 MCU family.

Based around an enhanced S12 core, the MC9S12XD-Family will deliver 2 to 5 times the performance of a 25MHz S12 whilst retaining a high degree of pin and code compatibility with the S12.

The MC9S12XD-Family introduces the performance boosting XGATE module. Using enhanced DMA functionality, this parallel processing module offloads the CPU by providing high speed data processing and transfer between peripheral modules, RAM and I/O ports. Providing up to 80MIPS of performance additional to the CPU, the XGATE can access all peripherals and the RAM block.

The MC9S12XDP512 is composed of standard on-chip peripherals including 512K bytes of Flash EEPROM, 32K bytes of RAM, 4K bytes of EEPROM, six asynchronous serial communications interfaces (SCI), three serial peripheral interfaces (SPI), an 8-channel IC/OC enhanced capture timer, an 8-channel, 10-bit analog-to-digital converter, an 8-channel pulse-width modulator (PWM), five CAN 2.0 A, B software compatible modules (MSCAN12), two Inter-IC Bus blocks and a Periodic Interrupt Timer. The MC9S12XDP512 has full 16-bit data paths throughout. The non-multiplexed expanded bus interface available on the 144-Pin versions allows an easy interface to external memories.

The inclusion of a PLL circuit allows power consumption and performance to be adjusted to suit operational requirements. System power consumption can be further improved with the new "fast exit from STOP mode" feature.

In addition to the I/O ports available in each module, up to 25 further I/O ports are available with interrupt capability allowing Wake-Up from STOP or WAIT mode.

The MC9S12XDP512 will be available in 144-Pin LQFP with external bus interface and in 112-Pin LQFP or 80-Pin QFP package without external bus interface.

1.2 Features

- HCS12X Core
 - 16-bit HCS12X CPU
 - i. Upward compatible with MC9S12 instruction set
 - ii. Interrupt stacking and programmer's model identical to MC9S12
 - iii. Instruction queue
 - iv. Enhanced indexed addressing
 - v. Enhanced instruction set
 - EBI (External Bus Interface)



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- MMC (Module Mapping Control)
- INT (Interrupt Controller)
- DBG (Debug module to monitor HCS12X CPU and XGATE bus activity)
- BDM (Background Debug Mode)
- XGATE (Peripheral Co-Processo)
 - Parallel processing module offloads the CPU by providing high speed data processing and transfer
 - Data transfer between Flash EEPROM, RAM, peripheral modules and I/O ports
- PIT (Periodic Interrupt Timer)
 - Four timers with independent time-out periods
 - Time-out periods selectable between 1 and 2^{24} bus clock cycles
- CRG (Clock and Reset Generator)
 - Low noise/low power pierce oscillator
 - PLL
 - COP watchdog
 - Real time interrupt
 - Clock monitor
 - Fast wake-up from Stop Mode
- 8-bit ports with interrupt functionality
 - Digital filtering
 - Programmable rising or falling edge trigger
- Memory
 - 512K byte Flash EEPROM
 - 4K byte EEPROM
 - 32K byte RAM
- One 8-channel and one 16 channel Analog-to-Digital Converter
 - 10-bit resolution
 - External conversion trigger capability
- Five 1M bit per second, CAN 2.0 A, B software compatible modules
 - Five receive and three transmit buffers
 - Flexible identifier filter programmable as 2 x 32 bit, 4 x 16 bit or 8 x 8 bit
 - Four separate interrupt channels for Rx, Tx, error and wake-up
 - Low-pass filter wake-up function

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- Loop-back for self test operation
- ECT (Enhanced Capture Timer)
 - 16-bit main counter with 7-bit prescaler
 - 8 programmable input capture or output compare channels
 - Four 8-bit or two 16-bit pulse accumulators
- 8 PWM channels
 - Programmable period and duty cycle
 - 8-bit 8-channel or 16-bit 4-channel
 - Separate control for each pulse width and duty cycle
 - Center-aligned or left-aligned outputs
 - Programmable clock select logic with a wide range of frequencies
 - Fast emergency shutdown input
 - Usable as interrupt inputs
- Serial interfaces
 - Six asynchronous Serial Communication Interfaces (SCI) with additional LIN support and selectable IrDA 1.4 return-to-zero-inverted (RZI) format with programmable pulse width
 - Three Synchronous Serial Peripheral Interfaces (SPI)
- IIC (Two Inter-IC Bus modules)
 - Compatible with IIC Bus standard
 - Multi-master operation
 - Software programmable for one of 256 different serial clock frequencies
- On chip Voltage Regulator
 - Two parallel, linear voltage regulators with bandgap reference
 - Low Voltage detect (LVD) with Low Voltage Interrupt (LVI)
 - Power On Reset (POR) circuit
 - 3.3V 5.5V operation
 - Low Voltage Reset (LVR)
 - Ultra Low Power Wake-up Timer
- 144 Pin LQFP, 112-Pin LQFP package and 80-Pin QFP package
 - I/O lines with 5V input and drive capability
 - Input threshold on external bus interface inputs switchable for 3.3V or 5V operation
 - 5V A/D converter inputs
 - Operation at 80MHz equivalent to 40MHz bus speed



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- Development support
 - Single-wire background debugTM mode (BDM)
 - 4 on-chip hardware breakpoints

1.3 Modes of Operation

User modes:

- Normal and Emulation Operating Modes
 - Normal Single-Chip Mode
 - Normal Expanded Mode
 - Emulation of Single Chip Mode
 - Emulation of Expanded Mode
- Special Operating Modes
 - Special Single-Chip Mode with active Background Debug Mode
 - Special Test Mode (Motorola use only)

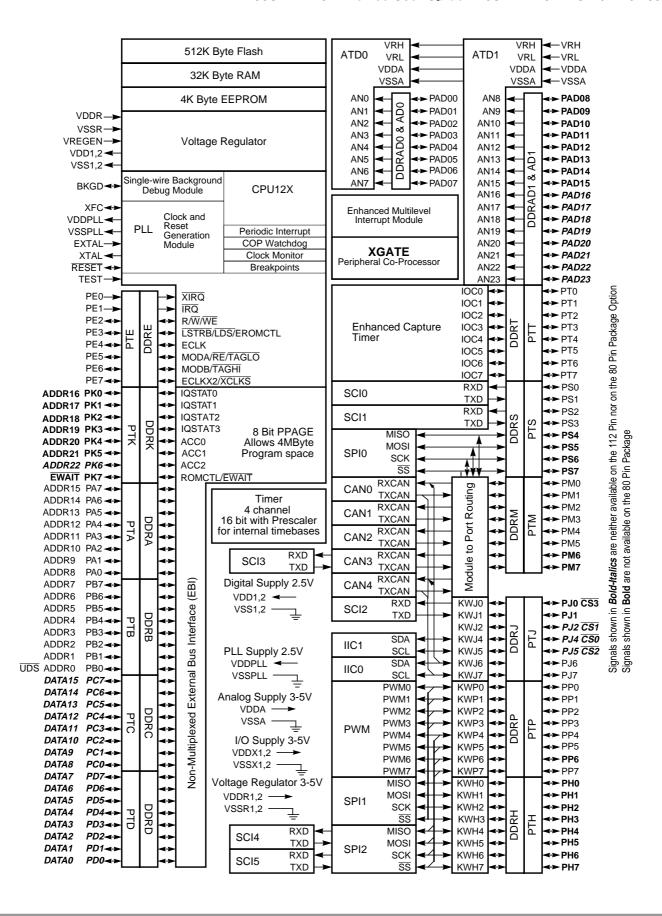
Low power modes:

- System Stop Modes
 - Pseudo Stop Mod
 - Full Stop Mode
- System Wait Mode

1.4 Block Diagram

Figure 1-1 shows a block diagram of the MC9S12XDP512 device.

Figure 1-1 MC9S12XDP512 Block Diagram



1.5 Device Memory Map

1.5.1 Device Register Memory Map

Table 1-1 shows the device register memory map of the MC9S12XDP512

Table 1-1 Device Register Memory Map

Address	Module	Size (Bytes)
\$0000 - \$0009	PIM (Port Integration Module)	10
\$000A -\$000B	MMC (Memory Map Control)	2
\$000C -\$000D	PIM (Port Integration Module)	2
\$000E - \$000F	EBI (External Bus Interface)	2
\$0010 - \$0017	MMC (Memory Map Control)	8
\$0018 - \$0019	Reserved	2
\$001A - \$001B	Device ID register	2
\$001C - \$001F	PIM (Port Integration Module)	4
\$0020 - \$002F	DBG (Debug Module)	16
\$0030 - \$0031	MMC (Memory Map Control)	2
\$0032 - \$0033	PIM (Port Integration Module)	2
\$0034 - \$003F	CRG (Clock and Reset Generator)	12
\$0040 - \$007F	ECT (Enhanced Capture Timer 16-bit 8 channel)s	64
\$0080 - \$00AF	ATD1 (Analog to Digital Converter 10-bit 16 channel)	48
\$00B0 - \$00B7	IIC1 (Inter IC Bus)	8
\$00B8 - \$00BF	SCI2 (Serial Communications Interface)	8
\$00C0 - \$00C7	SCI3 (Serial Communications Interface)	8
\$00C8 - \$00CF	SCI0 (Serial Communications Interface)	8
\$00D0 - \$00D7	SCI1 (Serial Communications Interface)	8
\$00D8 - \$00DF	Serial Peripheral Interface (SPI0)	8
\$00E0 - \$00E7	IIC0 (Inter IC Bus)	8
\$00E8 - \$00EF	Reserved	8
\$00F0 - \$00F7	SPI1 (Serial Peripheral Interface)	8
\$00F8 - \$00FF	SPI2 (Serial Peripheral Interface)	8
\$0100- \$010F	Flash Control Register	16
\$0110 - \$011B	EEPROM Control Register	12
\$011C - \$011F	MMC (Memory Map Control)	4
\$0120 - \$012F	INT (Interrupt Module)	16
\$0130 - \$0137	SCI4 (Serial Communications Interface)	8
\$0138 - \$013F	SCI5 (Serial Communications Interface)	8
\$0140 - \$017F	CAN0 (Motorola Scalable Can)	64
		•

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Table 1-1 Device Register Memory Map

Address	Module	Size (Bytes)
\$0180 - \$01BF	CAN1 (Motorola Scalable Can)	64
\$01C0 - \$01FF	CAN2 (Motorola Scalable Can)	64
\$0200 - \$023F	CAN3 (Motorola Scalable Can)	64
\$0240 - \$027F	PIM (Port Integration Module)	64
\$0280 - \$02BF	CAN4 (Motorola Scalable Can)	64
\$02C0 - \$02DF	ATD0 (Analog to Digital Converter 10 bit 8 channel	32
\$02E0 - \$02EF	Reserved	16
\$02F0 - \$02F7	Voltage Regulator	8
\$02F8 - \$02FF	Reserved	8
\$0300 - \$0327	Pulse Width Modulator 8 Channels	40
\$0328 - \$033F	Reserved	24
\$0340 - \$0367	Periodic Interrupt Timer	40
\$0368 - \$037F	Reserved	24
\$0380 - \$03BF	XGATE	64
\$03C0 - \$07FF	Reserved	1024

Reserved register space shown in **Table 1-1** is not allocated to any module. This register space is reserved for future use. Writing to these locations have no effect. Read access to these locations returns zero.

1.5.2 MC9S12XDP512/MC9S12XA512 Local to Global Address Mapping

Figure 1-2 Local to Global Address Mapping S12X_CPU/S12X_BDM

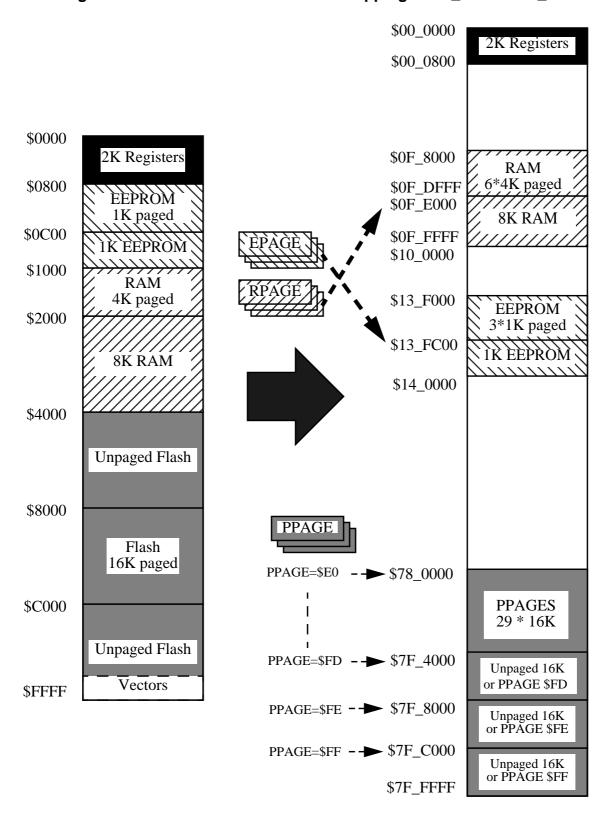
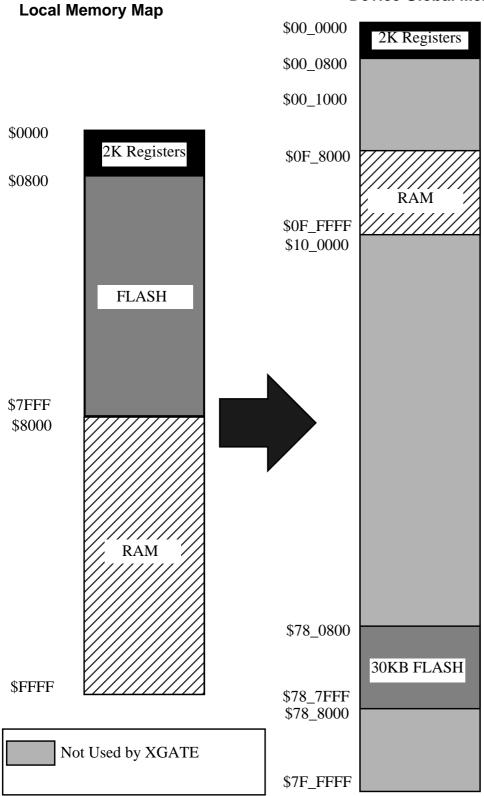


Figure 1-3 Local to Global Address Mapping XGATE

XGATE

Device Global Memory Map



1.5.3 Logical Address Maps of MC9S12XD and MC9S12XA-Family Devices

Figure 1-4 MC9S12XDP512/MC9S12XDT512/MC9S12XA512 Memory Map

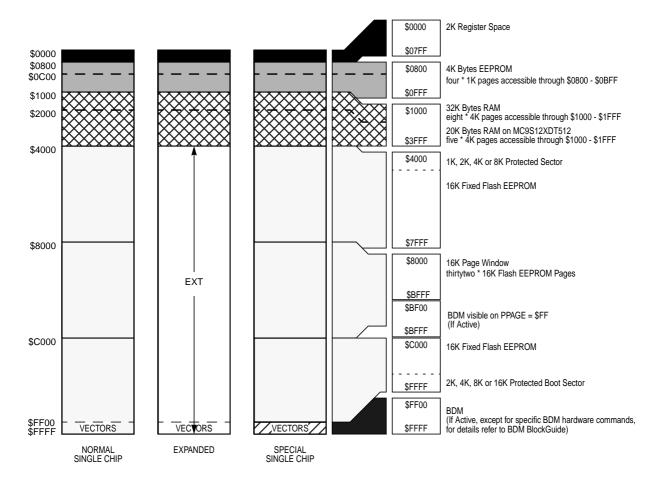
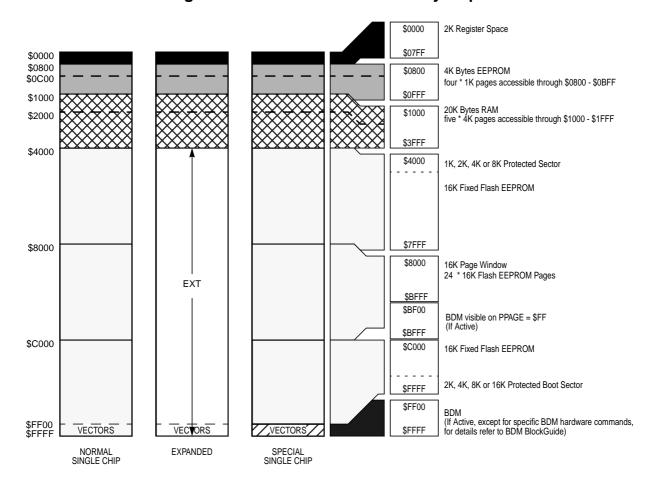


Figure 1-5 MC9S12XDT384 Memory Map



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Figure 1-6 MC9S12XDT256/MC9S12XD256/MC9S12XA256 Memory Map

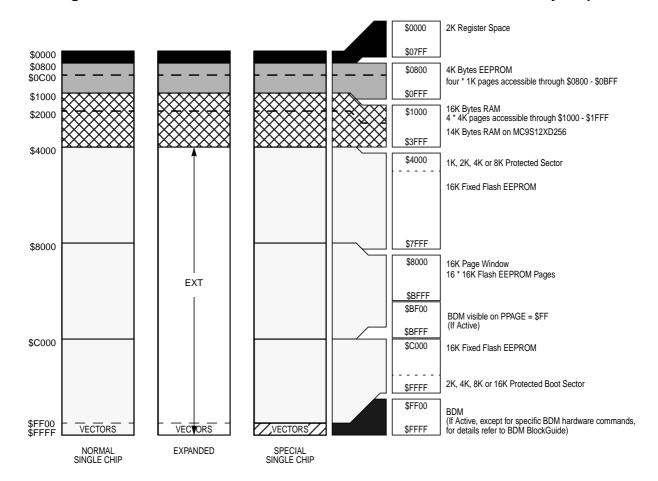
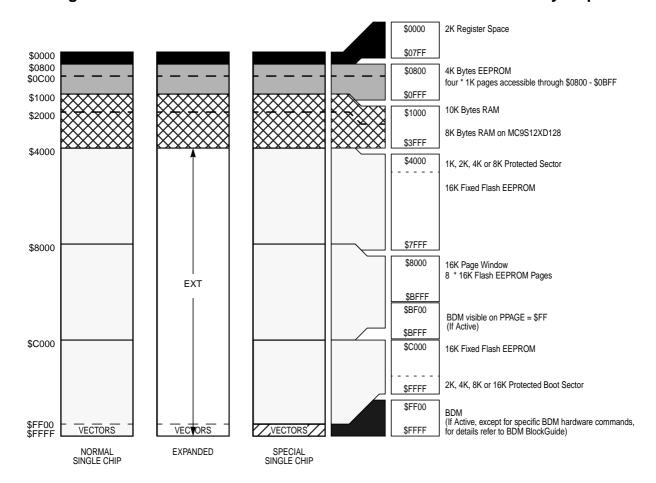
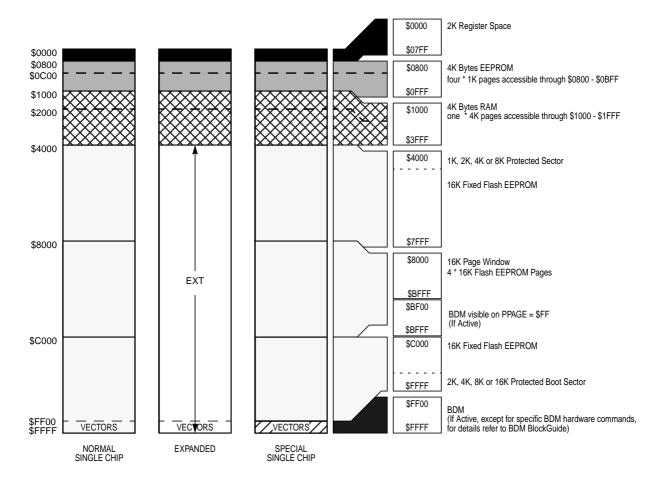


Figure 1-7 MC9S12XD128/MC9S12XDG128/MC9S12XA128 Memory Map



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Figure 1-8 MC9S12XD64 Memory Map



1.5.4 Detailed Register Map

The following tables show the detailed register map of the MC9S12XDP512.

\$0000 - \$0009

Port Integration Module (PIM) Map 1 of 5

Address	Name
\$0000	PORTA
\$0001	PORTB
\$0002	DDRA
\$0003	DDRB
\$0004	PORTC
\$0005	PORTD
\$0006	DDRC
\$0007	DDRD
\$0008	PORTE
\$0009	DDRE

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	PA 7	PA6	PA5	PA4	PA3	PA2	PA1	PA 0
Read: Write:	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Read: Write:	DDRA7	DDRA6	DDRA5	DDRA4	DDRA3	DDRA2	DDRA1	DDRA0
Read: Write:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
Read: Write:	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Read: Write:	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Read: Write:	DDRC7	DDRC6	DDRC5	DDRC4	DDRC3	DDRC2	DDRC1	DDRC0
Read: Write:	DDRD7	DDRD6	DDRD5	DDRD4	DDRD3	DDRD2	DDRD1	DDRD0
Read: Write:	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Read: Write:	DDRE7	DDRE6	DDRE5	DDRE4	DDRE3	DDRE2	0	0

\$000A - \$000B

Address Name \$000A MMCCTL0

MODE

Module Mapping Control (S12XMMC) Map 1 of 4

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	0	0	0	0	0	CS2E	CS1E	CS0E
Write:						CSZE	CSIE	CSUE
Read:	MODC	MODB	MODA	0	0	0	0	0
Write:	MODC	MODE	MODA					

\$000C - \$000D

\$000B

Address	Name
\$000C	PUCR
C10002	DDDI\/

Port Integration Module (PIM) Map 2 of 5

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	PUPKE	BKPUE	0	DIIDEE	DIIDNE	DLIDCE	PUPBE	PUPAE
Write:	TOTAL	DIXI OL		TOTLL	1 OI DL	10101	TOTAL	TOTAL
Read:	RDPK	0	0	RDPE	RDPD	RDPC	RDPB	RDPA
Write:	NDFK			NDFE	משטא	NDFC	אטרם	NDFA

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\$000E - \$000F

External Bus Interface (S12XEBI) Map

Address	Name
\$000E	EBICTL0
\$000F	EBICTL1

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	ITHRS	0	HDBE	ASIZ4	ASIZ3	ASIZ2	ASIZ1	ASIZ0
Write:	IIIINO		TIDBE	ASIZ4	ASIZS	ASIZZ	ASIZI	ASIZU
Read:	EWAITE	0	0	0	0	EVETDO	EXSTR1	EVETDO
Write:	EVVAIIE					EASIRZ	EVOLKI	EXSIRU

\$0010 - \$0017

Module Mapping Control (S12XMMC) Map 2 of 4

Address	Name
\$0010	GPAGE
\$0011	DIRECT
\$0012	Reserved
\$0013	MMCCTL1
\$0014	Reserved
\$0015	Reserved
\$0016	RPAGE
\$0017	EPAGE

			•	•	•	-		
[Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	0	GP6	GP5	GP4	GP3	GP2	GP1	GP0
Read: Write:	DP15	DP14	DP13	DP12	DP11	DP10	DP9	DP8
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	EROMON	ROMHM	ROMON
Write:						EKOWON	KOMINIM	KOWON
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read: Write:	RP7	RP6	RP5	RP4	RP3	RP2	RP1	RP0
Read: Write:	EP7	EP6	EP5	EP4	EP3	EP2	EP1	EP0

\$0018 - \$001B

Miscellaneous Peripheral

Address	Name
\$0018	Reserved
\$0019	Reserved
\$001A	PARTIDH
\$001B	PARTIDL

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	1	1	0	0	0	1	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								

\$001C - \$001D

Port Integration Module (PIM) Map 3 of 5

Address	Name
\$001C	ECLKCTL
\$001D	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Read:	NECLK	NCLKX2	0	0	0	0	EDIV1	EDIV0	
Write:	NECLK	INCLEAZ					EDIVI	EDIVO	
Read:	0	0	0	0	0	0	0	0	
Write:									

42

\$001E - \$001F

Port Integration Module (PIM) Map 3 of 5

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit (
\$001E	IDOCD	Read:	IRQE	IRQEN	0	0	0	0	0	0
Φ001⊑	IRQCR	Write:	IKQE	IRQEN						
€004 □	Decembed	Read:	0	0	0	0	0	0	0	0
\$001F	Reserved	Write:								

\$0020 - \$0027

Debug Module (S12XDBG) Map

Address	Name	1	Bit 7	Bit 6	Dit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	ivaille	Read:		0	Bit 5	DIL 4	סוו ט	DIL Z	DILI	DIL U
\$0020	DBGC1	Write:	ARM	TRIG	XGSBPE	BDM	DBG	BRK	COMRV	
\$0021	DBGSR	Read:	TBF	EXTF	0	0	0	SSF2	SSF1	SSF0
ψ0021	DBGSK	Write:								
\$0022	DBGTCR	Read: Write:	TSOL	JRCE	TRA	NGE	TRC	MOD	TALIGN	
\$0023	DBGC2	Read:	0	0	0	0	CD	CM	AB	CM
Φ0023	DBGC2	Write:					ט	Civi	AD.	Civi
\$0024	DBGTBH	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
φυυ24	рветвп	Write:								
\$0025	DBGTBL	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
φ0023	DBGTBL	Write:								
\$0026	DBGCNT	Read:	0				CNT			
φ0020	DBGCNT	Write:								
\$0027	DBGSCRX	Read:	0	0	0	0	SC3	SC2	SC1	SC0
φυυΖι	DBGSCKA	Write:					303	302	301	300
@00001	DBGXCTL	Read:	0	NDB	TAG	BRK	RW	RWE	SRC	COMPE
\$0028 ¹	(COMPA/C)	Write:		מטא	IAG	DIVIN	IXVV	KVVE	SKC	COMPE
# 00002	DBGXCTL	Read:	SZE	SZ	TAG	BRK	RW	RWE	SRC	COMPE
\$0028 ²	(COMPB/D)	Write:	SZE	32	IAG	DKK	ΓXVV	KVVE	SKC	COMPE
\$0029	DBGXAH	Read:	0	Bit 22	21	20	19	18	17	Bit 16
\$0029	рвалап	Write:		DIL ZZ	21	20	19	10	17	DIL TO
\$002A	DBGXAM	Read:	Bit 15	14	13	12	11	10	9	Bit 8
Φ002A	DBGAAN	Write:	DIL 13	14	13	12	11	10	9	DILO
\$002B	DBGXAL	Read:	Bit 7	6	5	4	3	2	1	Bit 0
Ф 002Б	DBGAAL	Write:	DIL 1	0	5	4	3	2	ı	DIL U
# 0000	DBGXDH	Read:	Bit 15	14	13	10	11	10	0	Dit 0
\$002C	DBGVDH	Write:	כו וום	14	13	12	11	10	9	Bit 8
Ф000D	DDCVDI	Read:	D:4 7		_	4	•	0	4	D:4 0
\$002D	DBGXDL	Write:	Bit 7	6	5	4	3	2	1	Bit 0
Ф ООО Г	DDCVDUM	Read:	D:: 45	4.4	40	40	4.4	10	•	D:4 0
\$002E	DBGXDHM	Write:	Bit 15	14	13	12	11	10	9	Bit 8
Ф002 Г		Read:	D:+ 7	6	_	4	2	2	4	Dit O
\$002F	DBGXDLM	Write:	Bit 7	6	5	4	3	2	1	Bit 0
NOTEO										

NOTES:

- 1. This represents the contents if the Comparator A or C control register is blended into this address
- 2. This represents the contents if the Comparator B or D control register is blended into this address

MC9S12XDP512 Device User of the escale semiconductor, Inc.

\$0030 - \$0031

Module Mapping Control (S12XMMC) Map 3of 4

Address	Name
\$0030	PPAGE
\$0031	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	PIX7	PIX6	PIX5	PIX4	PIX3	PIX2	PIX1	PIX0
Read:	0	0	0	0	0	0	0	0
Write:								

\$0032 - \$0033

Port Integration Module (PIM) Map 4 of 5

Address	Name
\$0032	PORTK
\$0033	DDRK

	L
Read:	I
Write:	l
Read:	Ī
Write:	l

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ad: ite:	PK7	PK6	PK5	PK4	PK3	PK2	PK1	PK0
ad: ite:	DDRK7	DDRK6	DDRK5	DDRK4	DDRK3	DDRK2	DDRK1	DDRK0

\$0034 - \$003F

Clock and Reset Generator (CRG) Map

,	•					, -	-,	•		
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0034	SYNR	Read:	0	0	SYN5	SYN4	SYN3	SYN2	SYN1	SYN0
ΨΟΟΟΤ	OTIVIX	Write:			01110	01114	01110	01112	01111	01110
\$0035	REFDV	Read:	0	0	REFDV5	REFDV4	REFDV3	REFDV2	REFDV1	REFDV0
φοσσσ	ILLI DV	Write:								
\$0036	CTFLG	Read:	0	0	0	0	0	0	0	0
ψοσσσ	01120	Write:			Re	eserved Fo	r Factory Te			
\$0037	CRGFLG	Read:	RTIF	PORF	LVRF	LOCKIF	LOCK	TRACK	SCMIF	SCM
φοσοι	OROI EO	Write:		1 010		2001111			COMM	
\$0038	CRGINT	Read:	RTIE	ILAF	0	LOCKIE	0	0	SCMIE	0
φοσσσ	O. CO. C.	Write:							002	
\$0039	CLKSEL	Read:	PLLSEL	PSTP	0	0	PLLWAI	0	RTIWAI	COPWAI
Ψοσοσ	00	Write:		. •			,			
\$003A	PLLCTL	Read:	CME	PLLON	AUTO	ACQ	FSTWKP	PRE	PCE	SCME
*****		Write:								
\$003B	RTICTL	Read:	RTDEC	RTR6	RTR5	RTR4	RTR3	RTR2	RTR1	RTR0
		Write:								
\$003C	COPCTL	Read:	WCOP	RSBCK	0	0	0	CR2	CR1	CR0
		Write:								
\$003D	FORBYP	Read:	0	0	0	0	0	0	0	0
		Write:		•			r Factory Te			
\$003E	CTCTL	Read:	0	0	0	0		0	0	0
·		Write:					r Factory Te			
\$003F	ARMCOP	Read:	0	0	0	0	0	0	0	0
		Write:	Bit 7	6	5	4	3	2	1	Bit 0

\$0040 - \$007F

Enhanced Capture Timer 16 Bit 8 Channels (ECT) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0040	TIOS	Read: Write:	IOS7	IOS6	IOS5	IOS4	IOS3	IOS2	IOS1	IOS0
ФОО 4.4	OFORO	Read:	0	0	0	0	0	0	0	0
\$0041	CFORC	Write:	FOC7	FOC6	FOC5	FOC4	FOC3	FOC2	FOC1	FOC0
\$0042	OC7M	Read: Write:	OC7M7	ОС7М6	OC7M5	OC7M4	ОС7М3	OC7M2	OC7M1	ОС7М0
\$0043	OC7D	Read: Write:	OC7D7	OC7D6	OC7D5	OC7D4	OC7D3	OC7D2	OC7D1	OC7D0
\$0044	TCNT (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$0045	TCNT (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write: Read:						0	0	0
\$0046	TSCR1	Write:	TEN	TSWAI	TSFRZ	TFFCA	PRNT			0
\$0047	TTOV	Read: Write:	TOV7	TOV6	TOV5	TOV4	TOV3	TOV2	TOV1	TOV0
\$0048	TCTL1	Read: Write:	OM7	OL7	ОМ6	OL6	OM5	OL5	OM4	OL4
\$0049	TCTL2	Read: Write:	ОМЗ	OL3	OM2	OL2	OM1	OL1	ОМ0	OL0
\$004A	TCTL3	Read: Write:	EDG7B	EDG7A	EDG6B	EDG6A	EDG5B	EDG5A	EDG4B	EDG4A
\$004B	TCTL4	Read: Write:	EDG3B	EDG3A	EDG2B	EDG2A	EDG1B	EDG1A	EDG0B	EDG0A
\$004C	TIE	Read: Write:	C7I	C6I	C5I	C4I	C3I	C2I	C1I	COI
\$004D	TSCR2	Read: Write:	TOI	0	0	0	TCRE	PR2	PR1	PR0
\$004E	TFLG1	Read:	C7F	C6F	C5F	C4F	C3F	C2F	C1F	C0F
		Write: Read:		0	0	0	0	0	0	0
\$004F	TFLG2	Write:	TOF	J		,	J			J
\$0050	TC0 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$0051	TC0 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0052	TC1 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$0053	TC1 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0054	TC2 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$0055	TC2 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0056	TC3 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$0057	TC3 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0058	TC4 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8

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\$0040 - \$007F

Enhanced Capture Timer 16 Bit 8 Channels (ECT) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0059	TC4 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$005A	TC5 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$005B	TC5 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$005C	TC6 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$005D	TC6 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$005E	TC7 (hi)	Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
\$005F	TC7 (lo)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0060	PACTL	Read: Write:	0	PAEN	PAMOD	PEDGE	CLK1	CLK0	PAOVI	PAI
\$0061	PAFLG	Read: Write:	0	0	0	0	0	0	PAOVF	PAIF
\$0062	PACN3 (hi)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0063	PACN2 (Io)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0064	PACN1 (hi)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0065	PACN0 (Io)	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0066	MCCTL	Read: Write:	MCZI	MODMC	RDMCL	0 ICLAT	0 FLMC	MCEN	MCPR1	MCPR0
\$0067	MCFLG	Read: Write:	MCZF	0	0	0	POLF3	POLF2	POLF1	POLF0
\$0068	ICPAR	Read: Write:	0	0	0	0	PA3EN	PA2EN	PA1EN	PA0EN
\$0069	DLYCT	Read: Write:	DLY7	DLY6	DLY5	DLY4	DLY3	DLY2	DLY1	DLY0
\$006A	ICOVW	Read: Write:	NOVW7	NOVW6	NOVW5	NOVW4	NOVW3	NOVW2	NOVW1	NOVW0
\$006B	ICSYS	Read: Write:	SH37	SH26	SH15	SH04	TFMOD	PACMX	BUFEN	LATQ
\$006C	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$006D	TIMTST	Read:	0	0	0	0 eserved Fo	0	0	0	0
\$006E	PTPSR	Write: Read:	PTPS7	PTPS6	PTPS5	PTPS4	PTPS3	PTPS2	PTPS1	PTPS0
		Write: Read:					PTMPS3	PTMPS2	PTMPS1	
\$006F	PTMCPSR	Write: Read:	PTMPS7	PTMPS6	PTMPS5 0	PTMPS4 0	0	0 0		PTMPS0 0
\$0070	PBCTL	Write:		PBEN					PBOVI	
\$0071	PBFLG	Read: Write:	0	0	0	0	0	0	PBOVF	0

\$0040 - \$007F

Enhanced Capture Timer 16 Bit 8 Channels (ECT) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0072	PA3H	Read:	PA3H7	PA3H6	PA3H5	PA3H4	PA3H3	PA3H2	PA3H1	PA3H0
φ0072	FASH	Write:								
\$0073	PA2H	Read:	PA2H7	PA2H6	PA2H5	PA2H4	PA2H3	PA2H2	PA2H1	PA2H0
φυυ/ 3	ф00/3 PAZH									
\$0074	PA1H	Read:	PA1H7	PA1H6	PA1H5	PA1H4	PA1H3	PA1H2	PA1H1	PA1H 0
ψ0074	FAIII	Write:								
\$0075	PA0H	Read:	PA0H7	PA0H6	PA0H5	PA0H4	PA0H3	PA0H2	PA0H1	PA0H0
φυστο	FAUL	Write:								
\$0076	MCCNT (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
φυστυ	MCCIVI (III)	Write:	טונ זט	14	13	12	!!	10	9	סונס
\$0077	MCCNT (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
ψοστι	MCCIVI (IO)	Write:	וומ	U	<u> </u>	7	3		'	Dit 0
\$0078	TC0H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
ψοστο	10011 (111)	Write:								
\$0079	TC0H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
φοστο	10011 (10)	Write:								
\$007A	TC1H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
φοσιπ	10111 (111)	Write:								
\$007B	TC1H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
ΨΟΟΙΒ	10111 (10)	Write:								
\$007C	TC2H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
φουνο	10211 (111)	Write:								
\$007D	TC2H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
ΨΟΟΙΒ	10211 (10)	Write:								
\$007E	TC3H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
ψ001∟	10311 (111)	Write:								
\$007F	TC3H (Io)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
\$007F	TC3H (lo)	Write:								

\$0080 - \$00AF			Analog	∣to Digit	tal Conv	erter 10)-bit 16	Channe	Is (ATD [,]	1) Map
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0080	ATD1CTL0	Read:	0	0	0	0	WRAP3	WRAP2	WRAP1	WRAP0
ψοσοσ	AIDICILO	Write:					WINAIS	WINAI Z	VVIXAI I	VVIXALO
\$0081	ATD1CTL1	Read:	ETRIG	0	0	0	ETRIG	ETRIG	ETRIG	ETRIG
ψοσοι	AIDIOILI	Write:	SEL				CH3	CH2	CH1	CH0
\$0082	ATD1CTL2	Read:	ADPU	AFFC	AWAI	ETRIGLE	ETRIGP	ETRIGE	ASCIE	ASCIF
ψ0002	AIDICILZ	Write:	ADI O	λι ι Ο	AVVAI	LINIOLL		LIMOL	AGGIL	
\$0083	ATD1CTL3	Read:	0	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
ψυσσο	AIDICILS	Write:		560	<u> </u>	020	5	1110	111/21	11120
\$0084	ATD1CTL4	Read:	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
ΨΟΟΟΙ	AIDIOILT	Write:	ONLOG	OIVII I	Olvii o	11.01	1 100	11102	11(01	- 1100
\$0085	ATD1CTL5	Read:	DJM	DSGN	SCAN	MULT	CD	СС	СВ	CA
ψοσσσ	AIDIOILO	Write:	Down	D0011		WOL				
\$0086	ATD1STAT0	Read:	SCF	0	ETORF	FIFOR	CC3	CC2	CC1	CC0
ψοσσο	AIDIOIAIO	Write:	001		LIOI	111 010				
\$0087	Reserved	Read:	0	0	0	0	0	0	0	0
ψοσοι	Reserved	Write:								
\$0088	ATD1TEST0	Read:	U	U	U	U	U	U	U	U
ψυσου	AIDITESIU	Write:			Re	eserved For	Factory Te	est		

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Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0089	ATD1TEST1	Read:	0	0	0	0	0	0	0	0
*****		Write:					Factory Te			
\$008A	ATD1STAT2	Read: Write:	CCF15	CCF14	CCF13	CCF12	CCF11	CCF10	CCF9	CCF8
\$008B	ATD1STAT1	Read: Write:	CCF7	CCF6	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
\$008C	ATD1DIEN0	Read: Write:	IEN15	IEN14	IEN13	IEN12	IEN11	IEN10	IEN9	IEN8
\$008D	ATD1DIEN	Read: Write:	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
\$008E	PORTAD0	Read: Write:	PTAD15	PTAD14	PTAD13	PTAD12	PTAD11	PTAD10	PTAD9	PTAD8
\$008F	PORTAD1	Read: Write:	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
\$0090	ATD1DR0H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8
\$0091	ATD1DR0L	Read:	Bit7	Bit6	0	0	0	0	0	0
\$0092	ATD1DR1H	Write: Read:	Bit15	14	13	12	11	10	9	Bit8
\$0093	ATD1DR1L	Write: Read:	Bit7	Bit6	0	0	0	0	0	0
\$0094	ATD1DR2H	Write: Read:	Bit15	14	13	12	11	10	9	Bit8
\$0095	ATD1DR2L	Write: Read:	Bit7	Bit6	0	0	0	0	0	0
φοσσσ	AIDIDIZE	Write:	- · · · -							5115
\$0096	ATD1DR3H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8
\$0097	ATD1DR3L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
\$0098	ATD1DR4H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8
\$0099	ATD1DR4L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
\$009A	ATD1DR5H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8
\$009B	ATD1DR5L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
\$009C	ATD1DR6H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8
\$009D	ATD1DR6L	Read:	Bit7	Bit6	0	0	0	0	0	0
\$009E	ATD1DR7H	Write: Read:	Bit15	14	13	12	11	10	9	Bit8
\$009F	ATD1DR7L	Write: Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A0	ATD1DR8H	Write: Read:	Bit15	14	13	12	11	10	9	Bit8
		Write: Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A1	ATD1DR8L	Write: Read:	Bit15	14	13	12	11	10	9	Bit8
\$00A2	ATD1DR9H	Write:	-		-			-		7-

Address	Name	Г	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
, taa. 000		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A3	ATD1DR9L	Write:	Ditt	Dito		J	J		,	
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00A4	ATD1DR10H	Write:	Ditto		10	12		10	J	Dito
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A5	ATD1DR10L	Write:	Ditt	Dito		J	J	J	J	
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00A6	ATD1DR11H	Write:	Dit10	17	10	12	- ' '	10	3	Dito
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A7	ATD1DR11L	Write:	Diti	Dito		U	U	U	0	0
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00A8	ATD1DR12H	Write:	Dit10	17	10	12	- ' '	10	3	Dito
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00A9	ATD1DR12L	Write:	Ditt	Dito		U	U	U	U	
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00AA	ATD1DR13H	Write:	Ditto		10	12		10	J	Dito
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00AB	ATD1DR13L	Write:	Ditt	Dito		J	J	J	J	
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00AC	ATD1DR14H	Write:	Dicto		10	12		10	J	Dito
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00AD	ATD1DR14L	Write:	Ditt	Dito		J	J	J	J	
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$00AE	ATD1DR15H	Write:	210		.0			.0	,	5.10
		Read:	Bit7	Bit6	0	0	0	0	0	0
\$00AF	ATD1DR15L	Write:	Diti	Dito		J	J	J		
		******C.[

\$00B0 - \$00B7

Inter IC Bus (IIC1) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00B0	IBAD	Read: Write:	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	0
\$00B1	IBFD	Read: Write:	IBC7	IBC6	IBC5	IBC4	IBC3	IBC2	IBC1	IBC0
\$00B2	IBCR	Read:	IBEN	IBIE	MS/SL	TX/RX	TXAK	0	0	IBSWAI
ΨΟΟΒΣ	IDCK	Write:	IDLIN	בונו	IVIO/OL	17/11/1	IAAR	RSTA		IDOVVAI
\$00B3	IBSR	Read:	TCF	IAAS	IBB	IBAL	0	SRW	IBIF	RXAK
φυυμο	IDOK	Write:				IDAL			IDIF	
\$00B4	IBDR	Read: Write:	D7	D6	D5	D4	D3	D2	D1	D 0
\$00B5	Decembed	Read:	0	0	0	0	0	0	0	0
фиоро	Reserved	Write:								
\$00B6	Reserved	Read:	0	0	0	0	0	0	0	0
фиоро	Reserved	Write:								
¢00P7	Decembed	Read:	0	0	0	0	0	0	0	0
φυυσί	00B7 Reserved	Write:								

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\$00B8 - \$00BF

Asynchronous Serial Interface (SCI2) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00B8	SCI2BDH ¹	Read:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
φυυδο	SCIZBDH.	Write:	INEIN	IINFI	TINEO	SBK 12	SBKII	SBK10	SDK9	SDNO
\$00B9	CCIODDI 1	Read:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
фоора	SCI2BDL ¹	Write:	3BK1	SBRO	SBKS	SBN4	SDRS	JDRZ	SBKT	SBRU
\$00BA	SCI2CR1 ¹	Read:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
φυυρΑ	SCIZCRT	Write:	LOOPS	SCISWAI	KSKC	IVI	WAKE	ILI	PE	FI
¢ ∩∩D0	001040042	Read:	RXEDGI	0	0	0	0	DEDD\/	DEDDIE	DVDIE
\$00B8	SCI2ASR1 ²	Write:	F					BERRV	BERRIF	BKDIF
¢ ∩∩D∩	001040042	Read:	RXEDGI	0	0	0	0	0	DEDDIE	DVDIE
\$00B9	SCI2ACR1 ²	Write:	Е						BERRIE	BKDIE
\$00BA	SCI2ACR2 ²	Read:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
φυυρΑ	SCI2ACR2	Write:						DEKKIVII	DEKKIVIU	DKDLE
¢ ∩∩DD	CCIOCDO	Read:	TIE	TCIE	DIE	шт	тг	DE	RWU	CDIZ
\$00BB	SCI2CR2	Write:	110	ICIE	RIE	ILIE	TE	RE	KWU	SBK
¢00₽C	CCIOCD4	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
\$00BC	SCI2SR1	Write:								
¢00₽D	CCIOCDO	Read:	AMAP	0	0	TVDOL	RXPOL	DDI/42	TXDIR	RAF
\$00BD	SCI2SR2	Write:	AWAP			TXPOL	KAPUL	BRK13	INDIR	
¢ ∩∩D⊏	CCIODDIII	Read:	R8	то	0	0	0	0	0	0
\$00BE	SCI2DRH	Write:		T8						
\$00BF SCI2DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0	
	SCI2DRI	Write:	T7	T6	T5	T4	T3	T2	T1	T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI2SR2 register is set to zero 2. Those registers are accessible if the AMAP bit in the SCI2SR2 register is set to one

\$00C0 - \$00C7

Asynchronous Serial Interface (SCI3) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00C0	SCI3BDH ¹	Read: Write:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
\$00C1	SCI3BDL ¹	Read: Write:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
\$00C2	SCI3CR1 ¹	Read: Write:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
\$00C0	SCI3ASR1 ²	Read: Write:	RXEDGI F	0	0	0	0	BERRV	BERRIF	BKDIF
#0004	001040042	Read:	RXEDGI	0	0	0	0	0	חבחחוב	DVDIE
\$00C1	SCI3ACR1 ²	Write:	Е						BERRIE	BKDIE
\$00C2	SCI3ACR2 ²	Read:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
ψ00 0 2	SCISACKZ	Write:						DEIXIXIII	DEIXIXIVIO	DINDIL
\$00C3	SCI3CR2	Read:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
φοσσσ	OOIOONE	Write:		1012	1112	1-1-		11.	11110	OBIC
\$00C4	SC13SD1	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
\$00C4 SCI3SR1		Write:								

\$00C0 - \$00C7

Asynchronous Serial Interface (SCI3) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00C5 SCI3SR2		Read:	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
φ00C3	SCISSKZ	Write:	AWAF			IXFOL	KAFOL	DKKIS	IADIK	
\$00C6	SCI3DRH	Read:	R8	Т8	0	0	0	0	0	0
\$00C0	SCISDKH	Write:		10						
\$00C7	SCI3DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
φυσοι	SCISDRL	Write:	T7	T6	T5	T4	T3	T2	T1	T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI3SR2 register is set to zero
- 2. Those registers are accessible if the AMAP bit in the SCI3SR2 register is set to one

\$00C8 - \$00CF

Asynchronous Serial Interface (SCI0) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00C8	SCI0BDH ¹	Read: Write:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
\$00C9	SCI0BDL ¹	Read: Write:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
\$00CA	SCI0CR1 ¹	Read: Write:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
\$00 0 \$	001040042	Read:	RXEDGI	0	0	0	0	BERRV	BERRIF	BKDIF
\$00C8	SCI0ASR1 ²	Write:	F					DEKKV	DEKKIF	PKDIF
\$00C9	001040042	Read:	RXEDGI	0	0	0	0	0	BERRIE	BKDIE
\$00C9	SCI0ACR1 ²	Write:	Е						DEKKIE	DKDIE
Φ00C Λ	SCI0ACR2 ²	Read:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
\$00CA	SCIUACR2-	Write:						DEKKIVII	DEKKIVIU	DVDLE
\$00CB	SCI0CR2	Read: Write:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
\$00CC	CCIOCD4	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
\$00CC	SCI0SR1	Write:								
\$00CD	SCI0SR2	Read:	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
\$00CD	3CIU3R2	Write:	AWAP			IAPOL	KAPUL	DKKIS	IVDIK	
¢00CE	CCIODDIU	Read:	R8	то	0	0	0	0	0	0
\$00CE	SCI0DRH	Write:		T8						
\$00CF	CCIODDI	Read:	R7	R6	R5	R4	R3	R2	R1	R0
φυυΟΓ	SCI0DRL	Write:	T7	T6	T5	T4	T3	T2	T1	T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI0SR2 register is set to zero 2. Those registers are accessible if the AMAP bit in the SCI0SR2 register is set to one

\$00D0 - \$00D7

Asynchronous Serial Interface (SCI1) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00D0	SCI1BDH ¹	Read: Write:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
\$00D1	SCI1BDL ¹	Read: Write:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0



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\$00D0 - \$00D7

Asynchronous Serial Interface (SCI1) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00D2	SCI1CR1 ¹	Read: Write:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
\$00D0	SCI1ASR1 ²	Read: Write:	RXEDGI F	0	0	0	0	BERRV	BERRIF	BKDIF
\$00D1	SCI1ACR1 ²	Read: Write:	RXEDGI E	0	0	0	0	0	BERRIE	BKDIE
\$00D2	SCI1ACR2 ²	Read: Write:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
\$00D3	SCI1CR2	Read: Write:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
\$00D4	SCI1SR1	Read: Write:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
\$00D5	SCI1SR2	Read: Write:	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
\$00D6	SCI1DRH	Read: Write:	R8	Т8	0	0	0	0	0	0
\$00D7	SCI1DRL	Read: Write:	R7 T7	R6 T6	R5 T5	R4 T4	R3 T3	R2 T2	R1 T1	R0 T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI1SR2 register is set to zero
- 2. Those registers are accessible if the AMAP bit in the SCI1SR2 register is set to one

\$00D8 - \$00DF

Serial Peripheral Interface (SPI0) Map

Address	Name	[Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$00D8	SPI0CR1	Read: Write:	SPIE	SPE	SPTIE	MSTR	CPOL	СРНА	SSOE	LSBFE
\$00D9	SPINCR2	Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
ф00D9	SFIUCKZ	Write:				IVIODI LIV	DIDINOL		OI IOVVAI	31 00
\$00DA	SPI0BR	SPIORR Read:		SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
ΨΟΟΒΑ	SFIODIX	Write:		011112	011111	011110		01 112	OI IXI	OI IXO
\$00DB	SPI0SR	Read:	SPIF	0	SPTEF	MODF	0	0	0	0
ΨΟΟΟΒ	SFIUSK	Write:								
\$00DC	Reserved	Read:	0	0	0	0	0	0	0	0
\$00DC	Reserved	Write:								
\$00DD	SPI0DR	Read:	Bit7	6	5	4	3	2	1	Bit0
\$00DD	SPIUDK	Write:	Diti	O	3	4	3	2	I	DILU
\$00DE	Reserved	Read:	0	0	0	0	0	0	0	0
\$00DE	Reserved	Write:								
¢00DE	DE Deserved	Read:	0	0	0	0	0	0	0	0
\$00DF Reserved	Write:									

\$00E0 - \$00E7

Inter IC Bus (IIC0) Map

Address	Name
\$00E0	IBAD
\$00E1	IBFD
\$00E2	IBCR
\$00E3	IBSR
\$00E4	IBDR
\$00E5	Reserved
\$00E6	Reserved
\$00E7	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	0
Read: Write:	IBC7	IBC6	IBC5	IBC4	IBC3	IBC2	IBC1	IBC0
Read:	IBEN	IBIE	MS/SL	TX/ RX	TXAK	0	0	IDC////I
Write:	IDEIN	IDIE	IVIS/SL	IA/KA	IAAN	RSTA		IBSWAI
Read:	TCF	IAAS	IBB	IBAL	0	SRW	IBIF	RXAK
Write:				IDAL			IDIF	
Read: Write:	D7	D6	D5	D4	D3	D2	D1	D 0
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								

\$00E8 - \$00EF

Reserved

Address	Name
\$00E8	Reserved
\$00E9	Reserved
\$00EA	Reserved
\$00EB	Reserved
\$00EC	Reserved
\$00ED	Reserved
\$00EE	Reserved
\$00EF	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								

\$00F0 - \$00F7

Serial Peripheral Interface (SPI1) Map

Address	Name
\$00F0	SPI1CR1
\$00F1	SPI1CR2
\$00F2	SPI1BR
\$00F3	SPI1SR

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	SPIE	SPE	SPTIE	MSTR	CPOL	СРНА	SSOE	LSBFE
Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
Write:				INIODEEN	DIDIKOE		SPISWAI	3500
Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
Write:		SPFKZ	SPEKI	SPPRU		SFKZ	SPKI	SPRU
Read:	SPIF	0	SPTEF	MODF	0	0	0	0
Write:								

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\$00F0 - \$00F7

Serial Peripheral Interface (SPI1) Map

Address	Name
\$00F4	Reserved
\$00F5	SPI1DR
\$00F6	Reserved
\$00F7	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	0	0	0	0	0	0	0	0
Write:								
Read: Write:	Bit7	6	5	4	3	2	1	Bit0
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								

\$00F8 - \$00FF

Serial Peripheral Interface (SPI2) Map

Address	Name
\$00F8	SPI2CR1
\$00F9	SPI2CR2
\$00FA	SPI2BR
\$00FB	SPI2SR
\$00FC	Reserved
\$00FD	SPI2DR
\$00FE	Reserved
\$00FF	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read: Write:	SPIE	SPE	SPTIE	MSTR	CPOL	СРНА	SSOE	LSBFE
Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
Write:				MODELIN	BIDIKOL		SFISWAI	3500
Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
Write:		SFFRZ	SEEKI	SFFRU		SFRZ	SEKT	SFRU
Read:	SPIF	0	SPTEF	MODF	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								
Read: Write:	Bit7	6	5	4	3	2	1	Bit0
Read:	0	0	0	0	0	0	0	0
Write:								
Read:	0	0	0	0	0	0	0	0
Write:								

\$0100 - \$010F

Flash Control Register (FTX512K4) Map

Address	Name
\$0100	FCLKDIV
\$0101	FSEC
\$0102	FTSTMOD
\$0103	FCNFG
\$0104	FPROT
\$0105	FSTAT
\$0106	FCMD
\$0107	FCTL

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	FDIVLD	PRDIV8	FDIV5	FDIV4	FDIV3	FDIV2	FDIV1	FDIV0
Write:		PKDIVO	FDIVS	FDIV4	LDIA2	FDIVZ	FUIVI	FDIVU
Read:	KEYEN1	KEYEN0	RNV5	RNV4	RNV3	RNV2	SEC1	SEC0
Write:								
Read:	0	MD	DC	WDALL	0	0	0	0
Write:		IVIR	DS	WRALL				
Read:	CDEIE	C I	KEVACC	0	0	0	0	0
Write:	CBEIE	CCIE	KEYACC					
Read:	EDODEN.	RNV6	ED11010		EDITO		ED! 04	
Write:	FPOPEN		FPHDIS	FPHS1	FPHS0	FPLDIS	FPLS1	FPLS0
Read:	ODELE	CCIF	D) ((O)	400500	0	BLANK	0	0
Write:	CBEIF		PVIOL	ACCERR				
Read:	0				OMDDIG:01			
Write:					CMDB[6:0]			
Read:	NV7	NV6	NV5	NV4	NV3	NV2	NV1	NV0
Write:								
vviile.								

\$0100 - \$010F Flash Control Register (FTX512K4) Map

		_								
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CO400	EADDDIII	Read:				FADI	DRHI			
\$0108	FADDRHI	Write:								
\$0109	FADDRLO	Read:				FADE	RLO			
Ф 0109	FADDRLO	Write:								
Φ040A	ГРАТАЦИ	Read:				FDA	TAHI			
\$010A	FDATAHI	Write:								
\$010B	EDATALO.	Read:	FDATALO							
ФОТОВ	FDATALO	Write:								
\$010C	Decembed	Read:	0	0	0	0	0	0	0	0
\$010C	Reserved	Write:								
\$010D	Reserved	Read:	0	0	0	0	0	0	0	0
φυτυμ	Reserved	Write:							0 0	
\$010E	Reserved	Read:	0	0	0	0	0	0	0	0
φυτυ⊏	Reserved	Write:								
\$010F	Reserved	Read:	0	0	0	0	0	0	0	0
ψυτυΓ	Reserved	Write:								

\$0110 - \$011B EEPROM Control Register (EETX4K) Map

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0110	ECLKDIV	Read: EDIVLD Write:	PRDIV8	EDIV5	EDIV4	EDIV3	EDIV2	EDIV1	EDIV0
\$0111	Reserved	Read: 0	0	0	0	0	0	0	0
ψΟΙΙΙ	Reserved	Write:							
\$0112	Reserved	Read: 0	0	0	0	0	0	0	0
****	. 1000. 100	Write:		_	-	_	_	_	-
\$0113	ECNFG	Read: CBEIE	CCIE	0	0	0	0	0	0
		vvrite:		DNI)/F	DAIV/4				
\$0114	EPROT	Read: EPOPEI	N RNV6	RNV5	RNV4	EPDIS	EPS2	EPS1	EPS0
		Write:	CCIF			0	DI ANIZ	0	0
\$0115	ESTAT	Read: Write: CBEIF	CCIF	PVIOL	ACCERR	U	BLANK	U	0
		Read: 0							
\$0116	ECMD	Write:			(CMDB[6:0]			
		Read: 0	0	0	0	0	0	0	0
\$0117	Reserved	Write:							
CO440	EADDDIII	Read: 0	0	0	0	0		EABHI	
\$0118	EADDRHI	Write:							
¢0110	EADDDLO	Read:			EAE	BLO			
\$0119	EADDRLO	Write:							
\$011A	EDATAHI	Read:	•		ED	HI			
φυτικ	EDAIANI	Write:							
\$011B	EDATALO	Read:			ED	LO			
ΨΟΙΙΟ	LDAIALO	Write:							

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\$011C - \$011F

Memory Map Control (S12XMMC) Map 4 of 4

Address	Name
\$011C	RAMWPC
\$011D	RAMXGU
\$011E	RAMSHL
\$011F	RAMSHU

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	RPWE	0	0	0	0	0	AVIE	AVIF
Write:	KFWE						AVIE	AVIF
Read:	1	XGU6	XGU5	XGU4	VCIII	XGU2	XGU1	VCLIO
Write:		AGU6	AGUS	AGU4	XGU3	AGUZ	AGUT	XGU0
Read:	1	CHIC	SHL5	CLII 4	SHL3	SHL2	CLII 4	SHL0
Write:		SHL6	SHLS	SHL4	SHLS	SHLZ	SHL1	SHLU
Read:	1	CHILE	SHU5	CHITA	CHITA	SHU2	CHITA	SHU0
Write:		SHU6	SHUS	SHU4	SHU3	3HU2	SHU1	SHUU

\$0120 - \$012F

Interrupt Module (S12XINT) Map

Address	Name	[Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0120	Reserved	Read:	0	0	0	0	0	0	0	0
\$0121	IVBR	Write:				IVB_AD	DR[7:0]			
\$0122	Reserved	Write: Read:	0	0	0	0	0	0	0	0
		Write: Read:	0	0	0	0	0	0	0	0
\$0123	Reserved	Write: Read:	0	0	0	0	0	0	0	0
\$0124	Reserved	Write:							-	
\$0125	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0126	INT_XGPRIO	Read: Write:	0	0	0	0	0		XILVL[2:0]	
\$0127	INT_CFADDR	Read: Write:		INT_CFA	DDR[7:4]		0	0 0 0		
\$0128	INT_CFDATA0	Read: Write:	RQST	0	0	0	0	Р	RIOLVL[2:0	D]
\$0129	INT_CFDATA1	Read: Write:	RQST	0	0	0	0	Р	RIOLVL[2:0	D]
\$012A	INT_CFDATA2	Read:	RQST	0	0	0	0	P	RIOLVL[2:0	01
\$012B	- INT_CFDATA3	Write: Read:	RQST	0	0	0	0		RIOLVL[2:0	
		Write: Read:		0	0	0	0			
\$012C	INT_CFDATA4	Write:	RQST					P	RIOLVL[2:0)]
\$012D	INT_CFDATA5	Read: Write:	RQST	0	0	0	0	P	RIOLVL[2:0	0]
\$012E	INT_CFDATA6	Read: Write:	RQST	0	0	0	0	Р	RIOLVL[2:0	0]
\$012F	INT_CFDATA7	Read: Write:	RQST	0	0	0	0	Р	RIOLVL[2:0	D]

\$00130 - \$0137

Asynchronous Serial Interface (SCI4) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0130	SCI4BDH ¹	Read: Write:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
\$0131	SCI4BDL ¹	Read: Write:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
\$0132	SCI4CR1 ¹	Read: Write:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
¢ 0420	001440542	Read:	RXEDGI	0	0	0	0	DEDDV	DEDDIE	DIADIE
\$0130	SCI4ASR1 ²	Write:	F					BERRV	BERRIF	BKDIF
\$0131	001440042	Read:	RXEDGI	0	0	0	0	0	BERRIE	DKDIE
φυισι	SCI4ACR1 ²	Write:	Е						DEKKIE	BKDIE
\$0132	SCI4ACR2 ²	Read:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
φ013Z	SCI4ACR2-	Write:						DEKKIVII	DEKKIVIU	DKDLE
\$0133	SCI4CR2	Read: Write:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
\$0134	CCI4CD4	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
φ013 4	SCI4SR1	Write:								
\$0135	CCI4CD2	Read:	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
φυτου	SCI4SR2	Write:	AWAF			IXFOL	KAFOL	DIXIO	IVDIK	
\$0136	SCI4DRH	Read:	R8	Т8	0	0	0	0	0	0
φ0130	3CI4DKH	Write:		10						
\$0137	SCI4DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
ψυ 131	3CI4DKL	Write:	T7	T6	T5	T4	T3	T2	T1	T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI4SR2 register is set to zero 2. Those registers are accessible if the AMAP bit in the SCI4SR2 register is set to one

\$0138 - \$013F

Asynchronous Serial Interface (SCI5) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0138	SCI5BDH ¹	Read: Write:	IREN	TNP1	TNP0	SBR12	SBR11	SBR10	SBR9	SBR8
\$0139	SCI5BDL ¹	Read: Write:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
\$013A	SCI5CR1 ¹	Read: Write:	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
\$0138	SCI5ASR1 ²	Read:	RXEDGI	0	0	0	0	BERRV	BERRIF	BKDIF
φ0130	SCISASKI	Write:	F					BERKV	DEKKIF	DKDIF
\$0139	SCI5ACR1 ²	Read:	RXEDGI	0	0	0	0	0	BERRIE	BKDIE
φ0139	SCISACRI	Write:	Е						BERNIE	DNDIE
\$013A	SCI5ACR2 ²	Read:	0	0	0	0	0	BERRM1	BERRM0	BKDFE
φυιзн	SCISACR2-	Write:						DEKKIVII	DEKKIVIU	DNDFE
\$013B	SCI5CR2	Read: Write:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
\$013C	CCIECD1	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
φυιου	SCI5SR1	Write:								

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\$0138 - \$013F

Asynchronous Serial Interface (SCI5) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$013D SCI5SR2	SCI5SD2	Read:	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
ΨΟΙΟΕ	30133112	Write:	AIVIAI			INIOL	IXXI OL	DIXIXIO	INDIN	
\$013E	SCI5DRH	Read:	R8	Т8	0	0	0	0	0	0
Φ013E	SCISDKH	Write:		10						
\$013F	SCI5DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
φυιοτ	SCISDRL	Write:	T7	T6	T5	T4	T3	T2	T1	T0

NOTES:

- 1. Those registers are accessible if the AMAP bit in the SCI5SR2 register is set to zero
- 2. Those registers are accessible if the AMAP bit in the SCI5SR2 register is set to one

\$0140 - \$017F

Motorola Scalable CAN - MSCAN (CAN0) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0140	CAN0CTL0	Read: Write:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
\$0141	CAN0CTL1	Read: Write:	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
\$0142	CAN0BTR0	Read: Write:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
\$0143	CAN0BTR1	Read: Write:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
\$0144	CAN0RFLG	Read: Write:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
\$0145	CANORIER	Read: Write:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
\$0146	CAN0TFLG	Read: Write:	0	0	0	0	0	TXE2	TXE1	TXE0
\$0147	CAN0TIER	Read: Write:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
\$0148	CAN0TARQ	Read: Write:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
\$0149	CAN0TAAK	Read:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0
\$014A	CAN0TBSEL	Write: Read: Write:	0	0	0	0	0	TX2	TX1	TX0
\$014B	CANOIDAC	Read: Write:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
\$014C	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$014D	CANOMISC	Read: Write:	0	0	0	0	0	0	0	BOHOLD
\$014E	CAN0RXERR	Read: Write:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
\$014F	CAN0TXERR	Read: Write:	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
\$0150 - \$0153	CANOIDARO - CANOIDAR3	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0154 - \$0157	CANOIDMR0 - CANOIDMR3	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0

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\$0140 - \$017F Motorola Scalable CAN - MSCAN (CAN0) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
\$0158 - \$015B	CANOIDAR4 - CANOIDAR7	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0		
\$015C - \$015F	CANOIDMR4 - CANOIDMR7	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0		
\$0160 - \$016F	CAN0RXFG	Read:	FOREG	FOREGROUND RECEIVE BUFFER see Detailed MSCAN Foreground Re and Transmit Buffer Layout								
φοτοι		Write:										
\$0170 - \$017F	CAN0TXFG	Read: Write:	FOREGR	OUND TR	ANSMIT BI and		Detailed Buffer Lay		oreground	Receive		

Detailed MSCAN Foreground Receive and Transmit Buffer Layout

		г								
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	Extended ID	Read:	ID28	ID27	ID26	ID25	ID24	ID23	ID22	ID21
\$xxx0	Standard ID	Read:	ID10	ID9	ID8	ID7	ID6	ID5	ID4	ID3
	CANxRIDR0	Write:								
	Extended ID	Read:	ID20	ID19	ID18	SRR=1	IDE=1	ID17	ID16	ID15
\$xxx1	Standard ID	Read:	ID2	ID1	ID0	RTR	IDE=0			
	CANxRIDR1	Write:								
	Extended ID	Read:	ID14	ID13	ID12	ID11	ID10	ID9	ID8	ID7
\$xxx2	Standard ID	Read:								
	CANxRIDR2	Write:								
	Extended ID	Read:	ID6	ID5	ID4	ID3	ID2	ID1	ID0	RTR
\$xxx3	Standard ID	Read:								
	CANxRIDR3	Write:								
\$xxx4-	CANxRDSR0 -	Read:	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
\$xxxB	CANxRDSR7	Write:								
		Read:					DLC3	DLC2	DLC1	DLC0
\$xxxC	CANRxDLR	Write:								
		Read:								
\$xxxD	Reserved	Write:								
		Read:	TSR15	TSR14	TSR13	TSR12	TSR11	TSR10	TSR9	TSR8
\$xxxE	CANxRTSRH	Write:								
		Read:	TSR7	TSR6	TSR5	TSR4	TSR3	TSR2	TSR1	TSR0
\$xxxF	CANxRTSRL	Write:								
	Extended ID	Read:								
	CANxTIDR0	Write:	ID28	ID27	ID26	ID25	ID24	ID23	ID22	ID21
\$xx10	Standard ID	Read:								
		Write:	ID10	ID9	ID8	ID7	ID6	ID5	ID4	ID3
	Extended ID	Read:				222				
	CANxTIDR1	Write:	ID20	ID19	ID18	SRR=1	IDE=1	ID17	ID16	ID15
\$xx10	Standard ID	Read:								
		Write:	ID2	ID1	ID0	RTR	IDE=0			
	Extended ID	Read:								
	CANxTIDR2	Write:	ID14	ID13	ID12	ID11	ID10	ID9	ID8	ID7
\$xx12	Standard ID	Read:								
		Write:								

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Detailed MSCAN Foreground Receive and Transmit Buffer Layout

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$xx13	Extended ID CANxTIDR3	Read: Write:	ID6	ID5	ID4	ID3	ID2	ID1	ID0	RTR
ΨΑΛΙΟ	Standard ID	Read: Write:								
\$xx14- \$xx1B	CANxTDSR0 - CANxTDSR7	Read: Write:	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
\$xx1C	CANxTDLR	Read: Write:					DLC3	DLC2	DLC1	DLC0
\$xx1D	CANxTTBPR	Read: Write:	PRIO7	PRIO6	PRIO5	PRIO4	PRIO3	PRIO2	PRIO1	PRIO0
\$xx1E	CANxTTSRH	Read:	TSR15	TSR14	TSR13	TSR12	TSR11	TSR10	TSR9	TSR8
ΨΛΛΙΣ	5, 11 V/11 TOTAL	Write:								
\$xx1F	CANxTTSRL	Read:	TSR7	TSR6	TSR5	TSR4	TSR3	TSR2	TSR1	TSR0
ψππι	C/ II J/ I TOILE	Write:								

\$0180 - \$01BF

Motorola Scalable CAN - MSCAN (CAN1) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0180	CAN1CTL0	Read: Write:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
\$0181	CAN1CTL1	Read: Write:	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
\$0182	CAN1BTR0	Read: Write:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
\$0183	CAN1BTR1	Read: Write:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
\$0184	CAN1RFLG	Read: Write:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
\$0185	CAN1RIER	Read: Write:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
\$0186	CAN1TFLG	Read: Write:	0	0	0	0	0	TXE2	TXE1	TXE0
\$0187	CAN1TIER	Read: Write:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
\$0188	CAN1TARQ	Read: Write:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
\$0189	CAN1TAAK	Read: Write:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0
\$018A	CAN1TBSEL	Read: Write:	0	0	0	0	0	TX2	TX1	TX0
\$018B	CAN1IDAC	Read: Write:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
\$018C	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$018D	CAN1MISC	Read: Write:	0	0	0	0	0	0	0	BOHOLD
\$018E	CAN1RXERR	Read: Write:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0

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\$0180 - \$01BF

Motorola Scalable CAN - MSCAN (CAN1) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Read:	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
\$018F	CAN1TXERR	Write:	TALIKK	TALITIO	TALITIO	TALITA	TALIKKO	TALITA	IXEIXI	TALITO
\$0190	CAN1IDAR0	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0191	CAN1IDAR1	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0192	CAN1IDAR2	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0193	CAN1IDAR3	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0194	CAN1IDMR0	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0195	CAN1IDMR1	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0196	CAN1IDMR2	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0197	CAN1IDMR3	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0198	CAN1IDAR4	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0199	CAN1IDAR5	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$019A	CAN1IDAR6	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$019B	CAN1IDAR7	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$019C	CAN1IDMR4	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$019D	CAN1IDMR5	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$019E	CAN1IDMR6	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$019F	CAN1IDMR7	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$01A0 - \$01AF	CAN1RXFG	Read:	FOREGI	ROUND RE			Detailed I Buffer Lay		reground	Receive
		Write:								
\$01B0 - \$01BF	CAN1TXFG	Read: Write:	FOREGR	OUND TR			Detailed Buffer Lay		oreground	Receive

\$01C0 - \$01FF

Motorola Scalable CAN - MSCAN (CAN2) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$01C0	CAN2CTL0	Read: Write:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
\$01C1	CAN2CTL1	Read: Write:	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
\$01C2	CAN2BTR0	Read: Write:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0

MC9S12XDP512 Device User diceescale Semiconductor, Inc.

\$01C0 - \$01FF

Motorola Scalable CAN - MSCAN (CAN2) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$01C3	CAN2BTR1	Read: Write:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
\$01C4	CAN2RFLG	Read: Write:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
\$01C5	CAN2RIER	Read: Write:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
\$01C6	CAN2TFLG	Read: Write:	0	0	0	0	0	TXE2	TXE1	TXE0
\$01C7	CAN2TIER	Read: Write:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
\$01C8	CAN2TARQ	Read: Write:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
\$01C9	CAN2TAAK	Read: Write:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0
\$01CA	CAN2TBSEL	Read: Write:	0	0	0	0	0	TX2	TX1	TX0
\$01CB	CAN2IDAC	Read: Write:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
\$01CC	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$01CD	CAN2MISC	Read: Write:	0	0	0	0	0	0	0	BOHOLD
\$01CE	CAN2RXERR	Read: Write:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
\$01CF	CAN2TXERR	Read: Write:	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
\$01D0	CAN2IDAR0	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01D1	CAN2IDAR1	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01D2	CAN2IDAR2	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01D3	CAN2IDAR3	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01D4	CAN2IDMR0	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$01D5	CAN2IDMR1	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$01D6	CAN2IDMR2	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$01D7	CAN2IDMR3	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$01D8	CAN2IDAR4	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01D9	CAN2IDAR5	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01DA	CAN2IDAR6	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$01DB	CAN2IDAR7	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0

\$01C0 - \$01FF

Motorola Scalable CAN - MSCAN (CAN2) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$01DC	CAN2IDMR4	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$01DD	CAN2IDMR5	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$01DE	CAN2IDMR6	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$01DF	CAN2IDMR7	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$01E0 - \$01EF	CAN2RXFG	Read:	FOREGI	ROUND RE	CEIVE BU		Detailed I Buffer Lay		reground	Receive
ф∪т⊑г		Write:								
\$01F0 - \$01FF	CAN2TXFG	Read: Write:	FOREGR	OUND TR	ANSMIT BI and		Detailed Buffer Lay		oreground	Receive

\$0200 - \$023F

Motorola Scalable CAN - MSCAN (CAN3)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0200	CAN3CTL0	Read: Write:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
\$0201	CAN3CTL1	Read: Write:	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
\$0202	CAN3BTR0	Read: Write:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
\$0203	CAN3BTR1	Read: Write:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
\$0204	CAN3RFLG	Read: Write:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
\$0205	CAN3RIER	Read: Write:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
\$0206	CAN3TFLG	Read: Write:	0	0	0	0	0	TXE2	TXE1	TXE0
\$0207	CAN3TIER	Read: Write:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
\$0208	CAN3TARQ	Read: Write:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
\$0209	CAN3TAAK	Read: Write:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0
\$020A	CAN3TBSEL	Read: Write:	0	0	0	0	0	TX2	TX1	TX0
\$020B	CAN3IDAC	Read: Write:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
\$020C	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$020D	Reserved	Read: Write:	0	0	0	0	0	0	0	BOHOLD
\$020E	CAN3RXERR	Read: Write:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
\$020F	CAN3TXERR	Read: Write:	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0

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\$0200 - \$023F

Motorola Scalable CAN - MSCAN (CAN3)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Read:								
\$0210	CAN3IDAR0	Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0211	CAN3IDAR1	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0212	CAN3IDAR2	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0213	CAN3IDAR3	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0214	CAN3IDMR0	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0215	CAN3IDMR1	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0216	CAN3IDMR2	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0217	CAN3IDMR3	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0218	CAN3IDAR4	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0219	CAN3IDAR5	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$021A	CAN3IDAR6	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$021B	CAN3IDAR7	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$021C	CAN3IDMR4	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$021D	CAN3IDMR5	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$021E	CAN3IDMR6	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$021F	CAN3IDMR7	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$0220 - \$022F	CAN3RXFG	Read:	FOREG	ROUND RE			Detailed I Buffer Lay		preground	Receive
		Write:	FORECE		ANCMIT	IEEED co.	Detailed	MCCANIT	0 4 0 0 4 0 1 5 to 5	Deseive
\$0230 - \$023F	CAN3TXFG	Read: Write:	TUKEGR	ROUND TR			Buffer Lay		oreground	Receive

\$0240 - \$027F

Port Integration Module PIM_9DX (PIM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0240	PTT	Read: Write:	PTT7	PTT6	PTT5	PTT4	PTT3	PTT2	PTT1	PTT0
\$0241	DTIT	Read:	PTIT7	PTIT6	PTIT5	PTIT4	PTIT3	PTIT2	PTIT1	PTIT0
φυ24 Ι	PTIT	Write:								
\$0242	DDRT	Read: Write:	DDRT7	DDRT7	DDRT5	DDRT4	DDRT3	DDRT2	DDRT1	DDRT0
\$0243	RDRT	Read: Write:	RDRT7	RDRT6	RDRT5	RDRT4	RDRT3	RDRT2	RDRT1	RDRT0

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\$0240 - \$027F Port Integration Module PIM_9DX (PIM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0244	PERT	Read: Write:	PERT7	PERT6	PERT5	PERT4	PERT3	PERT2	PERT1	PERT0
\$0245	PPST	Read: Write:	PPST7	PPST6	PPST5	PPST4	PPST3	PPST2	PPST1	PPST0
\$0246	Reserved	Read:	0	0	0	0	0	0	0	0
		Write: Read:	0	0	0	0	0	0	0	0
\$0247	Reserved	Write:								
\$0248	PTS	Read: Write:	PTS7	PTS6	PTS5	PTS4	PTS3	PTS2	PTS1	PTS0
\$0249	PTIS	Read: Write:	PTIS7	PTIS6	PTIS5	PTIS4	PTIS3	PTIS2	PTIS1	PTIS0
\$024A	DDRS	Read: Write:	DDRS7	DDRS7	DDRS5	DDRS4	DDRS3	DDRS2	DDRS1	DDRS0
\$024B	RDRS	Read: Write:	RDRS7	RDRS6	RDRS5	RDRS4	RDRS3	RDRS2	RDRS1	RDRS0
\$024C	PERS	Read: Write:	PERS7	PERS6	PERS5	PERS4	PERS3	PERS2	PERS1	PERS0
\$024D	PPSS	Read: Write:	PPSS7	PPSS6	PPSS5	PPSS4	PPSS3	PPSS2	PPSS1	PPSS0
\$024E	WOMS	Read: Write:	WOMS7	WOMS6	WOMS5	WOMS4	WOMS3	WOMS2	WOMS1	WOMS0
\$024F	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0250	PTM	Read: Write:	PTM7	PTM6	PTM5	PTM4	PTM3	PTM2	PTM1	PTM0
\$0251	PTIM	Read:	PTIM7	PTIM6	PTIM5	PTIM4	PTIM3	PTIM2	PTIM1	PTIM0
		Write: Read:								
\$0252	DDRM	Write:	DDRM7	DDRM7	DDRM5	DDRM4	DDRM3	DDRM2	DDRM1	DDRM0
\$0253	RDRM	Read: Write:	RDRM7	RDRM6	RDRM5	RDRM4	RDRM3	RDRM2	RDRM1	RDRM0
\$0254	PERM	Read: Write:	PERM7	PERM6	PERM5	PERM4	PERM3	PERM2	PERM1	PERM0
\$0255	PPSM	Read: Write:	PPSM7	PPSM6	PPSM5	PPSM4	PPSM3	PPSM2	PPSM1	PPSM0
\$0256	WOMM	Read: Write:	WOMM7	WOMM6	WOMM5	WOMM4	WOMM3	WOMM2	WOMM1	WOMM0
\$0257	MODRR	Read: Write:	0	MODRR6	MODRR5	MODRR4	MODRR3	MODRR2	MODRR1	MODRR0
\$0258	PTP	Read: Write:	PTP7	PTP6	PTP5	PTP4	PTP3	PTP2	PTP1	PTP0
\$0259	PTIP	Read: Write:	PTIP7	PTIP6	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
\$025A	DDRP	Read: Write:	DDRP7	DDRP7	DDRP5	DDRP4	DDRP3	DDRP2	DDRP1	DDRP0
\$025B	RDRP	Read: Write:	RDRP7	RDRP6	RDRP5	RDRP4	RDRP3	RDRP2	RDRP1	RDRP0
\$025C	PERP	Read: Write:	PERP7	PERP6	PERP5	PERP4	PERP3	PERP2	PERP1	PERP0

MC9S12XDP512 Device User of the escale semiconductor, Inc.

\$0240 - \$027F Port Integration Module PIM_9DX (PIM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$025D	PPSP	Read: Write:	PPSP7	PPSP6	PPSP5	PPSP4	PPSP3	PPSP2	PPSP1	PPSS0
\$025E	PIEP	Read: Write:	PIEP7	PIEP6	PIEP5	PIEP4	PIEP3	PIEP2	PIEP1	PIEP0
\$025F	PIFP	Read: Write:	PIFP7	PIFP6	PIFP5	PIFP4	PIFP3	PIFP2	PIFP1	PIFP0
\$0260	PTH	Read: Write:	PTH7	PTH6	PTH5	PTH4	PTH3	PTH2	PTH1	PTH0
\$0261	PTIH	Read: Write:	PTIH7	PTIH6	PTIH5	PTIH4	PTIH3	PTIH2	PTIH1	PTIH0
\$0262	DDRH	Read: Write:	DDRH7	DDRH7	DDRH5	DDRH4	DDRH3	DDRH2	DDRH1	DDRH0
\$0263	RDRH	Read: Write:	RDRH7	RDRH6	RDRH5	RDRH4	RDRH3	RDRH2	RDRH1	RDRH0
\$0264	PERH	Read: Write:	PERH7	PERH6	PERH5	PERH4	PERH3	PERH2	PERH1	PERH0
\$0265	PPSH	Read: Write:	PPSH7	PPSH6	PPSH5	PPSH4	PPSH3	PPSH2	PPSH1	PPSH0
\$0266	PIEH	Read: Write:	PIEH7	PIEH6	PIEH5	PIEH4	PIEH3	PIEH2	PIEH1	PIEH0
\$0267	PIFH	Read: Write:	PIFH7	PIFH6	PIFH5	PIFH4	PIFH3	PIFH2	PIFH1	PIFH0
\$0268	PTJ	Read: Write:	PTJ7	PTJ6	PTJ5	PTJ4	0	PTJ2	PTJ1	PTJ0
\$0269	PTIJ	Read: Write:	PTIJ7	PTIJ6	PTIJ5	PTIJ4	0	PTIJ2	PTIJ1	PTIJ0
\$026A	DDRJ	Read: Write:	DDRJ7	DDRJ7	DDRJ5	DDRJ4	0	DDRJ2	DDRJ1	DDRJ0
\$026B	RDRJ	Read: Write:	RDRJ7	RDRJ6	RDRJ5	RDRJ4	0	RDRJ2	RDRJ1	RDRJ0
\$026C	PERJ	Read: Write:	PERJ7	PERJ6	PERJ5	PERJ4	0	PERJ2	PERJ1	PERJ0
\$026D	PPSJ	Read: Write:	PPSJ7	PPSJ6	PPSJ5	PPSJ4	0	PPSJ2	PPSJ1	PPSJ0
\$026E	PIEJ	Read: Write:	PIEJ7	PIEJ6	PIEJ5	PIEJ4	0	PIEJ2	PIEJ1	PIEJ0
\$026f	PIEJ	Read: Write:	PIFJ7	PIFJ6	PIFJ5	PIFJ4	0	PIFJ2	PIFJ1	PIFJ0
\$0270	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0271	PT1AD0	Read: Write:	PT1AD07	PT1AD06	PT1AD05	PT1AD04	PT1AD03	PT1AD02	PT1AD01	PT1AD00
\$0272	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0273	DDR1AD0	Read: Write:	DDR1 AD07	DDR1 AD06	DDR1 AD05	DDR1 AD04	DDR1 AD03	DDR1 AD02	DDR1 AD01	DDR1 AD01
\$0274	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$0275	RDR1AD0	Read: Write:	RDR1 AD07	RDR1 AD06	RDR1 AD05	RDR1 AD04	RDR1 AD03	RDR1 AD02	RDR1 AD01	RDR1 AD00

\$0240 - \$027F

Port Integration Module PIM_9DX (PIM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
40076	Decembed	Read:	0	0	0	0	0	0	0	0
\$0276	Reserved	Write:								
¢ 0277		Read:	PER1AD							
\$0277	PER1AD0	Write:	07	06	05	04	03	02	01	00
¢0070	DTO A D4	Read:	PT0AD1							
\$0278	PT0AD1	Write:	23	22	21	20	19	18	17	16
#0070	DT4 4 D4	Read:	PT1AD1							
\$0279	PT1AD1	Write:	15	14	13	12	11	10	9	8
		Read:	DDR0							
\$027A	DDR0AD1	\	AD1							
		Write:	23	22	21	20	19	18	17	16
		Read:	DDR1							
\$027B	DDR1AD1	\	AD1							
		Write:	15	14	13	12	11	10	9	8
		Read:	RDR0							
\$027C	RDR0AD1	\\/rita.	AD1							
		Write:	23	22	21	20	19	18	17	16
		Read:	RDR1AD							
\$027D	RDR1AD1	\\/rita.	1	1	1	1	1	1	1	1
		Write:	15	14	13	12	11	10	9	8
		Read:	PER0							
\$027E	PER0AD1	\	AD1							
		Write:	23	22	21	20	19	18	17	16
		Read:	PER1							
\$027F	PER1AD1	\	AD1	AD1	AD1	AD1	AD1	A1D	AD1	AD1
		Write:	15	14	13	12	11	10	9	8

\$0280 - \$02BF

Motorola Scalable CAN - MSCAN (CAN4) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0280	CAN4CTL0	Read: Write:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
\$0281	CAN4CTL1	Read: Write:	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
\$0282	CAN4BTR0	Read: Write:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
\$0283	CAN4BTR1	Read: Write:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
\$0284	CAN4RFLG	Read: Write:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
\$0285	CAN4RIER	Read: Write:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
\$0286	CAN4TFLG	Read: Write:	0	0	0	0	0	TXE2	TXE1	TXE0
\$0287	CAN4TIER	Read: Write:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
\$0288	CAN4TARQ	Read: Write:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
\$0289	CAN4TAAK	Read: Write:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0

MC9S12XDP512 Device User of the escale semiconductor, Inc.

\$0280 - \$02BF

Motorola Scalable CAN - MSCAN (CAN4) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$028A	CAN4TBSEL	Read: Write:	0	0	0	0	0	TX2	TX1	TX0
\$028B	CAN4IDAC	Read:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
	0	Write: Read:	0	0	0	0	0	0	0	0
\$028C	Reserved	Write:	Ü	- U			Ü	Ü	Ü	
\$028D	CAN4MISC	Read: Write:	0	0	0	0	0	0	0	BOHOLD
\$028E	CAN4RXERR	Read:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
Ψ020L	CAN4IXALIKI	Write:	TVEDDZ	TYEDDE	TVEDDE	TXERR4	TVEDDA	TYEDDA	TVEDD4	TVEDDO
\$028F	CAN4TXERR	Read: Write:	TXERR7	TXERR6	TXERR5	IAERR4	TXERR3	TXERR2	TXERR1	TXERR0
\$0290	CAN4IDAR0	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0291	CAN4IDAR1	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0292	CAN4IDAR2	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0293	CAN4IDAR3	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0294	CAN4IDMR0	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$0295	CAN4IDMR1	Read: Write:	AM7	AM6	AM5	AM4	АМЗ	AM2	AM1	AM0
\$0296	CAN4IDMR2	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$0297	CAN4IDMR3	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$0298	CAN4IDAR4	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$0299	CAN4IDAR5	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$029A	CAN4IDAR6	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$029B	CAN4IDAR7	Read: Write:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
\$029C	CAN4IDMR4	Read: Write:	AM7	AM6	AM5	AM4	АМ3	AM2	AM1	AM0
\$029D	CAN4IDMR5	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$029E	CAN4IDMR6	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$029F	CAN4IDMR7	Read: Write:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
\$02A0 -	041451/56	Read:	FOREGI	ROUND RE		FFER see			reground	Receive
\$02AF	CAN4RXFG	Write:			and	Transmit	Duffer Lay	out		
\$02B0 -	CANATYEC	Read:	FOREGR	OUND TR	ANSMIT B	JFFER see	Detailed	MSCAN F	oreground	Receive
\$02BF	CAN4TXFG	Write:			and	l Transmit	Buffer Lay	out	•	

68



\$02C0 - \$02DF Analog to Digital Converter 10 Bit 8 Channel (ATD0) Map

Address	Name	[Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$02C0	ATD0CTL0	Read:	0	0	0	0	0	WRAP2	WRAP1	WRAP0
ψ0200	AIDOCILO	Write:	===:0							
\$02C1	ATD0CTL1	Read: Write:	ETRIG SEL	0	0	0	0	ETRIG CH2	ETRIG CH1	ETRIG CH0
#		Read:		4550		ETDIOL E	ETDIOD			ASCIF
\$02C2	ATD0CTL2	Write:	ADPU	AFFC	AWAI	ETRIGLE	ETRIGP	ETRIGE	ASCIE	
\$02C3	ATD0CTL3	Read: Write:	0	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
\$02C4	ATD0CTL4	Read: Write:	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
\$02C5	ATD0CTL5	Read: Write:	DJM	DSGN	SCAN	MULT	0	СС	СВ	CA
\$02C6	ATD0STAT0	Read: Write:	SCF	0	ETORF	FIFOR	0	CC2	CC1	CC0
# 0007		Read:	U	U	U	U	U	U	U	U
\$02C7	Reserved	Write:								
\$02C8	ATD0TEST0	Read:	U	U	U	U	U	U	U	U
		Write: Read:	U	U	0	0	0	0	0	
\$02C9	ATD0TEST1	Write:	J			, and the second				SC
\$02CA	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$02CB	ATD0STAT1	Read: Write:	CCF7	CCF6	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
\$02CC	Reserved	Read: Write:	0	0	0	0	0	0	0	0
\$02CD	ATD0DIEN	Read: Write:	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
\$02CE	Reserved	Read:	0	0	0	0	0	0	0	0
Ψ0202	110001100	Write:	D:47	0		4	2	0	4	DITO
\$02CF	PORTAD0	Read: Write:	Bit7	6	5	4	3	2	1	BIT 0
ф02 D 0	ATDODDOLL	Read:	Bit15	14	13	12	11	10	9	Bit8
\$02D0	ATD0DR0H	Write:								
\$02D1	ATD0DR0L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
		Read:	Bit15	14	13	12	11	10	9	Bit8
\$02D2	ATD0DR1H	Write:	2.1.10							2.1.0
\$02D3	ATD0DR1L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
\$02D4	ATD0DR2H	Read:	Bit15	14	13	12	11	10	9	Bit8
ΨΟΖΒΉ	AIDODICEII	Write:	D::=	Dire						
\$02D5	ATD0DR2L	Read: Write:	Bit7	Bit6	0	0	0	0	0	0
\$02D6	ATD0DR3H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write: Read:	Bit7	Bit6	0	0	0	0	0	0
\$02D7	ATD0DR3L	Write:	DILI	טונט	0	0	U	0	0	0
\$02D8	ATD0DR4H	Read: Write:	Bit15	14	13	12	11	10	9	Bit8

MC9S12XDP512 Device User of the escale semiconductor, Inc.

\$02C0 - \$02DF

Analog to Digital Converter 10 Bit 8 Channel (ATD0) Map

A -1 -1	NI	Г	D:+ 7	D:+ 0	Dir.E	Dit 4	D:4 0	D:+ 0	Dit 4	D:+ 0
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$02D9	ATD0DR4L	Read:	Bit7	Bit6	0	0	0	0	0	0
ψυΖυσ	AIDUDN4L	Write:								
\$02DA ATD0DR	ATD0DR5H	Read:	Bit15	14	13	12	11	10	9	Bit8
φυΖΔΑ	ALDODKSH	Write:								
\$02DB	ATD0DR5L	Read:	Bit7	Bit6	0	0	0	0	0	0
ΦυΖΟΒ	ALDODKSL	Write:								
#00DO	ATD0DR6H	Read:	Bit15	14	13	12	11	10	9	Bit8
\$02DC		Write:								
\$02DD	ATD0DR6L	Read:	Bit7	Bit6	0	0	0	0	0	0
φυΖυυ	AIDUDROL	Write:								
\$02DE	ATD0DR7H	Read:	Bit15	14	13	12	11	10	9	Bit8
φυΖυΕ	AI DUDK/II	Write:								
\$02DF	ATDODDZI	Read:	Bit7	Bit6	0	0	0	0	0	0
φυΖυΓ	ATD0DR7L	Write:								

\$02E0 - \$02EF

Reserved

Address	Name
\$02E0	D
- \$02EF	Reserved

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Read:	0	0	0	0	0	0	0	0
Write:								

\$02F0 - \$02F7

Voltage Regulator (VREG_3V3) Map

۸ ما ما سه م م	Maria		D:4 7	D:4 C	D:4 F	D:4 4	D:+ 0	D:4 0	D:4.4	D:4 0			
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
\$02F0	VREGHTCL	Read:	Reserved for Factory Test										
ψ02. σ	VII. 20111 02	Write:		1.555.155.157.456.17.155.1									
\$02F1	VREGCTRL	Read:	0	0	0	0	0	LVDS	LVIE	LVIF			
ψ021 1	VICEGUINE	Write:							LVIL	LVIF			
¢ ∩⊃⊏⊃	VREGAPICL	Read:	APICLK	0	0	0	0	APIFE	ADIE	APIF			
\$02F2	VREGAPICE	Write:	APICLK					APIFE	APIE	APIF			
\$02F3	VREGAPITR	Read:	APITR5	APITR4	APITR3	APITR2	APITR1	APITR0	0	0			
φυΖΕ3	VNEGAFIIN	Write:	AFIINS	AFIIN4	AFIINS	AFIINZ	AFIIKI	AFIINU					
\$02F4	VREGAPIRH	Read:	0	0	0	0	APIR11	APIR10	APIR9	APIR8			
ψ021 4	VICEGALIKII	Write:					ALIIVII	ALIIVIO	ALINS	ALIIVO			
\$02F5	VREGAPIRL	Read:	APIR7	APIR6	APIR5	APIR4	APIR3	APIR2	APIR1	APIR0			
φ02F3	VNEGAFINE	Write:	AFINI	AFINO	AFINO	AFIN 4	AFINS	AFINZ	AFINI	AFINU			
¢∩っ⊑ら	Posonyod	Read:	0	0	0	0	0	0	0	0			
\$02F6 Reserved	Write:												
\$02F7	Reserved	Read	0	0	0	0	0	0	0	0			
ψυΖΓ1	Neserveu	Write:											

\$02F8 - \$02FF

Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$02F8	Pagaryad	Read:	0	0	0	0	0	0	0	0
- \$02FF	Reserved	Write:								

70

\$0300 - \$0327

Pulse Width Modulator 8 Bit 8 Channel (PWM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0300	PWME	Read: Write:	PWME7	PWME6	PWME5	PWME4	PWME3	PWME2	PWME1	PWME0
\$0301	PWMPOL	Read: Write:	PPOL7	PPOL6	PPOL5	PPOL4	PPOL3	PPOL2	PPOL1	PPOL0
\$0302	PWMCLK	Read: Write:	PCLK7	PCLK6	PCLK5	PCLK4	PCLK3	PCLK2	PCLK1	PCLK0
\$0303	PWMPRCLK	Read: Write:	0	PCKB2	PCKB1	PCKB0	0	PCKA2	PCKA1	PCKA0
\$0304	PWMCAE	Read: Write:	CAE7	CAE6	CAE5	CAE4	CAE3	CAE2	CAE1	CAE0
\$0305	PWMCTL	Read: Write:	CON67	CON45	CON23	CON01	PSWAI	PFRZ	0	0
\$0306	PWMTST Test Only	Read: Write:	0	0	0	0	0	0	0	0
\$0307	PWMPRSC	Read: Write:	0	0	0	0	0	0	0	0
\$0308	PWMSCLA	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0309	PWMSCLB	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$030A	PWMSCNTA	Read: Write:	0	0	0	0	0	0	0	0
\$030B	PWMSCNTB	Read: Write:	0	0	0	0	0	0	0	0
\$030C	PWMCNT0	Read: Write:	Bit 7 0	6	5	4 0	3	0	0	Bit 0
\$030D	PWMCNT1	Read: Write:	Bit 7 0	6	5 0	4 0	3	0	0	Bit 0
\$030E	PWMCNT2	Read: Write:	Bit 7 0	6 0	5 0	4 0	3	2	1 0	Bit 0
\$030F	PWMCNT3	Read: Write:	Bit 7	6	5 0	4 0	3	2	1 0	Bit 0
\$0310	PWMCNT4	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0311	PWMCNT5	Read: Write:	Bit 7	6	5 0	4	3	2	1 0	Bit 0
\$0312	PWMCNT6	Read: Write:	Bit 7	6	5	4 0	3	2	1 0	Bit 0
\$0313	PWMCNT7	Read: Write:	Bit 7	6	5	4 0	3	2	1 0	Bit 0
\$0314	PWMPER0	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0315	PWMPER1	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0316	PWMPER2	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0317	PWMPER3	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0318	PWMPER4	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0

MC9S12XDP512 Device User clifeescale Semiconductor, Inc.

\$0300 - \$0327

Pulse Width Modulator 8 Bit 8 Channel (PWM) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0319	PWMPER5	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031A	PWMPER6	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031B	PWMPER7	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031C	PWMDTY0	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031D	PWMDTY1	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031E	PWMDTY2	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$031F	PWMDTY3	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0320	PWMDTY4	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0321	PWMDTY5	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0322	PWMDTY6	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0323	PWMDTY7	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
\$0324	PWMSDN	Read: Write:	PWMIF	PWMIE	0 PWM RSTRT	PWMLVL	0	PWM7IN	PWM7IN L	PWM7E NA
\$0325	Reserved	Read:	0	0	0	0	0	0	0	0
ψυυΖυ	176261 AGU	Write:								
\$0326	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:	0		0			0		
\$0327	Reserved	Read: Write:	0	0	0	0	0	0	0	0

\$0328 - \$033F

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0328	Bosoniad	Read:	0	0	0	0	0	0	0	0
- \$033F	Reserved	Write:								
				-	-	-	-	-	-	-

\$0340 - \$0367

Periodic Interrupt Timer (PIT) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0340	PITCFLMT	Read:	PITE	PITSWAI	PITFRZ	0	0	0	0	0
ΨΟΟ-ΤΟ	FITCELINIT	Write:	1116	I IIOWAI	1 111 112				PFLMT1	PFLMT0
\$0341	DITTIT	Read:	0	0	0	0	0	0	0	0
φυ3 4 Ι	PITFLT	Write:					PFLT3	PFLT2	PFLT1	PFLT0
#0040	DITOF	Read:	0	0	0	0	000	000	DOE4	DOEO
\$0342	PITCE	Write:					PCE3	PCE2	PCE1	PCE0
\$0343	DITMIN	Read:	0	0	0	0	DMIIVO	DMINO	DMIIVA	DMILIVO
	PITMUX	Write:					PMUX3	PMUX2	PMUX1	PMUX0

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\$0340 - \$0367

Periodic Interrupt Timer (PIT) Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Read:	0	0	0					
\$0344	PITINTE	Write:					PINTE3	PINTE2	PINTE1	PINTE0
\$0345	PITTF	Read:	0	0	0	0	PTF3	PTF2	PTF1	PTF0
****		Write:						–		
\$0346	PITMTLD0	Read: Write:	PMTLD7	PMTLD6	PMTLD5	PMTLD4	PMTLD3	PMTLD2	PMTLD1	PMTLD0
\$0347	PITMTLD1	Read: Write:	PMTLD7	PMTLD6	PMTLD5	PMTLD4	PMTLD3	PMTLD2	PMTLD1	PMTLD0
\$0348	PITLD0 (hi)	Read: Write:	PLD15	PLD14	PLD13	PLD12	PLD11	PLD10	PLD9	PLD8
\$0349	PITLD0 (lo)	Read: Write:	PLD7	PLD6	PLD5	PLD4	PLD3	PLD2	PLD1	PLD0
\$034A	PITCNT0 (hi)	Read: Write:	PCNT15	PCNT14	PCNT13	PCNT12	PCNT11	PCNT10	PCNT9	PCNT8
\$034B	PITCNT0 (lo)	Read: Write:	PCNT7	PCNT6	PCNT5	PCNT4	PCNT3	PCNT2	PCNT1	PCNT0
\$034C	PITLD1 (hi)	Read: Write:	PLD15	PLD14	PLD13	PLD12	PLD11	PLD10	PLD9	PLD8
\$034D	PITLD1 (lo)	Read: Write:	PLD7	PLD6	PLD5	PLD4	PLD3	PLD2	PLD1	PLD0
\$034E	PITCNT1 (hi)	Read: Write:	PCNT15	PCNT14	PCNT13	PCNT12	PCNT11	PCNT10	PCNT9	PCNT8
\$034F	PITCNT1 (lo)	Read: Write:	PCNT7	PCNT6	PCNT5	PCNT4	PCNT3	PCNT2	PCNT1	PCNT0
\$0350	PITLD2 (hi)	Read: Write:	PLD15	PLD14	PLD13	PLD12	PLD11	PLD10	PLD9	PLD8
\$0351	PITLD2 (lo)	Read: Write:	PLD7	PLD6	PLD5	PLD4	PLD3	PLD2	PLD1	PLD0
\$0352	PITCNT2 (hi)	Read: Write:	PCNT15	PCNT14	PCNT13	PCNT12	PCNT11	PCNT10	PCNT9	PCNT8
\$0353	PITCNT2 (lo)	Read: Write:	PCNT7	PCNT6	PCNT5	PCNT4	PCNT3	PCNT2	PCNT1	PCNT0
\$0354	PITLD3 (hi)	Read: Write:	PLD15	PLD14	PLD13	PLD12	PLD11	PLD10	PLD9	PLD8
\$0355	PITLD3 (lo)	Read: Write:	PLD7	PLD6	PLD5	PLD4	PLD3	PLD2	PLD1	PLD0
\$0356	PITCNT3 (hi)	Read: Write:	PCNT15	PCNT14	PCNT13	PCNT12	PCNT11	PCNT10	PCNT9	PCNT8
\$0357	PITCNT3 (lo)	Read: Write:	PCNT7	PCNT6	PCNT5	PCNT4	PCNT3	PCNT2	PCNT1	PCNT0
\$0358 -	Reserved	Read:	0	0	0	0	0	0	0	0
\$0367	110001100	Write:								

\$0368 - \$037F

Reserved

Address Name \$0368 - \$037F Reserved

Read: Write:

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ad:	0	0	0	0	0	0	0	0
te:								

\$0380 - \$03BF XGATE Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Addiess	IName	Read:	0	0	0	0	0	0	0	Dit 0
\$0380	XGMCTL	Write:	XGEM	XGFRZM	XGDBGM	XGSSM	XGFACT M			XGIEM
\$0381	Reserved	Read: Write:	XGE	XGFRZ	XGDBG	XGSS	XGFACT	0	XGSWEI F	XGIE
¢ስລຄລ	XGCHID	Read:	0			X	GCHID[6:0)]		
\$0382	лоспір	Write:								
\$0383	Reserved	Read:	0	0	0	0	0	0	0	0
		Write: Read:	0	0	0	0	0	0	0	0
\$0384	XGVBR	Write:	U	0	U	0	0	0	0	0
# 000 F	VOVDD	Read:	0	0	0	0		\/O\/DE		
\$0385	XGVBR	Write:						XGVBF	([19:16]	
\$0386	XGVBR	Read: Write:				XGVBI	R[15:8]			
\$0387	XGVBR	Read: Write:)	KGVBR[7:1]			0
\$0388	XGIF	Read:	0	0	0	0	0	0	0	XGIF_78
φυσου	AGIF	Write:								AGIF_76
\$0389	XGIF	Read: Write:	XGIF_77	XGIF_76	XGIF_75	XGIF_74	XGIF_73	XGIF_72	XGIF_71	XGIF_70
\$038A	XGIF	Read: Write:	XGIF_6F	XGIF_6E	XGIF_6D	XGIF_6C	XGIF_6B	XGIF_6A	XGIF_69	XGIF_68
\$023B	XGIF	Read: Write:	XGIF_67	XGIF_66	XGIF_65	XGIF_64	XGIF_63	XGIF_62	XGIF_61	XGIF_60
\$023C	XGIF	Read: Write:	XGIF_5F	XGIF_5E	XGIF_5D	XGIF_5C	XGIF_5B	XGIF_5A	XGIF_59	XGIF_58
\$038D	XGIF	Read: Write:	XGIF_57	XGIF_56	XGIF_55	XGIF_54	XGIF_53	XGIF_52	XGIF_51	XGIF_50
\$038E	XGIF	Read: Write:	XGIF_4F	XGIF_4E	XGIF_4D	XGIF_4C	XGIF_4B	XGIF_4A	XGIF_49	XGIF_48
\$038F	XGIF	Read: Write:	XGIF_47	XGIF_46	XGIF_45	XGIF_44	XGIF_43	XGIF_42	XGIF_41	XGIF_40
\$0390	XGIF	Read: Write:	XGIF_3F	XGIF_3E	XGIF_3D	XGIF_3C	XGIF_3B	XGIF_3A	XGIF_39	XGIF_38
\$0391	XGIF	Read: Write:	XGIF_37	XGIF_36	XGIF_35	XGIF_34	XGIF_33	XGIF_32	XGIF_31	XGIF_30
\$0392	XGIF	Read: Write:	XGIF_2F	XGIF_2E	XGIF_2D	XGIF_2C	XGIF_2B	XGIF_2A	XGIF_29	XGIF_28
\$0393	XGIF	Read: Write:	XGIF_27	XGIF_26	XGIF_25	XGIF_24	XGIF_23	XGIF_22	XGIF_21	XGIF_20
\$0394	XGIF	Read: Write:	XGIF_1F	XGIF_1E	XGIF_1D	XGIF_1C	XGIF_1B	XGIF_1A	XGIF_19	XGIF_18
\$0395	XGIF	Read: Write:	XGIF_17	XGIF_16	XGIF_15	XGIF_14	XGIF_13	XGIF_12	XGIF_11	XGIF_10
\$0396	XGIF	Read: Write:	XGIF_0F	XGIF_0E	XGIF_0D	XGIF_0C	XGIF_0B	XGIF_0A	XGIF_09	0

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\$0380 - \$03BF	XGATE Map

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
\$0397	XGIF	Read:	0	0	0	0	0	0	0	0		
φυσσι	AGIF	Write:										
\$0398	XGSWT (hi)	Read:	0	0	0	0	0	0	0	0		
ψυσσυ	X00VV (III)	Write:				XGSW	TM[7:0]					
\$0399	XGSWT (lo)	Read: Write:		XGSWT[7:0]								
		Read:	0	0 0 0 0 0 0 0								
\$039A	XGSEM (hi)	Write:				XGSEN						
\$039B	XGSEM (lo)	Read: Write:				XGSE						
		Read:	0	0	0	0	0	0	0	0		
\$039C	Reserved	Write:	U	0	0	0	U	U	U	0		
		Read:	0	0	0	0						
\$039D	XGCCR	Write:	U			U	XGN	XGZ	XGV	XGC		
		Read:										
\$039E	XGPC (hi)	Write:				XGPC	[15:8]					
\$039F	XGPC (lo)	Read:				XGPO	C[7:0]					
Ψ000.	7(0)	Write:			1							
\$03A0	Reserved	Read:	0	0	0	0	0	0	0	0		
,		Write:										
\$03A1	Reserved	Read:	0	0	0	0	0	0	0	0		
vvrite:												
\$03A2	XGR1 (hi)	Read:				XGR1	[15:8]					
		Write:										
\$03A3	XGR1 (lo)	Read: Write:				XGR ²	1[7:0]					
		Read:										
\$03A4	XGR2 (hi)	Write:				XGR2	[15:8]					
		Read:										
\$03A5	XGR2 (lo)	Write:				XGR	2[7:0]					
00040	VOD0 (L.)	Read:				VOD0						
\$03A6	XGR3 (hi)	Write:				XGR3	[15:8]					
\$03A7	XGR3 (lo)	Read:				VCD'	2[7:0]					
φυ3Α7	AGR3 (10)	Write:				XGR	5[7.0]					
\$03A8	XGR4 (hi)	Read:				XGR4	[15:8]					
ψυσπο	AGIN4 (III)	Write:				70114	-[13.0]					
\$03A9	XGR4 (lo)	Read:				XGR	4[7·0]					
φοσι το	λοιτι (ιο)	Write:										
\$03AA	XGR5 (hi)	Read:	X(=R5115:X)									
* = =: " *	()	Write:					r1					
\$03AB	XGR5(lo)	Read:				XGR!	5[7:0]					
•	· -/	Write:										
\$03AC	XGR6 (hi)	Read:				XGR6	[15:8]					
		Write:					-					
\$03AD	XGR6 (Io)	Read:				XGR	6[7:0]					
Write:												

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XGATE Map

ψυσου	ψουΣ.		/\ O /\\\	· map							
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
\$03AE	XGR7 (hi)	Read: Write:		XGR7[15:8]							
\$03AF	XGR7 (lo)	Read: Write:		XGR7[7:0]							
\$03B0 - \$03BF	Reserved	Read: Write:		0	0	0	0	0	0	0	

\$03C0 - \$07FF			Reserved									
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
\$03C0	Decembed	Read:	0	0	0	0	0	0	0	0		
- \$07FF	Reserved	Write:										

1.6 Part ID Assignments

\$0380 - \$03BF

The part ID is located in two 8-bit registers PARTIDH and PARTIDL (addresses \$001A and \$001B). The read-only value is a unique part ID for each revision of the chip. **Table 1-2** shows the assigned part ID number and Mask Set number.

Table 1-2 Assigned Part ID Numbers

Device	Mask Set Number	Part ID ¹		
MC9S12XDP512	L40V	\$C400		
MC9S12XDP512	L15Y	\$C410		

NOTES:

1. The coding is as follows:

Bit 15-12: Major family identifier

Bit 11-8: Minor family identifier

Bit 7-4: Major mask set revision number including FAB transfers

Bit 3-0: Minor - non full - mask set revision

Section 2 Signal Description

This section describes signals that connect off-chip. It includes a pinout diagram, a table of signal properties, and detailed discussion of signals. It is built from the signal description sections of the Block User Guides of the individual IP blocks on the device.

2.1 Device Pinout

The XD-Family of devices offers pin-compatible packaged devices to assist with system development and accommodate expansion of the application.

The MC9S12XD-Family and MC9S12XA-Family devices are offered in the following package options:

- 144-pin LQFP package with an external bus interface (address/data bus)
- 112-pin LQFP without external bus interface
- 80-pin QFP without external bus interface

Most pins perform two or more functions, as described in more detail in **Section 2.2 Signal Properties Summary**. **Figure 2-1**, **Figure 2-2** and **Figure 2-3** show the pin assignments for the various packages.

Figure 2-1 MC9S12XD-Family Pin Assignment 144 LQFP Package

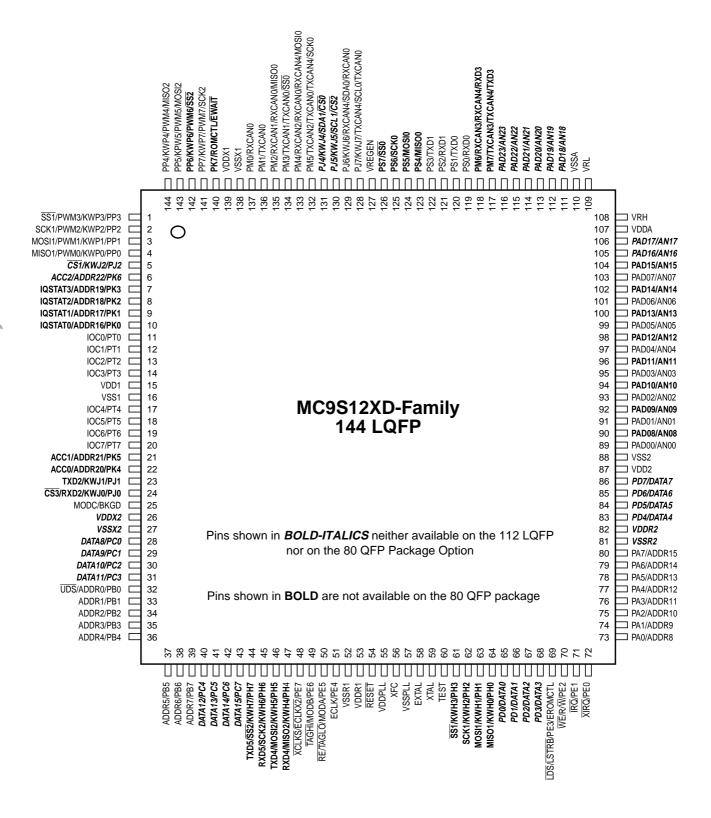


Figure 2-2 MC9S12XD-Family Pin assignments 112 LQFP Package

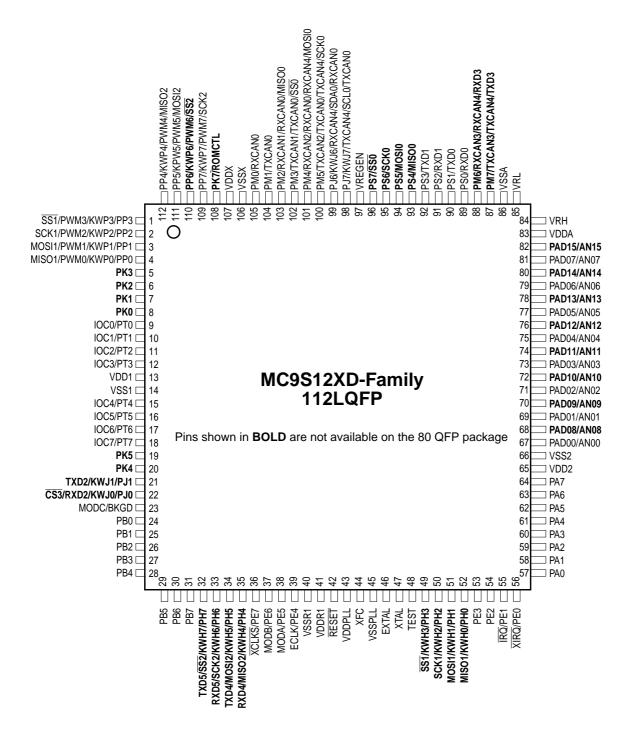
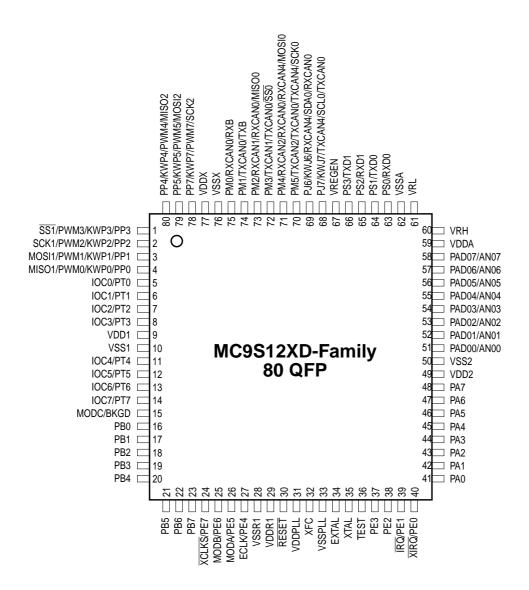


Figure 2-3 MC9S12XD-Family Pin assignments 80 QFP Package



2.2 Signal Properties Summary

Table 2-1 summarizes the pin functionality.

Table 2-1 Signal Properties Summary

	Pin Name	Pin Name	Din Name	Din Name	Pin Name	Dower		nal Pull sistor	
	Funct. 1	Funct. 2	Funct. 3	Pin Name Funct. 4	Funct. 5	Power Supply	CTRL	Reset State	Description
-	EXTAL		_		_	VDDPLL	NA	NA	Oscillator Pins
	XTAL	_	_		_	VDDPLL	NA	NA	Oscillator Firis
	RESET	_	_	_	_	VDDR	PU	LLUP	External Reset
	TEST	_	_	_	_	N.A.	RESET PIN	DOWN	Test Input
	VREGEN	_	_	_	_	VDDX	Always on	Up	Voltage Regulator Enable Input
Ţ	XFC	_	_	_	_	VDDPLL	NA	NA	PLL Loop Filter
9	BKGD	MODC	_	_	_	VDDR	Always on	Up	Background Debug
	PAD[23:08]	AN[23:8]	_		_	VDDA	PER0 AD1/ PER1 AD1	Disabled	Port AD Inputs of ATD1, Analog Inputs of ATD1
9	PAD[07:00]	AN[7:0]	_	_	_	VDDA	PER1 AD0	Disabled	Port AD Inputs of ATD0, Analog Inputs of ATD0
	PA[7:0]	ADDR[15:8]	IVD[15:8]	_	_	VDDR	PUCR	Disabled	Port A I/O, Address Bus, Internal Visibility Data
	PB[7:1]	ADDR[7:1]	IVD[7:0]	1	_	VDDR	PUCR	Disabled	Port B I/O, Address Bus, Internal Visibility Data
e	PB0	ADDR0	UDS			VDDR	PUCR	Disabled	Port B I/O, Address Bus, Upper Data Strobe
N.	PC[7:0]	DATA[15:8]	_	1	_	VDDR	PUCR	Disabled	Port C I/O, Data Bus
7	PD[7:0]	DATA[7:0]	_		_	VDDR	PUCR	Disabled	Port D I/O, Data Bus
0	PE7	ECLKX2	XCLKS	-	_	VDDR	PUCR	Up	Port E I/O, System clock output, Clock Select
	PE6	TAGHI	MODB	_	_	VDDR	pin	RESET is low: own	Port E I/O, Tag High, Mode Input
	PE5	RE	MODA	TAGLO	_	VDDR	pin	RESET is low: own	Port E I/O, Read Enable, Mode Input, Tag Low Input
	PE4	ECLK	_	_	_	VDDR	PUCR	Up	Port E I/O, Bus Clock Output
	PE3	LSTRB	LDS	EROMCTL	_	VDDR	PUCR	Up	Port E I/O, Low Byte Data strobe, EROMON control
	PE2	R/W	WE	_	_	VDDR	PUCR	Up	Port E I/O, Read/Write
	PE1	ĪRQ	_	_	_	VDDR	PUCR	Up	Port E Input, Maskable Interrupt

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D:	n Nama	Din Name	Din Name	Din Nome	Din Nome	Dawar		nal Pull sistor	
1	n Name unct. 1	Pin Name Funct. 2	Pin Name Funct. 3	Pin Name Funct. 4	Pin Name Funct. 5	Power Supply	CTRL	Reset State	Description
	PE0	XIRQ	_	_	_	VDDR	PUCR	Up	Port E Input, Non Maskable Interrupt
	PH7	KWH7	SS2	TXD5	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SS of SPI2, TXD of SCI5
	PH6	KWH6	SCK2	RXD5	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SCK of SPI2, RXD of SCI5
	PH5	KWH5	MOSI2	TXD4	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MOSI of SPI2, TXD of SCI4
	PH4	KWH4	MISO2	RXD4	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MISO of SPI2, RXD of SCI4
	PH3	KWH3	SS1	_	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SS of SPI1
pc	PH2	KWH2	SCK1	_	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SCK of SPI1
Ţ	PH1	KWH1	MOSI1	_		VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MOSI of SPI1
	PH0	KWH0	MISO1	_	_	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MISO of SPI1
<u> </u>	PJ7	KWJ7	TXCAN4	SCL0	TXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, TX of CAN4, SCL of IIC0, TX of CAN0
<u> </u>	PJ6	KWJ6	RXCAN4	SDA0	RXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, RX of CAN4, SDA of IIC0, RX of CAN0
9	PJ5	KWJ5	SCL1	CS2	_	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, SCL of IIC1, Chip Select 2
	PJ4	KWJ4	SDA1	CS0	_	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, SDA of IIC1, Chip Select 0
n	PJ2	KWJ2	CS1	_	_	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupts, Chip Select 1
	PJ1	KWJ1	TXD2	_	_	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupts, TXD of SCI2
S	PJ0	KWJ0	RXD2	CS3	_	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupts, RXD of SCI2
9	PK7	EWAIT	ROMCTL	_	_	VDDX	PUCR	Up	Port K I/O, EWAIT input, ROM On Control
ш.	PK[6:4]	ADDR [22:20]	ACC[2:0]	_	_	VDDX	PUCR	Up	Port K I/O, Extended Addresses, Access Source for external Access
	PK3	ADDR19	IQSTAT3	_	_	VDDX	PUCR	Up	Extended Address, PIPE status
	PK2	ADDR18	IQSTAT2	_	_	VDDX	PUCR	Up	Extended Address, PIPE status
	PK1	ADDR17	IQSTAT1	_	_	VDDX	PUCR	Up	Extended Address, PIPE status
	PK0	ADDR16	IQSTAT0	_	_	VDDX	PUCR	Up	Extended Address, PIPE status
	PM7	TXCAN3	TXD3	TXCAN4	_	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of CAN3&4, TXD of SCI3
	PM6	RXCAN3	RXD3	RXCAN4	_	VDDX	PERM/ PPSM	Disabled	Port M I/O RX of CAN3&4, RXD of SCI3

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Pin Name	Pin Name	Din Nama	Pin Name	Pin Name	Power		nal Pull sistor	
Funct. 1	Funct. 2	Funct. 3	Funct. 4	Funct. 5	Supply	CTRL	Reset State	Description
PM5	TXCAN2	TXCAN0	TXCAN4	SCK0	VDDX	PERM/ PPSM	Disabled	Port M I/OCAN0, CAN2, CAN4, SCK of SPI0
PM4	RXCAN2	RXCAN0	RXCAN4	MOSI0	VDDX	PERM/ PPSM	Disabled	Port M I/O, CAN0, CAN2, CAN4, MOSI of SPI0
PM3	TXCAN1	TXCAN0	_	SS0	VDDX	PERM/ PPSM	Disabled	Port M I/O TX of CAN1, CAN0, SS of SPI0
PM2	RXCAN1	RXCAN0	_	MISO0	VDDX	PERM/ PPSM	Disabled	Port M I/O, RX of CAN1, CAN0, MISO of SPI0
PM1	TXCAN0		_	_	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of CAN0
РМ0	RXCAN0		_	_	VDDX	PERM/ PPSM	Disabled	Port M I/O, RX of CAN0
PP7	KWP7	PWM7	SCK2	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 7 of PWM, SCK of SPI2
PP6	KWP6	PWM6	SS2	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 6 of PWM, SS of SPI2
PP5	KWP5	PWM5	MOSI2	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 5 of PWM, MOSI of SPI2
PP4	KWP4	PWM4	MISO2	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 4 of PWM, MISO2 of SPI2
PP3	KWP3	PWM3	SS1	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 3 of PWM, SS of SPI1
PP2	KWP2	PWM2	SCK1	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 2 of PWM, SCK of SPI1
PP1	KWP1	PWM1	MOSI1	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 1 of PWM, MOSI of SPI1
PP0 PS7	KWP0	PWM0	MISO1	_	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 0 of PWM, MISO2 of SPI1
PS7	SS0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, SS of SPI0
PS6	SCK0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, SCK of SPI0
PS5	MOSI0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, MOSI of SPI0
PS4	MISO0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, MISO of SPI0
PS3	TXD1	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, TXD of SCI1
PS2	RXD1	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, RXD of SCI1
PS1	TXD0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, TXD of SCI0

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	Pin Name	Din Nama	Din Nama	Din Nama	Din Nama	Dower	Internal Pull Resistor		
	Funct. 1	Funct. 2	Funct. 3	Funct. 4	lame Pin Name Powe Supply		CTRL	Reset State	Description
•	PS0	RXD0	_	_	_	VDDX	PERS/ PPSS	Up	Port S I/O, RXD of SCI0
	PT[7:0]	IOC[7:0]	_	_	_	VDDX	PERT/ PPST	Disabled	Port T I/O, Timer channels

NOTE: For devices assembled in 80-pin and 112-pin packages all non-bonded out pins should be configured as outputs after reset in order to avoid current drawn from floating inputs. Refer to **Table 2-1** for affected pins.

2.3 Detailed Signal Descriptions

2.3.1 EXTAL, XTAL — Oscillator Pins

EXTAL and XTAL are the crystal driver and external clock pins. On reset all the device clocks are derived from the EXTAL input frequency. XTAL is the crystal output.

2.3.2 RESET — External Reset Pin

The **RESET** pin is an active low bidirectional control signal. It acts as an input to initialize the MCU to a known start-up state, and an output when an internal MCU function causes a reset. The **RESET** pin has an internal pullup device.

2.3.3 TEST — Test Pin

This input only pin is reserved for test. This pin has a pulldown device.

NOTE: The TEST pin must be tied to VSS in all applications.

2.3.4 VREGEN — Voltage Regulator Enable Pin

This input only pin enables or disables the on-chip voltage regulator. The input has a pullup device.

2.3.5 XFC — PLL Loop Filter Pin

Please ask your Motorola representative for the interactive application note to compute PLL loop filter elements. Any current leakage on this pin must be avoided.

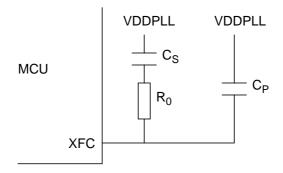


Figure 2-4 PLL Loop Filter Connections

2.3.6 BKGD / MODC — Background Debug and Mode Pin

The BKGD/MODC pin is used as a pseudo-open-drain pin for the background debug communication. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODC bit at the rising edge of RESET. The BKGD pin has a pullup device.

2.3.7 PAD[23:08] / AN[23:8] — Port AD Input Pin of ATD1

PAD[23:08] are general purpose input or output pins and analog inputs AN[23:8] of the analog to digital converter ATD1.

2.3.8 PAD[07:00] / AN[7:0] — Port AD Input Pins of ATD0

PAD[07:00] are general purpose input or output pins and analog inputs AN[7:0] of the analog to digital converter ATD0.

2.3.9 PA[7:0] / ADDR[15:8] / IVD[15:8] — Port A I/O Pins

PA7-PA0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the external address bus. In MCU emulation modes of operation, these pins are used for external address bus and internal visibility read data.

2.3.10 PB[7:1] / ADDR[7:1] / IVD[7:1] — Port B I/O Pins

PB7-PB1 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the external address bus. In MCU emulation modes of operation, these pins are used for external address bus and internal visibility read data.

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2.3.11 PB0 / ADDR0 / \(\overline{UDS}\) / IVD[0] — Port B I/O Pin

PB0 is a general purpose input or output pin. In MCU expanded modes of operation, this pin is used for the external address bus ADDR0 or as upper data strobe signal. In MCU emulation modes of operation, this pin is used for external address bus ADDR0 and internal visibility read data IVD0.

2.3.12 PC[7:0] / DATA [15:8] — Port C I/O Pins

PC7-PC0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the external data bus.

The input voltage thresholds for PC[7:0] can be configured to reduced levels, to allow data from an external 3.3V peripheral to be read by the MCU operating at 5.0V. The input voltage thresholds for PC[7:0] are configured to reduced levels out of reset in expanded and emulation modes. The input voltage thresholds for PC[7:0] are configured to 5V levels out of reset in normal modes.

2.3.13 PD[7:0] / DATA [7:0] — Port D I/O Pins

PD7-PD0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the external data bus.

The input voltage thresholds for PD[7:0] can be configured to reduced levels, to allow data from an external 3.3V peripheral to be read by the MCU operating at 5.0V. The input voltage thresholds for PD[7:0] are configured to reduced levels out of reset in expanded and emulation modes. The input voltage thresholds for PC[7:0] are configured to 5V levels out of reset in normal modes.

2.3.14 PE7 / ECLKX2 / XCLKS — Port E I/O Pin 7

PE7 is a general purpose input or output pin. The $\overline{\text{XCLKS}}$ is an input signal which controls whether a crystal in combination with the internal loop controlled (low power) Pierce oscillator is used or whether full swing Pierce oscillator/external clock circuitry is used.

The XCLKS pin selects the oscillator configuration during RESET low phase while a clock quality check is ongoing. This is the case for:

- Power on Reset or Low Voltage Reset
- Clock Monitor Reset
- Any Reset while in Self Clock Mode or Full Stop Mode

The selected oscillator configuration is frozen with the rising edge of RESET.

The pin can be configured to drive the internal system clock ECLKX2.



Figure 2-5 Loop Controlled Pierce Oscillator Connections (PE7=1)

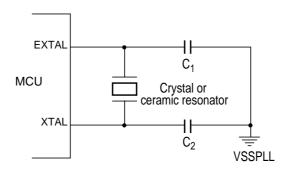


Figure 2-6 Full Swing Pierce Oscillator Connections (PE7=0)

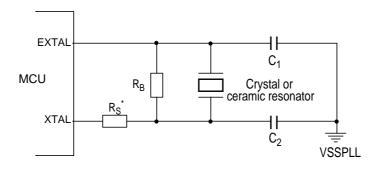
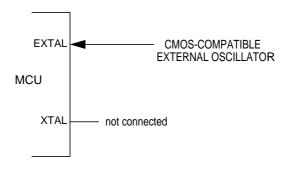


Figure 2-7 External Clock Connections (PE7=0)



2.3.15 PE6 / MODB / TAGHI — Port E I/O Pin 6

PE6 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODB bit at the rising edge of \overline{RESET} . This pin is an input with a pull-down device which is only active when \overline{RESET} is low. \overline{TAGHI} is used to tag the high half of the instruction word being read into the instruction queue.

The input voltage threshold for PE6 can be configured to reduced levels, to allow data from an external 3.3V peripheral to be read by the MCU operating at 5.0V. The input voltage threshold for PE6 is configured to reduced levels out of reset in expanded and emulation modes.

2.3.16 PE5 / MODA / TAGLO / RE — Port E I/O Pin 5

PE5 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODA bit at the rising edge of \overline{RESET} . This pin is shared with the Read Enable \overline{RE} output. This pin is an input with a pull-down device which is only active when \overline{RESET} is low. \overline{TAGLO} is used to tag the low half of the instruction word being read into the instruction queue.

The input voltage threshold for PE5 can be configured to reduced levels, to allow data from an external 3.3V peripheral to be read by the MCU operating at 5.0V. The input voltage threshold for PE5 is configured to reduced levels out of reset in expanded and emulation modes.

2.3.17 PE4 / ECLK — Port E I/O Pin 4

PE4 is a general purpose input or output pin. It can be configured to drive the internal bus clock ECLK. ECLK can be used as a timing reference.

2.3.18 PE3 / LSTRB / LDS / EROMCTL— Port E I/O Pin 3

PE3 is a general purpose input or output pin. In MCU expanded modes of operation, \overline{LSTRB} or \overline{LDS} can be used for the low byte strobe function to indicate the type of bus access. At the rising edge of \overline{RESET} the state of this pin is latched to the EROMON bit.

2.3.19 PE2 / R/W / WE—Port E I/O Pin 2

PE2 is a general purpose input or output pin. In MCU expanded modes of operations, this pin drives the read/write output signal or write enable output signal for the external bus. It indicates the direction of data on the external bus.

2.3.20 PE1 / IRQ — Port E Input Pin 1

PE1 is a general purpose input pin and the maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.21 PE0 / XIRQ — Port E Input Pin 0

PE0 is a general purpose input pin and the non-maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.22 PH7 / KWH7 / SS2 / TXD5 — Port H I/O Pin 7

PH7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as slave select pin \overline{SS} of the Serial Peripheral Interface 2 (SPI2). It can be configured as the transmit pin TXD of Serial Communication Interface 5 (SCI5).

2.3.23 PH6 / KWH6 / SCK2 / RXD5 — Port H I/O Pin 6

PH6 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as serial clock pin SCK of the Serial Peripheral Interface 2 (SPI2). It can be configured as the receive pin RXD of Serial Communication Interface 5 (SCI5).

2.3.24 PH5 / KWH5 / MOSI2 / TXD4 — Port H I/O Pin 5

PH5 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 2 (SPI2). It can be configured as the transmit pin TXD of Serial Communication Interface 4 (SCI4).

2.3.25 PH4 / KWH4 / MISO2 / RXD4 — Port H I/O Pin 2

PH4 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as master input (during master mode) or slave output (during slave mode) pin MISO of the Serial Peripheral Interface 2 (SPI2). It can be configured as the receive pin RXD of Serial Communication Interface 4 (SCI4).

2.3.26 PH3 / KWH3 / SS1 — Port H I/O Pin 3

PH3 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as slave select pin \overline{SS} of the Serial Peripheral Interface 1 (SPI1).

2.3.27 PH2 / KWH2 / SCK1 — Port H I/O Pin 2

PH2 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as serial clock pin SCK of the Serial Peripheral Interface 1 (SPI1).

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2.3.28 PH1 / KWH1 / MOSI1 — Port H I/O Pin 1

PH1 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 1 (SPI1).

2.3.29 PH0 / KWH0 / MISO1 — Port H I/O Pin 0

PH0 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as master input (during master mode) or slave output (during slave mode) pin MISO of the Serial Peripheral Interface 1 (SPI1).

2.3.30 PJ7 / KWJ7 / TXCAN4 / SCL0 / TXCAN0— PORT J I/O Pin 7

PJ7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the transmit pin TXCAN for the Motorola Scalable Controller Area Network controller 0 or 4 (CAN0 or CAN4) or as the serial clock pin SCL of the IIC0 module.

2.3.31 PJ6 / KWJ6 / RXCAN4 / SDA0 / RXCAN0 — PORT J I/O Pin 6

PJ6 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the receive pin RXCAN for the Motorola Scalable Controller Area Network controller 0 or 4 (CAN0 or CAN4) or as the serial data pin SDA of the IIC0 module.

2.3.32 PJ5 / KWJ5 / SCL1 / CS2 — PORT J I/O Pin 5

PJ5 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the serial clock pin SCL of the IIC1 module. It can be configured to provide a chip select output.

2.3.33 PJ4 / KWJ4 / SDA1 / CS0 — PORT J I/O Pin 4

PJ4 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the serial data pin SDA of the IIC1 module. It can be configured to provide a chip select output.

2.3.34 PJ2 / KWJ2 / CS1 — PORT J I/O Pin 2

PJ2 is a general purpose input or output pins. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured to provide a chip select output.

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2.3.35 PJ1 / KWJ1 / TXD2 — PORT J I/O Pin 1

PJ1 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the transmit pin TXD of the Serial Communication Interface 2 (SCI2).

2.3.36 PJ0 / KWJ0 / RXD2 / CS3 — PORT J I/O Pin 0

PJ0 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as the receive pin RXD of the Serial Communication Interface 2 (SCI2). It can be configured to provide a chip select output.

2.3.37 PK7 / EWAIT / ROMCTL — Port K I/O Pin 7

PK7 is a general purpose input or output pin. During MCU emulation modes and normal expanded modes of operation, this pin is used to enable the Flash EEPROM memory in the memory map (ROMCTL). At the rising edge of \overline{RESET} , the state of this pin is latched to the ROMON bit. The \overline{EWAIT} input signal maintains the external bus access until the external device is ready to capture data (write) or provide data (read).

The input voltage threshold for PK7 can be configured to reduced levels, to allow data from an external 3.3V peripheral to be read by the MCU operating at 5.0V. The input voltage threshold for PK7 is configured to reduced levels out of reset in expanded and emulation modes.

2.3.38 PK[6:4] / ADDR[22:20] / ACC[2:0] — Port K I/O Pin [6:4]

PK[6:4] are general purpose input or output pins. During MCU expanded modes of operation, the ACC[2:0] signals are used to indicate the access source of the bus cycle. This pins also provide the expanded addresses ADDR[22:20] for the external bus. In Emulation modes ACC[2:0] is available and is time multiplexed with the high addresses

2.3.39 PK[3:0] / ADDR[19:16] / IQSTAT[3:0] — Port K I/O Pins [3:0]

PK3-PK0 are general purpose input or output pins. In MCU expanded modes of operation, these pins provide the expanded address ADDR[19:16] for the external bus and carry instruction pipe information.

2.3.40 PM7 / TXCAN3 / TXCAN4 / TXD3 — Port M I/O Pin 7

PM7 is a general purpose input or output pin. It can be configured as the transmit pin TXCAN of the Motorola Scalable Controller Area Network controller 3 or 4 (CAN3 or CAN4). PM7 can be configured as the transmit pin TXD3 of the Serial Communication Interface 3 (SCI3).



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2.3.41 PM6 / RXCAN3 / RXCAN4 / RXD3 — Port M I/O Pin 6

PM6 is a general purpose input or output pin. It can be configured as the receive pin RXCAN of the Motorola Scalable Controller Area Network controller 3 or 4 (CAN3 or CAN4). PM6 can be configured as the receive pin RXD3 of the Serial Communication Interface 3 (SCI3).

2.3.42 PM5 / TXCAN0 / TXCAN2 / TXCAN4 / SCK0 — Port M I/O Pin 5

PM5 is a general purpose input or output pin. It can be configured as the transmit pin TXCAN of the Motorola Scalable Controller Area Network controllers 0, 2 or 4 (CAN0, CAN2 or CAN4). It can be configured as the serial clock pin SCK of the Serial Peripheral Interface 0 (SPI0).

2.3.43 PM4 / RXCAN0 / RXCAN2 / RXCAN4 / MOSI0 — Port M I/O Pin 4

PM4 is a general purpose input or output pin. It can be configured as the receive pin RXCAN of the Motorola Scalable Controller Area Network controllers 0,2 or 4 (CAN0, CAN2 or CAN4). It can be configured as the master output (during master mode) or slave input pin (during slave mode) MOSI for the Serial Peripheral Interface 0 (SPI0).

2.3.44 PM3 / TXCAN1 / TXCAN0 / SS0 — Port M I/O Pin 3

PM3 is a general purpose input or output pin. It can be configured as the transmit pin TXCAN of the Motorola Scalable Controller Area Network controllers 1 or 0 (CAN1 or CAN0). It can be configured as the slave select pin \overline{SS} of the Serial Peripheral Interface 0 (SPI0).

2.3.45 PM2 / RXCAN1 / RXCAN0 / MISO0 — Port M I/O Pin 2

PM2 is a general purpose input or output pin. It can be configured as the receive pin RXCAN of the Motorola Scalable Controller Area Network controllers 1 or 0 (CAN1 or CAN0). It can be configured as the master input (during master mode) or slave output pin (during slave mode) MISO for the Serial Peripheral Interface 0 (SPI0).

2.3.46 PM1 / TXCAN0 — Port M I/O Pin 1

PM1 is a general purpose input or output pin. It can be configured as the transmit pin TXCAN of the Motorola Scalable Controller Area Network controller 0 (CAN0).

2.3.47 PM0 / RXCAN0 — Port M I/O Pin 0

PM0 is a general purpose input or output pin. It can be configured as the receive pin RXCAN of the Motorola Scalable Controller Area Network controller 0 (CAN0).

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2.3.48 PP7 / KWP7 / PWM7 / SCK2 — Port P I/O Pin 7

PP7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 7 output. It can be configured as serial clock pin SCK of the Serial Peripheral Interface 2 (SPI2).

2.3.49 PP6 / KWP6 / PWM6 / SS2 — Port P I/O Pin 6

PP6 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 6 output. It can be configured as slave select pin \overline{SS} of the Serial Peripheral Interface 2 (SPI2).

2.3.50 PP5 / KWP5 / PWM5 / MOSI2 — Port P I/O Pin 5

PP5 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 5 output. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 2 (SPI2).

2.3.51 PP4 / KWP4 / PWM4 / MISO2 — Port P I/O Pin 4

PP4 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 4 output. It can be configured as master input (during master mode) or slave output (during slave mode) pin MISO of the Serial Peripheral Interface 2 (SPI2).

2.3.52 PP3 / KWP3 / PWM3 / SS1 — Port P I/O Pin 3

PP3 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 3 output. It can be configured as slave select pin \overline{SS} of the Serial Peripheral Interface 1 (SPI1).

2.3.53 PP2 / KWP2 / PWM2 / SCK1 — Port P I/O Pin 2

PP2 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 2 output. It can be configured as serial clock pin SCK of the Serial Peripheral Interface 1 (SPI1).

2.3.54 PP1 / KWP1 / PWM1 / MOSI1 — Port P I/O Pin 1

PP1 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 1 output. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 1 (SPI1).

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2.3.55 PP0 / KWP0 / PWM0 / MISO1 — Port P I/O Pin 0

PPO is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 0 output. It can be configured as master input (during master mode) or slave output (during slave mode) pin MISO of the Serial Peripheral Interface 1 (SPI1).

2.3.56 PS7 / SS0 — Port S I/O Pin 7

PS7 is a general purpose input or output pin. It can be configured as the slave select pin \overline{SS} of the Serial Peripheral Interface 0 (SPI0).

2.3.57 PS6 / SCK0 — Port S I/O Pin 6

PS6 is a general purpose input or output pin. It can be configured as the serial clock pin SCK of the Serial Peripheral Interface 0 (SPI0).

2.3.58 PS5 / MOSI0 — Port S I/O Pin 5

PS5 is a general purpose input or output pin. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 0 (SPI0).

2.3.59 PS4 / MISO0 — Port S I/O Pin 4

PS4 is a general purpose input or output pin. It can be configured as master input (during master mode) or slave output pin (during slave mode) MOSI of the Serial Peripheral Interface 0 (SPI0).

2.3.60 PS3 / TXD1 — Port S I/O Pin 3

PS3 is a general purpose input or output pin. It can be configured as the transmit pin TXD of Serial Communication Interface 1 (SCI1).

2.3.61 PS2 / RXD1 — Port S I/O Pin 2

PS2 is a general purpose input or output pin. It can be configured as the receive pin RXD of Serial Communication Interface 1 (SCI1).

2.3.62 PS1 / TXD0 — Port S I/O Pin 1

PS1 is a general purpose input or output pin. It can be configured as the transmit pin TXD of Serial Communication Interface 0 (SCI0).

2.3.63 PS0 / RXD0 — Port S I/O Pin 0

PS0 is a general purpose input or output pin. It can be configured as the receive pin RXD of Serial Communication Interface 0 (SCI0).

2.3.64 PT[7:0] / IOC[7:0] — Port T I/O Pins [7:0]

PT7-PT0 are general purpose input or output pins. They can be configured as input capture or output compare pins IOC7-IOC0 of the Enhanced Capture Timer (ECT).

2.4 Power Supply Pins

MC9S12XDP512 power and ground pins are described below.

NOTE: All VSS pins must be connected together in the application.

2.4.1 VDDX1, VDDX2, VSSX1, VSSX2 — Power & Ground Pins for I/O Drivers

External power and ground for I/O drivers. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. Bypass requirements depend on how heavily the MCU pins are loaded.

2.4.2 VDDR1, VDDR2, VSSR1, VSSR2 — Power & Ground Pins for I/O Drivers & for Internal Voltage Regulator

External power and ground for I/O drivers and input to the internal voltage regulator. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. Bypass requirements depend on how heavily the MCU pins are loaded.

2.4.3 VDD1, VDD2, VSS1, VSS2 — Core Power Pins

Power is supplied to the MCU through VDD and VSS. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible. This 2.5V supply is derived from the internal voltage regulator. There is no static load on those pins allowed. The internal voltage regulator is turned off, if VREGEN is tied to ground.

NOTE: No load allowed except for bypass capacitors.

2.4.4 VDDA, VSSA — Power Supply Pins for ATD and VREG

VDDA, VSSA are the power supply and ground input pins for the voltage regulator and the analog to digital converters.

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2.4.5 VRH, VRL — ATD Reference Voltage Input Pins

VRH and VRL are the reference voltage input pins for the analog to digital converter.

2.4.6 VDDPLL, VSSPLL — Power Supply Pins for PLL

Provides operating voltage and ground for the Oscillator and the Phased-Locked Loop. This allows the supply voltage to the Oscillator and PLL to be bypassed independently. This 2.5V voltage is generated by the internal voltage regulator.

NOTE: No load allowed except for bypass capacitors.

Table 2-2 MC9S12XDP512 Power and Ground Connection Summary

	Pin Number			Nominal		
Mnemonic	144-pin LQFP	112-pin LQFP	80-pin QFP	Voltage	Description	
VDD1, 2	15, 87	13, 65	9, 49	2.5 V	Internal power and ground	
VSS1, 2	16, 88	14, 66	10, 50	0V	generated by internal regulator	
VDDR1	53	41	29	5.0 V	External power and ground,	
VSSR1	52	40	28	0 V	supply to pin drivers and internal voltage regulator	
VDDX1	139	107	77	5.0 V	External power and ground,	
VSSX1	138	106	76	0 V	supply to pin drivers	
VDDX2	26	N.A.	N.A.	5.0 V	External power and ground,	
VSSX2	27	N.A.	N.A.	0 V	supply to pin drivers	
VDDR2	82	N.A.	N.A.	5.0 V	External power and ground,	
VSSR2	81	N.A.	N.A.	0 V	supply to pin drivers	
VDDA	107	83	59	5.0 V	Operating voltage and ground	
VSSA	110	86	62	0 V	for the analog-to-digital converters and the reference for the internal voltage regulator, allows the supply voltage to the A/D to be bypassed independently.	
VRL	109	85	61	0 V	Reference voltages for the	
VRH	108	84	60	5.0 V	analog-to-digital converter.	
VDDPLL	55	43	31	2.5 V	Provides operating voltage and	
VSSPLL	57	45	33	0 V	ground for the Phased-Locked Loop. This allows the supply voltage to the PLL to be bypassed independently. Internal power and ground generated by internal regulator.	
VREGEN	127	97	N.A.	5V	Internal Voltage Regulator enable/disable	

2.4.7 VREGEN — On Chip Voltage Regulator Enable

Enables the internal 5V to 2.5V voltage regulator. If this pin is tied low, VDD1,2 and VDDPLL must be supplied externally.

Section 3 System Clock Description

3.1 Overview

The Clock and Reset Generator module (CRG) provides the internal clock signals for the core and all peripheral modules. **Figure 3-1** shows the clock connections from the CRG to all modules.

Consult the CRG Block User Guide for details on clock generation.

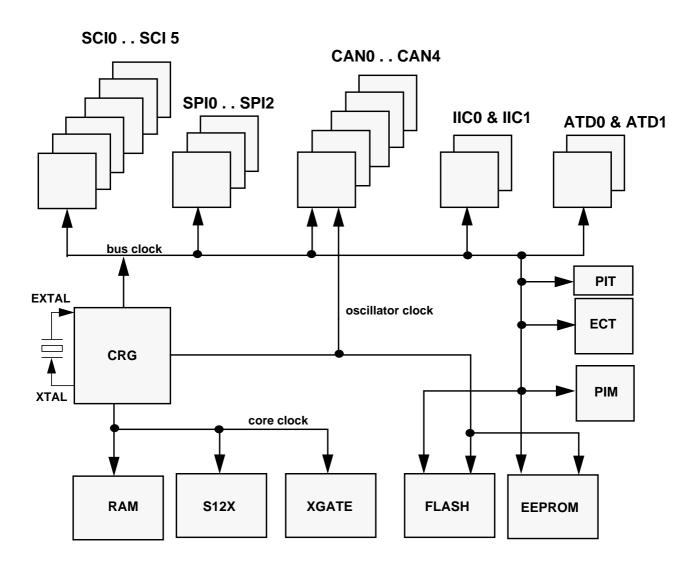


Figure 3-1 Clock Connections

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The MCU's system clock can be supplied in several ways enabling a range of system operating frequencies to be supported:

- the on chip phase Locked Loop (PLL)
- the pll self clocking
- the Oscillator

The clock generated by the PLL or Oscillator provides the main system clock frequencies Core Clock and Bus Clock. As shown in **Figure 3-1** this system clocks are used throughout the MCU to drive the Core, the memories and the peripherals.

The Program Flash memory and the EEPROM are supplied by the Bus Clock and the Oscillator clock. The Oscillator clock is used as a time base to derive the program and erase times for the NVM's. Consult the FTX512k4 block guide and the EETX4K block guide for more details on the operation of the NVM's.

The CAN modules may be configured to have their clock sources derived either from the bus clock or directly from the Oscillator clock. This allows the user to select its clock based on the required jitter performance. Consult MSCAN block description for more details on the operation and configuration of the CAN blocks.

The frequency generated by the PLL is determined by the two registers REFDIV and SYNR.

Please note that it is possible to configure the PLL to generate a system frequency higher than that supported by the design of the device. It is the responsibility of the user to insure that the device is operated within its specified limits at all time.

In order to ensure the presence of the clock the MCU includes an on-chip Clock Monitor connected to the output of the Oscillator. The Clock Monitor can be configured to invoke the PLL self clocking mode or to generate a system reset if it is allowed to time out as a result of no oscillator clock being present.

In addition to the clock monitor the MCU also provides a clock quality checker which performs a more accurate check of the clock. The clock quality checker counts a predetermined number of clock edges within a defined time window to insure that the clock is running. The checker can be invoked following specific events such as on wake-up or clock monitor failure.



Section 4 Modes of Operation

4.1 Overview

The MCU can operate in six different user modes. The different user modes, the state of **ROMCTL** and **EROMCTL** pin on rising edge of **RESET** and the security state of the MCU affects the following device characteristics:

- External bus interface configuration
- Flash in memory map or not
- Debug features enabled or disabled

The **XCLKS** pin defines the configuration of the on chip oscillator and the **VREGEN** pin defines whether the on chip voltage regulator is enabled or disabled.

4.2 User Modes

4.2.1 Normal Expanded Mode

Ports K, A and B are configured as a 23-bit address bus, Ports C and D are configured as a 16-bit data bus, and Port E provides bus control and status signals. This mode allows 16-bit external memory and peripheral devices to be interfaced to the system. The fastest external bus rate is divide by 2 from the internal bus rate.

4.2.2 Normal Single-Chip Mode

There is no external bus in this mode. The processor program is executed from internal memory. Ports A, B,C,D, K, and most pins of Port E are available as general-purpose I/O.

4.2.3 Special Single-Chip Mode

This mode is used for debugging single-chip operation, boot-strapping, or security related operations. The background debug module BDM is active in this mode. The CPU executes a monitor program located in an on-chip ROM. BDM firmware is waiting for additional serial commands through the **BKGD** pin. There is no external bus after reset in this mode.

4.2.4 Emulation of Expanded Mode

Developers use this mode for emulation systems in which the users target application is Normal Expanded Mode. Code is executed from external memory or from internal memory depending on the state of ROMON and EROMON bit. In this mode the internal operation is visible on external bus interface.



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4.2.5 Emulation of Single-Chip Mode

Developers use this mode for emulation systems in which the user s target application is Normal Single-Chip Mode. Code is executed from external memory or from internal memory depending on the state of ROMON and EROMON bit . In this mode the internal operation is visible on external bus interface.

4.2.6 Special Test Mode

Motorola internal use only.

4.3 Low Power Modes

The microcontroller features two main low power modes. Consult the respective Block Guide for information on the module behavior in System Stop, System Pseudo Stop, and System Wait Mode. An important source of information about the clock system is the Clock and Reset Generator Block Guide (CRG).

4.3.1 System Stop Modes

The System Stop Modes are entered if the CPU executes the STOP instruction and the XGATE doesn't execute a thread and the XGFACT bit in the XGMCTL register is cleared. Depending on the state of the PSTP bit in the CLKSEL register the MCU goes into Pseudo Stop Mode or Full Stop Mode. Please refer to CRG Block Guide. Asserting **RESET**, **XIRQ**, **IRQ** or any other interrupt end the System Stop Modes.

4.3.1.1 Pseudo Stop Mode

In this mode the clocks are stopped but the oscillator is still running and the Real Time Interrupt (RTI) or Watchdog (COP) sub module can stay active. Other peripherals are turned off. This mode consumes more current than the System Stop Mode, but the wake up time from this mode is significantly shorter.

4.3.1.2 Full Stop Mode

The oscillator is stopped in this mode. All clocks are switched off. All counters and dividers remain frozen.

4.3.2 System Wait Mode

This mode is entered when the CPU executes the WAI instruction. In this mode the CPU will not execute instructions. The internal CPU clock is switched off. All peripherals and the XGATE can be active in System Wait Mode. For further power consumption the peripherals can individually turn off their local clocks. Asserting **RESET**, **XIRQ**, **IRQ** or any other interrupt that has not been masked ends System Wait Mode.



4.3.3 Run Mode

Although this is not a low power mode, unused peripheral modules should not be enabled in order to save power.

4.4 Freeze Mode

The Enhanced Capture Timer, Pulse Width Modulator, Analog Digital Converters and the Periodic Interrupt Timer provide a software programmable option to freeze the module status during the Background Debug Module is active. This is useful when debugging application software. For detailed description of the behavior of the ATD0, ATD1, ECT, PWM and PIT during Background Debug Module is active consult the corresponding Block Guides.

4.5 Chip Configuration Summary

4.5.1 Mode Selection

The operating mode out of reset is determined by the states of the **MODC**, **MODB**, and **MODA** pins during reset (**Table 4-1**). The MODC, MODB, and MODA bits in the MODE register show the current operating mode and provide limited mode switching during operation. The states of the **MODC**, **MODB**, and **MODA** pins are latched into these bits on the rising edge of **RESET**.

Table 1 1 mede colociisi							
BKGD = MODC	PE6 = MODB	PE5 = MODA	Mode Description				
0	0	0	Special Single Chip Mode				
0	1	1	Emulation Expanded Mode				
0	1	0	Special Test Mode				
0	0	1	Emulation Single Chip Mode				
1	0	0	Normal Single Chip Mode				
1	0	1	Normal Expanded Mode				
1	1	Х	Reserved				

Table 4-1 Mode selection

4.5.2 ROMON and EROMON Configuration

In Normal Expanded Mode and in Emulation Modes the ROMON bit and the EROMON bit in the MISC register defines if the on chip Flash memory is the memory map or not. For a detailed description of the ROMON and EROMON bits refer to the S12XMMC Block Guide.

The state of the **ROMCTL** pin (**PK7**) is latched into the ROMON bit in the MISC register on the rising edge of the \overline{RESET} . The state of the **EROMCTL** pin (**PE3**) is latched into the EROMON bit in the MISC register on the rising edge of the \overline{RESET} .

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4.5.3 Oscillator Configuration

The configuration of the Oscillator can be selected using the $\overline{\textbf{XCLKS}}$ pin. (see **Table 4-2**) For a detailed description please refer to the CRG Block Guide.

Table 4-2 Clock Selection Based on PE7

PE7 = XCLKS	Description
0	Full swing pierce oscillator or external clock source selected
1	Loop controlled pierce oscillator selected

4.5.4 Voltage Regulator Control

The logic level on the voltage regulator enable pin **VREGEN** determines whether the on chip voltage regulator is enabled or disabled. (see **Table 4-3**)

Table 4-3 Voltage Regulator VREGEN

VREGEN	Description		
1	Internal Voltage Regulator enabled		
0	Internal Voltage Regulator disabled, VDD1,2 and VDDPLL must be supplied externally		

4.6 Security

The MCU security feature allows the protection of the on chip Flash and EEPROM memory. For a detailed description of the security features refer to the S12X9SEC Block Guide.

Section 5 Resets and Interrupts

5.1 Overview

Consult the S12XCPU Block Guide for information on Exception Processing.

5.2 Vectors

5.2.1 Vector Table

Table 5-1 lists all interrupt sources and vectors in the default order of priority. The Interrupt module (S12XINT) provides an Interrupt Vector Base Register (IVBR) to relocate the vectors. Associated with each I-bit maskable service request is a configuration register. It selects if the service request is enabled, the service request priority level and whether the service request is handled either by the S12X CPU or by the XGATE module.

The HPRIO register and functionality is no longer supported on the S12X devices. This functionality is superseded by a 7 level service request priority scheme. Please refer to the S12XINT Block Guide for detailed information.

Table 5-1 Interrupt Vector Locations

Vector Address ¹	XGATE Channel ID ²	Interrupt Source	CCR Mask	Local Enable
\$FFFE,	-	System Reset	None	None
\$FFFC	-	Clock Monitor Reset	None	PLLCTL (CME, SCME)
\$FFFA	-	COP Watchdog Reset	None	COP rate select
Vector Base + \$F8	-	Unimplemented instruction trap	None	None
Vector Base+ \$F6	-	SWI	None	None
Vector Base+ \$F4	-	XIRQ	X-Bit	None
Vector Base+ \$F2	-	IRQ	I-Bit	IRQCR (IRQEN)
Vector Base+ \$F0	\$78	Real Time Interrupt	I-Bit	CRGINT (RTIE)
Vector Base+ \$EE	\$77	Enhanced Capture Timer channel 0	I-Bit	TIE (COI)
Vector Base + \$EC	\$76	Enhanced Capture Timer channel 1	I-Bit	TIE (C1I)
Vector Base+ \$EA	\$75	Enhanced Capture Timer channel 2	I-Bit	TIE (C2I)
Vector Base+ \$E8	\$74	Enhanced Capture Timer channel 3	I-Bit	TIE (C3I)
Vector Base+ \$E6	\$73	Enhanced Capture Timer channel 4	I-Bit	TIE (C4I)
Vector Base+ \$E4	\$72	Enhanced Capture Timer channel 5	I-Bit	TIE (C5I)
Vector Base + \$E2	\$71	Enhanced Capture Timer channel 6	I-Bit	TIE (C6I)
Vector Base+ \$E0	\$70	Enhanced Capture Timer channel 7	I-Bit	TIE (C7I)
Vector Base+ \$DE	\$6F	Enhanced Capture Timer overflow	I-Bit	TSRC2 (TOF)
Vector Base+ \$DC	\$6E	Pulse accumulator A overflow	I-Bit	PACTL (PAOVI)

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Vector Base + \$DA	\$6D	Pulse accumulator input edge	I-Bit	PACTL (PAI)
Vector Base + \$D8	\$6C	SPI0		SPI0CR1 (SPIE, SPTIE)
Vector Base+ \$D6	\$6B	SCI0	I-Bit	SCI0CR2 (TIE, TCIE, RIE, ILIE)
Vector Base + \$D4	\$6A	SCI1	I-Bit	SCI1CR2 (TIE, TCIE, RIE, ILIE)
Vector Base + \$D2	\$69	ATD0	I-Bit	ATD0CTL2 (ASCIE)
Vector Base + \$D0	\$68	ATD1	I-Bit	ATD1CTL2 (ASCIE)
Vector Base + \$CE	\$67	Port J	I-Bit	PIEJ (PIEJ7-PIEJ0)
Vector Base + \$CC	\$66	Port H	I-Bit	PIEH (PIEH7-PIEH0)
Vector Base + \$CA	\$65	Modulus Down Counter underflow	I-Bit	MCCTL(MCZI)
Vector Base + \$C8	\$64	Pulse Accumulator B Overflow	I-Bit	PBCTL(PBOVI)
Vector Base + \$C6	\$63	CRG PLL lock	I-Bit	CRGINT(LOCKIE)
Vector Base + \$C4	\$62	CRG Self Clock Mode	I-Bit	CRGINT (SCMIE)
Vector Base + \$C2	\$61	Rese	ved	
Vector Base + \$C0	\$60	IIC0 Bus	I-Bit	IBCR0 (IBIE)
Vector Base + \$BE	\$5F	SPI1	I-Bit	SPI1CR1 (SPIE, SPTIE)
Vector Base + \$BC	\$5E	SPI2	I-Bit	SPI2CR1 (SPIE, SPTIE)
Vector Base + \$BA	\$5D	EEPROM	I-Bit	ECNFG (CCIE, CBEIE)
Vector Base + \$B8	\$5C	FLASH	I-Bit	FCNFG (CCIE, CBEIE)
Vector Base + \$B6	\$5B	CAN0 wake-up	I-Bit	CANORIER (WUPIE)
Vector Base + \$B4	\$5A	CAN0 errors	I-Bit	CANORIER (CSCIE, OVRIE)
Vector Base + \$B2	\$59	CAN0 receive	I-Bit	CANORIER (RXFIE)
Vector Base + \$B0	\$58	CAN0 transmit	I-Bit	CANOTIER (TXEIE2-TXEIE0)
Vector Base + \$AE	\$57	CAN1 wake-up	I-Bit	CAN1RIER (WUPIE)
Vector Base + \$AC	\$56	CAN1 errors	I-Bit	CAN1RIER (CSCIE, OVRIE)
Vector Base + \$AA	\$55	CAN1 receive	I-Bit	CAN1RIER (RXFIE)
Vector Base + \$A8	\$54	CAN1 transmit	I-Bit	CAN1TIER (TXEIE2-TXEIE0)
Vector Base + \$A6	\$53	CAN2 wake-up	I-Bit	CAN2RIER (WUPIE)
Vector Base + \$A4	\$52	CAN2 errors	I-Bit	CAN2RIER (CSCIE, OVRIE)
Vector Base + \$A2	\$51	CAN2 receive	I-Bit	CAN2RIER (RXFIE)
Vector Base + \$A0	\$50	CAN2 transmit	I-Bit	CAN2TIER (TXEIE2-TXEIE0)
Vector Base + \$9E	\$4F	CAN3 wake-up	I-Bit	CAN3RIER (WUPIE)
Vector Base+ \$9C	\$4E	CAN3 errors	I-Bit	CAN3RIER (CSCIE, OVRIE)
Vector Base+ \$9A	\$4D	CAN3 receive	I-Bit	CAN3RIER (RXFIE)
Vector Base + \$98	\$4C	CAN3 transmit	I-Bit	CAN3TIER (TXEIE2-TXEIE0)
Vector Base + \$96	\$4B	CAN4 wake-up	I-Bit	CAN4RIER (WUPIE)
Vector Base + \$94	\$4A	CAN4 errors	I-Bit	CAN4RIER (CSCIE, OVRIE)



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Vector Base + \$92	\$49	CAN4 receive	I-Bit	CAN4RIER (RXFIE)	
Vector Base + \$90	\$48	CAN4 transmit		CAN4TIER (TXEIE2-TXEIE0)	
Vector Base + \$8E	\$47	Port P Interrupt		PIEP (PIEP7-PIEP0)	
Vector Base+ \$8C	\$46	PWM Emergency Shutdown		PWMSDN (PWMIE)	
Vector Base + \$8A	\$45	SCI2	I-Bit	SCI2CR2 (TIE, TCIE, RIE, ILIE)	
Vector Base + \$88	\$44	SCI3	I-Bit	SCI3CR2 (TIE, TCIE, RIE, ILIE)	
Vector Base + \$86	\$43	SCI4	I-Bit	SCI4CR2 (TIE, TCIE, RIE, ILIE)	
Vector Base + \$84	\$42	SCI5	I-Bit	SCI5CR2 (TIE, TCIE, RIE, ILIE)	
Vector Base + \$82	\$41	IIC1 Bus	I-Bit	IBCR (IBIE)	
Vector Base + \$80	\$40	Low Voltage interrupt LVI	I-Bit	VREGCTRL (LVIE)	
Vector Base + \$7E	\$3F	Autonomous Periodical interrupt API	I-Bit	VREGAPICTRL (APIE)	
Vector Base + \$7C	\$3E	Reserved			
Vector Base + \$7A	\$3D	Periodic Interrupt Timer	I-Bit	PITINTE (PINTE0)	
Vector Base + \$78	\$3C	Periodic Interrupt Timer	I-Bit	PITINTE (PINTE1)	
Vector Base + \$76	\$3B	Periodic Interrupt Timer	I-Bit	PITINTE (PINTE2)	
Vector Base + \$74	\$3A	Periodic Interrupt Timer	I-Bit	PITINTE (PINTE3)	
Vector Base + \$72	\$39	XGATE Software Trigger 0	I-Bit	XGMCTL (XGIE)	
Vector Base + \$70	\$38	XGATE Software Trigger 1	I-Bit	XGMCTL (XGIE)	
Vector Base + \$6E	\$37	XGATE Software Trigger 2	I-Bit	XGMCTL (XGIE)	
Vector Base + \$6C	\$36	XGATE Software Trigger 3	I-Bit	XGMCTL (XGIE)	
Vector Base + \$6A	\$35	XGATE Software Trigger 4	I-Bit	XGMCTL (XGIE)	
Vector Base + \$68	\$34	XGATE Software Trigger 5	I-Bit	XGMCTL (XGIE)	
Vector Base + \$66	\$33	XGATE Software Trigger 6	I-Bit	XGMCTL (XGIE)	
Vector Base + \$64	\$32	XGATE Software Trigger 7	I-Bit	XGMCTL (XGIE)	
Vector Base + \$62	-	XGATE Software Error Interrupt	I-Bit	XGMCTL (XGIE)	
Vector Base + \$60	-	SRAM32K Access Violation	I-Bit	RAMWPC (AVIE)	
Vector Base+ \$12 to Vector Base + \$5E		Reserved	•		
Vector Base + \$10	-	Spurious Interrupt	-	None	

NOTES:

- 1. 16 bits Vector Address based
- 2. For detailed description of XGATE Channel ID refer to XGATE Block Guide

5.3 Effects of Reset

When a reset occurs, MCU registers and control bits are changed to known start-up states. Refer to the respective module Block Guides for register reset states.

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5.3.1 I/O pins

Refer to the PIM Block Guide for reset configurations of all peripheral module ports.

5.3.2 Memory

The RAM array is not initialized out of reset.

Section 6 S12X_CPU Block Description

Consult the S12X_CPU Block Guide for information about the S12XCPU module.

Section 7 S12X_MMC Block Description

Consult the S12X MMC Block Guide for information about the S12XMMC module.

Section 8 S12_XEBI Block Description

Consult the S12X_EBI Block Guide for information about the S12XEBI module.

Section 9 S12_XINT Block Description

Consult the S12X_INT Block Guide for information about the S12XINT module.

Section 10 S12X_DBG Block Description

Consult the S12X_DBG Block Guide for information about the S12XDBG module.

Section 11 S12X_BDM Block Description

Consult the S12X BDM Block Guide for information about the S12XBDM module.

Section 12 XGATE Block Description

Consult the XGATE Block Guide for information about the co-processor.

Section 13 Periodic Interrupt Timer (PIT) Block Description

The Periodic Interrupt Timer Module contains four hardware trigger signal lines PITTRIG0, PITTRIG1, PITTRIG2 and PITTRIG3. One for each timer channel. **Table 17-1** and **Table 18-1** show the connection of these trigger outputs on MC9S12XDP512 device. The trigger signal lines PITTRIG2 and PITTRIG3 are not used on MC9S12XDP512. Consult the PIT Block Guide for information about the Periodic Interrupt Timer module. When the PIT Block Guide refers to freeze mode this is equivalent to active BDM mode.

Section 14 Oscillator (OSC_LCP) Block

Consult the OSC LCP Block Guide for information about the Oscillator Module.

Section 15 Clock and Reset Generator (CRG) Block Description

The COP timeout rate bits CR[2:0] and the WCOP bit in the COPCTL register are loaded on rising edge of **RESET** from the Flash Control Register FCTL (\$0107) located in the Flash EEPROM block. See **Table 15-1** and **Table 15-2** for coding.

The FCTL register is loaded from the Flash Configuration Field byte at global address \$7F_FF0E during the reset sequence. For more information on FCTL register refer to the FTX512K4 Block Guide.

Table 15-1 Initial COP Rate Configuration

NV[2:0] in FCTL Register	CR[2:0] in COPCTL Register
000	111
001	110
010	101
011	100
100	011
101	010
110	001
111	000

Table 15-2 Initial WCOP Configuration

NV[3] in FCTL Register	WCOP in COPCTL Register
1	0
0	1

Consult the CRG Block Guide for information about the Clock and Reset Generator module.

Section 16 Enhanced Capture Timer (ECT) Block Description

Consult the ECT_16B8C Block Guide for information about the Enhanced Capture Timer module. When the ECT_16B8C Block Guide refers to freeze mode this is equivalent to active BDM mode.

Section 17 10 Bit 8 channel Analog to Digital Converter (ATD0) Block Description

The ATD_10B8C module includes four external trigger inputs ETRIG0, ETRIG1, ETRIG and ETRIG3. The external trigger allows the user to synchronize ATD conversion to external trigger events. **Table 17-1** shows the connection of the external trigger inputs on MC9S12XDP512.

Table 17-1 ATD0 External Trigger Sources

External Trigger Input	Connectivity
ETRIG0	Pulse Width Modulator Channel 1
ETRIG1	Pulse Width Modulator Channel 3
ETRIG2	Periodic Interrupt Timer Hardware Trigger 0
ETRIG3	Periodic Interrupt Timer Hardware Trigger 1

Consult the ATD_10B8C Block Guide for information about the Analog to Digital Converter module. When the ATD_10B8C Block Guide refers to freeze mode this is equivalent to active BDM mode.

Section 18 10 Bit 16 Channel Analog to Digital Converter (ATD1) Block Description

The ATD_10B16C module includes four external trigger inputs ETRIG0, ETRIG1, ETRIG and ETRIG3. The external trigger feature allows the user to synchronize ATD conversion to external trigger events. **Table 18-1** shows the connection of the external trigger inputs on MC9S12XDP512.

Table 18-1 ATD1 External Trigger Sources

External Trigger Input	Connectivity
ETRIG0	Pulse Width Modulator Channel 1
ETRIG1	Pulse Width Modulator Channel 3
ETRIG2	Periodic Interrupt Timer Hardware Trigger 0
ETRIG3	Periodic Interrupt Timer Hardware Trigger 1

Consult the ATD_10B16C Block Guide for information about the Analog to Digital Converter module. When the ATD_10B16C Block Guide refers to freeze mode this is equivalent to active BDM mode.

Section 19 Inter-IC Bus (IIC) Block Description

There are two Inter-IC Bus blocks implemented (IIC0, IIC1) on the MC9S12XDP512 device. Consult the IIC Block Guide for information about each Inter-IC Bus module.

Section 20 Serial Communications Interface (SCI) Block Description

There are six Serial Communications Interfaces (SCI0, SCI1, SCI2, SCI3, SCI4 and SCI5) implemented on the MC9S12XDP512 device. Consult the SCI Block Guide for information about each Serial Communications Interface module.

Section 21 Serial Peripheral Interface (SPI) Block Description

There are three Serial Peripheral Interfaces(SPI0, SPI1 and SPI2) implemented on MC9S12XDP512. Consult the SPI Block Guide for information about each Serial Peripheral Interface module.

Section 22 Pulse Width Modulator (PWM) Block Description

Consult the PWM_8B8C Block Guide for information about the Pulse Width Modulator module. When the PWM_8B8CBlock Guide refers to freeze mode this is equivalent to active BDM mode.

Section 23 Flash EEPROM 512K Block Description

(M) MOTOROLA

Consult the FTX512K4 Block Guide for information about the flash module.

The "S12 LRAE" is a generic Load RAM and Execute (LRAE) program which will be programmed into the flash memory of this device during manufacture. This LRAE program will provide greater programming flexibility to the end users by allowing the device to be programmed directly using CAN or SCI after it is assembled on the PCB. Use of the LRAE program is at the discretion of the end user and, if not required, it must simply be erased prior to flash programming. For more details of the S12 LRAE and its implementation, please see the S12 LREA Application Note (AN2546/D).

Section 24 EEPROM 4K Block Description

Consult the EETX4K Block Guide for information about the EEPROM module.

Section 25 MSCAN Block Description

There are five MSCAN modules (CAN4, CAN3, CAN2, CAN1 and CAN0) implemented on the MC9S12XDP512. Consult the MSCAN Block Guide for information about the Motorola Scalable CAN Module.

Section 26 Port Integration Module (PIM) Block Description

Consult the PIM_9XD Family Block Guide for information about the Port Integration Module.

Section 27 Voltage Regulator (VREG_3V3) Block Description

Consult the VREG3V3 Block Guide for information about the dual output linear voltage regulator.

- VREGEN is accessible externally
- The API Trimming bits APITR[5:0] need to be set by the customer if accurate period is wanted.

27.1 Recommended PCB Layout

The PCB must be carefully laid out to ensure proper operation of the voltage regulator as well as of the MCU itself. The following rules must be observed:

- Every supply pair must be decoupled by a ceramic capacitor connected as near as possible to the corresponding pins (C1 C6).
- Central point of the ground star for LQFP112/QFP80 should be the VSSR pin.
- Central point of the ground star for LQFP144 should be the VSSA pin.
- Use low ohmic low inductance connections between VSS1, VSS2 and VSSR.
- VSSPLL must be directly connected to VSSR.
- Keep traces of VSSPLL, EXTAL and XTAL as short as possible and occupied board area for C7, C8 and Q1 as small as possible.
- Do not place other signals or supplies underneath area occupied by C7, C8 and Q1 and the connection area to the MCU.
- Central power input should be fed in at the VDDA/VSSA pins.

Table 27-1 Recommended decoupling capacitor choice

Component	Purpose	Туре	Value	
C1	VDD1 filter cap	ceramic X7R	220nF	
C2	VDD2 filter cap (not 80 QFP)	ceramic X7R 220nF		
C3	VDDA filter cap	ceramic X7R	>=100nF	
C4	VDDR filter cap	X7R/tantalum	>=100nF	
C5	VDDPLL filter cap	ceramic X7R	200nF	
C6	VDDX filter cap	X7R/tantalum	>=100nF	
C7	OSC load cap	comes from crus	stal manufacturer	
C8	OSC load cap	comes nom crys	stal manulacturei	
C9	PLL loop filter cap	Soc PLL specie	fication chapter	
C10	PLL loop filter cap	See FLL Speci	ilication chapter	
C11	VDDX filter cap	X7R/tantalum	>=100nF	
C12	VDDX filter cap	X7R/tantalum >=100nF		
R1	PLL loop filter res	See PLL specification chapter		
Q1	Quartz			

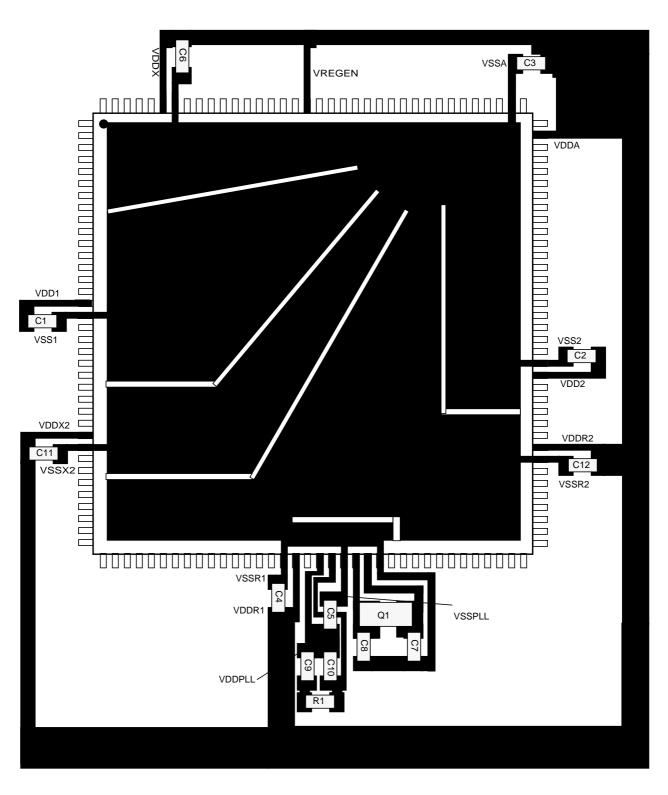
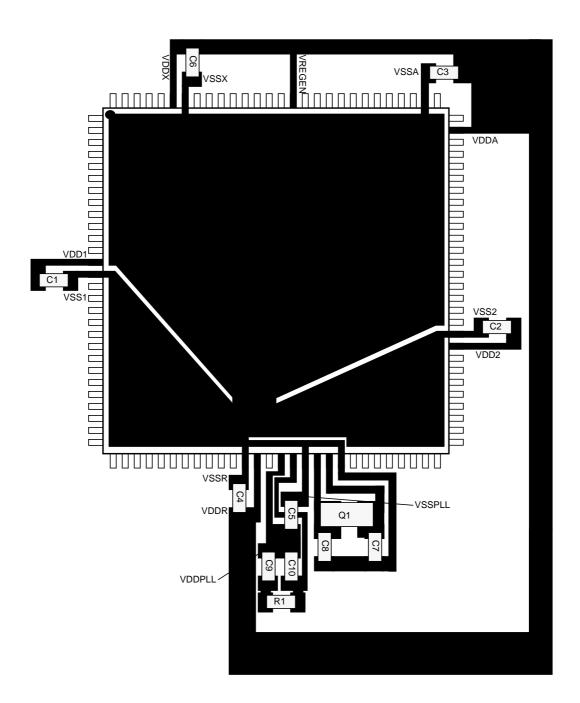


Figure 27-1 LQFP144 recommended PCB layout

Figure 27-2 LQFP112 recommended PCB layout



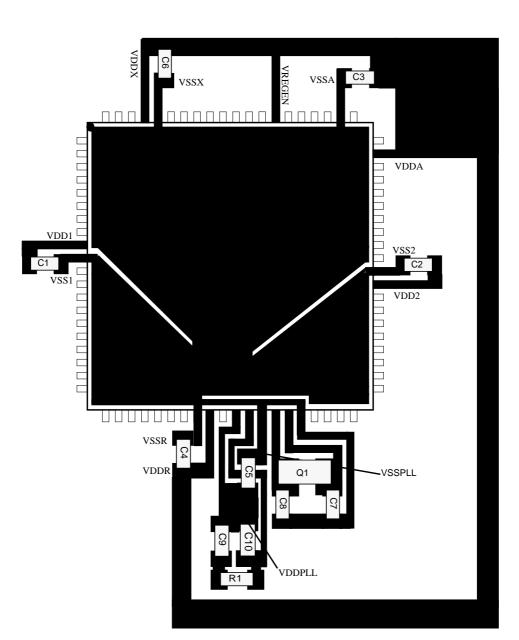


Figure 27-3 QFP80 recommended PCB layout

Appendix A Electrical Characteristics

A.1 General

NOTE:

The electrical characteristics given in this section are preliminary and should be used as a guide only. Values cannot be guaranteed by Motorola and are subject to change without notice.

This supplement contains the most accurate electrical information for the MC9S12XDP512 microcontroller available at the time of publication. The information should be considered **PRELIMINARY** and is subject to change.

This introduction is intended to give an overview on several common topics like power supply, current injection etc.

A.1.1 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate.

NOTE: This classification is shown in the column labeled "C" in the parameter tables where appropriate.

P:

Those parameters are guaranteed during production testing on each individual device.

C:

Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.

T:

Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.

D:

Those parameters are derived mainly from simulations.

A.1.2 Power Supply

The MC9S12XDP512 utilizes several pins to supply power to the I/O ports, A/D converter, oscillator and PLL as well as the digital core.

The VDDA, VSSA pair supplies the A/D converter and parts of the internal voltage regulator.

The VDDX, VSSX, VDDR and VSSR pairs supply the I/O pins, VDDR supplies also the internal voltage regulator.

VDD1, VSS1, VDD2 and VSS2 are the supply pins for the digital logic, VDDPLL, VSSPLL supply the oscillator and the PLL.

VSS1 and VSS2 are internally connected by metal.

VDDA, VDDX, VDDR as well as VSSA, VSSX, VSSR are connected by anti-parallel diodes for ESD protection.

NOTE:

In the following context VDD35 is used for either VDDA, VDDR and VDDX; VSS35

is used for either VSSA, VSSR and VSSX unless otherwise noted. IDD35 denotes the sum of the currents flowing into the VDDA, VDDX and VDDR

pins.

VDD is used for VDD1, VDD2 and VDDPLL, VSS is used for VSS1, VSS2 and

VSSPLL.

IDD is used for the sum of the currents flowing into VDD1 and VDD2.

A.1.3 Pins

There are four groups of functional pins.

A.1.3.1 I/O pins

Those I/O pins have a nominal level in the range of 3.0V to 5.5V. This class of pins is comprised of all port I/O pins, the analog inputs, BKGD and the RESET pins. The internal structure of all those pins is identical, however some of the functionality may be disabled. E.g. for the analog inputs the output drivers, pull-up and pull-down resistors are disabled permanently.

A.1.3.2 Analog Reference

This group is made up by the VRH and VRL pins.

A.1.3.3 Oscillator

The pins XFC, EXTAL, XTAL dedicated to the oscillator have a nominal 2.5V level. They are supplied by VDDPLL.

A.1.3.4 TEST

This pin is used for production testing only.

A.1.3.5 VREGEN

This pin is used to enable the on chip voltage regulator.

A.1.4 Current Injection

Power supply must maintain regulation within operating V_{DD35} or V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{in} > V_{DD35}$) is greater than I_{DD35} , the injection current may flow out of VDD35 and could result in external power supply going out of regulation. Ensure external VDD35 load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power; e.g. if no system clock is present, or if clock rate is very low which would reduce overall power consumption.

A.1.5 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only. A functional operation under or outside those maxima is not guaranteed. Stress beyond those limits may affect the reliability or cause permanent damage of the device.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either V_{SS35} or V_{DD35}).

Table A-1 Absolute Maximum Ratings¹

Num	Rating	Symbol	Min	Max	Unit
1	I/O, Regulator and Analog Supply Voltage	V _{DD35}	-0.3	6.0	V
2	Digital Logic Supply Voltage ²	V _{DD}	-0.3	3.0	V
3	PLL Supply Voltage (2)	V _{DDPLL}	-0.3	3.0	V
4	Voltage difference VDDX to VDDR and VDDA	Δ_{VDDX}	-0.3	0.3	V
5	Voltage difference VSSX to VSSR and VSSA	Δ_{VSSX}	-0.3	0.3	V
6	Digital I/O Input Voltage	V _{IN}	-0.3	6.0	V
7	Analog Reference	V _{RH} , V _{RL}	-0.3	6.0	V
8	XFC, EXTAL, XTAL inputs	V _{ILV}	-0.3	3.0	V
9	TEST input	V _{TEST}	-0.3	10.0	V
10	Instantaneous Maximum Current Single pin limit for all digital I/O pins ³	I _D	-25	+25	mA
11	Instantaneous Maximum Current Single pin limit for XFC, EXTAL, XTAL ⁴	I _{DL}	-25	+25	mA
12	Instantaneous Maximum Current Single pin limit for TEST ⁵	I _{DT}	-0.25	0	mA
13	Storage Temperature Range	T _{stg}	– 65	155	°C

^{1.} Beyond absolute maximum ratings device might be damaged.



- 2. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when the device is powered from an external source.
- 3. All digital I/O pins are internally clamped to V_{SSX} and V_{DDX}, V_{SSR} and V_{DDR} or V_{SSA} and V_{DDA}.
- 4. Those pins are internally clamped to V_{SSPLL} and V_{DDPLL}.
 5. This pin is clamped low to V_{SSPLL}, but not clamped high. This pin must be tied low in applications.

A.1.6 ESD Protection and Latch-up Immunity

All ESD testing is in conformity with CDF-AEC-Q100 Stress test qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM), the Machine Model (MM) and the Charge Device Model.

A device will be defined as a failure if after exposure to ESD pulses the device no longer meets the device specification. Complete DC parametric and functional testing is performed per the applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Table A-2 ESD and Latch-up Test Conditions

Model	Description	Symbol	Value	Unit
	Series Resistance	R1	1500	Ohm
l <u>-</u> .	Storage Capacitance	С	100	pF
Human Body	Number of Pulse per pin positive negative	-	- 3 3	
	Series Resistance	R1	0	Ohm
	Storage Capacitance	С	200	pF
Machine	Number of Pulse per pin positive negative	-	- 3 3	
Latch up	Minimum input voltage limit		-2.5	V
Latch-up	Maximum input voltage limit		7.5	V

Table A-3 ESD and Latch-Up Protection Characteristics

Num	С	Rating	Symbol	Min	Max	Unit
1	С	Human Body Model (HBM)	V _{HBM}	2000	-	V
2	С	Machine Model (MM)	V _{MM}	200	-	V
3	С	Charge Device Model (CDM)	V _{CDM}	500	-	V
4	С	Latch-up Current at T _A = 125°C positive negative	I _{LAT}	+100 -100	-	mA
5	С	Latch-up Current at T _A = 27°C positive negative	I _{LAT}	+200 -200	-	mA

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A.1.7 Operating Conditions

This chapter describes the operating conditions of the device. Unless otherwise noted those conditions apply to all the following data.

NOTE: Please refer to the temperature rating of the device (C, V, M) with regards to the ambient temperature T_A and the junction temperature T_J . For power dissipation calculations refer to **Section A.1.8 Power Dissipation and Thermal** Characteristics.

Table A-4 Operating Conditions

Rating	Symbol	Min	Тур	Max	Unit
I/O, Regulator and Analog Supply Voltage	V _{DD35}	3	5	5.5	V
Digital Logic Supply Voltage ¹	V_{DD}	2.35	2.5	2.75	V
PLL Supply Voltage (2)	V _{DDPLL}	2.35	2.5	2.75	V
Voltage Difference VDDX to VDDR and VDDA	Δ_{VDDX}	-0.1	0	0.1	V
Voltage Difference VSSX to VSSR and VSSA	Δ_{VSSX}	-0.1	0	0.1	V
Oscillator	f _{osc}	0.5	-	16	MHz
Bus Frequency	f _{bus}	0.5	-	40	MHz
MC9S12XDP512 C					
Operating Junction Temperature Range	T_J	-40	-	100	°C
Operating Ambient Temperature Range ²	T _A	-40	27	85	°C
MC9S12XDP512 V					
Operating Junction Temperature Range	T_J	-40	-	120	°C
Operating Ambient Temperature Range (2)	T _A	-40	27	105	°C
MC9S12XDP512 M					
Operating Junction Temperature Range	T_J	-40	-	140	°C
Operating Ambient Temperature Range (2)	T _A	-40	27	125	°C

NOTES:

A.1.8 Power Dissipation and Thermal Characteristics

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in ${}^{\circ}C$ can be obtained from:



The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The
absolute maximum ratings apply when this regulator is disabled and the device is powered from an external
source.

^{2.} Please refer to **Section A.1.8 Power Dissipation and Thermal Characteristics** for more details about the relation between ambient temperature T_A and device junction temperature T_J .

$$T_J = T_A + (P_D \bullet \Theta_{JA})$$

T_I = Junction Temperature, [°C]

 T_{Δ} = Ambient Temperature, [°C]

P_D = Total Chip Power Dissipation, [W]

 Θ_{IA} = Package Thermal Resistance, [°C/W]

The total power dissipation can be calculated from:

$$P_D = P_{INT} + P_{IO}$$

P_{INT} = Chip Internal Power Dissipation, [W]

Two cases with internal voltage regulator enabled and disabled must be considered:

1. Internal Voltage Regulator disabled

$$P_{INT} = I_{DD} \cdot V_{DD} + I_{DDPLL} \cdot V_{DDPLL} + I_{DDA} \cdot V_{DDA}$$

$$P_{IO} = \sum_{i} R_{DSON} \cdot I_{IO_{i}}^{2}$$

P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

For R_{DSON} is valid:

$$R_{DSON} = \frac{V_{OL}}{I_{OL}}$$
; for outputs driven low

respectively

$$R_{DSON} = \frac{V_{DD5} - V_{OH}}{I_{OH}}$$
; for outputs driven high

2. Internal voltage regulator enabled

$$P_{INT} = I_{DDR} \cdot V_{DDR} + I_{DDA} \cdot V_{DDA}$$

I_{DDR} is the current shown in **Table A-9** and not the overall current flowing into VDDR, which additionally contains the current flowing into the external loads with output high.

$$P_{IO} = \sum_{i} R_{DSON} \cdot I_{IO_i}^2$$

 P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

Table A-5 Thermal Package Characteristics¹

Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Т	Thermal Resistance LQFP144, single sided PCB ²	θ_{JA}	-	-	45	°C/W
2	Т	Thermal Resistance LQFP144, double sided PCB with 2 internal planes ³	θ_{JA}	-	-	35	°C/W
3	Т	Thermal Resistance LQFP112, single sided PCB ²	θ_{JA}	-	-	46	°C/W
4	Т	Thermal Resistance LQFP112, double sided PCB with 2 internal planes ³	θ_{JA}	-	-	36	°C/W
5	Т	Thermal Resistance QFP 80, single sided PCB ²	θ_{JA}	-	-	50	°C/W
6	Т	Thermal Resistance QFP 80, double sided PCB with 2 internal planes ³	θ_{JA}	-	-	38	°C/W

- 1. The values for thermal resistance are achieved by package simulations
- 2. PC Board according to EIA/JEDEC Standard 51-2
- 3. PC Board according to EIA/JEDEC Standard 51-7

A.1.9 I/O Characteristics

This section describes the characteristics of all I/O pins.

Table A-6 3.3V I/O Characteristics

Num	ပ	Rating	Symbol	Min	Тур	Max	Unit
1	Р	Input High Voltage	V _{IH}	0.65*V _{DD35}	-	-	V
	Т	Input High Voltage	V _{IH}	-	-	V _{DD35} + 0.3	V
2	Р	Input Low Voltage	V _{IL}	-	-	0.35*V _{DD35}	V
	Т	Input Low Voltage	V _{IL}	V _{SS35} - 0.3	-	-	V
3	С	Input Hysteresis	V _{HYS}		250		mV
4	Р	Input Leakage Current (pins in high impedance input mode) ¹ $V_{in} = V_{DD35}$ or V_{SS35}	I _{in}	-1	-	1	μΑ
5	С	Output High Voltage (pins in output mode) Partial Drive I _{OH} = -2mA	V _{OH}	V _{DD35} – 0.4	-	-	V
6	Р	Output High Voltage (pins in output mode) Full Drive IOH = -5.5mA	V _{OH}	V _{DD35} – 0.4	-	-	V
7	С	Output Low Voltage (pins in output mode) Partial Drive IOL = +2mA	V _{OL}	-	-	0.4	V
8	Р	Output Low Voltage (pins in output mode) Full Drive I _{OL} = +5.5mA	V _{OL}	-	-	0.4	V
9	Р	Internal Pull Up Device Current, tested at V _{IL} Max.	I _{PUL}	-	-	-60	μΑ
10	С	Internal Pull Up Device Current, tested at V _{IH} Min.	I _{PUH}	-6	-	-	μΑ
11	Р	Internal Pull Down Device Current, tested at V _{IH} Min.	I _{PDH}	-	-	60	μΑ
12	С	Internal Pull Down Device Current, tested at V _{IL} Max.	I _{PDL}	6	-	-	μΑ
13	D	Input Capacitance	C _{in}		6	-	pF
14	Т	Injection current ² Single Pin limit Total Device Limit. Sum of all injected currents	I _{ICS}	-2.5 -25	-	2.5 25	mA
15	Р	Port H, J, P Interrupt Input Pulse filtered ³	t _{PULSE}			3	μs
16	Р	Port H, J, P Interrupt Input Pulse passed ⁽³⁾	t _{PULSE}	10			μs

- 1. Maximum leakage current occurs at maximum operating temperature. Current decreases by approximately one-half for each 8 C to 12 C in the temperature range from 50 C to 125 C.
- 2. Refer to Section A.1.4 Current Injection, for more details
- 3. Parameter only applies in STOP or Pseudo STOP mode.



Freescale Semiconductor Properties User Guide — V02.05

Table A-7 5V I/O Characteristics

Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Р	Input High Voltage	V _{IH}	0.65*V _{DD35}	-	-	V
	Т	Input High Voltage	V _{IH}	-	-	V _{DD35} + 0.3	V
2	Р	Input Low Voltage	V _{IL}	-	-	0.35*V _{DD35}	V
	Т	Input Low Voltage	V _{IL}	V _{SS35} - 0.3	-	-	V
3	С	Input Hysteresis	V _{HYS}		250		mV
4	Р	Input Leakage Current (pins in high impedance input mode) ¹ $V_{in} = V_{DD35}$ or V_{SS35}	I _{in}	-1	-	1	μΑ
5	С	Output High Voltage (pins in output mode) Partial Drive I _{OH} = -2mA	V _{OH}	V _{DD35} – 0.8	-	-	V
6	Р	Output High Voltage (pins in output mode) Full Drive IOH = -10mA	V _{OH}	V _{DD35} – 0.8	-	-	V
7	С	Output Low Voltage (pins in output mode) Partial Drive IOL = +2mA	V _{OL}	-	-	0.8	V
8	Р	Output Low Voltage (pins in output mode) Full Drive I _{OL} = +10mA	V _{OL}	-	-	0.8	V
9	Р	Internal Pull Up Device Current, tested at V _{IL} Max.	I _{PUL}	-	-	-130	μΑ
10	С	Internal Pull Up Device Current, tested at V _{IH} Min.	I _{PUH}	-10	-	-	μА
11	Р	Internal Pull Down Device Current, tested at V _{IH} Min.	I _{PDH}	-	-	130	μА
12	С	Internal Pull Down Device Current, tested at V _{IL} Max.	I _{PDL}	10	-	-	μΑ
13	D	Input Capacitance	C _{in}		6	-	pF
14	Т	Injection current ² Single Pin limit Total Device Limit. Sum of all injected currents	I _{ICS}	-2.5 -25	-	2.5 25	mA
15	Р	Port H, J, P Interrupt Input Pulse filtered ³	t _{PULSE}			3	μs
16	Р	Port H, J, P Interrupt Input Pulse passed ⁽³⁾	t _{PULSE}	10			μs

- 1. Maximum leakage current occurs at maximum operating temperature. Current decreases by approximately one-half for each 8 C to 12 C in the temperature range from 50 C to 125 C.
- 2. Refer to Section A.1.4 Current Injection, for more details
- 3. Parameter only applies in STOP or Pseudo STOP mode.



Table A-8 I/O Characteristics for Port C, D, PE5, PE6 and PK7 for reduced input voltage thresholds

	Conditions are 4.5V < VDD35 <5.5V Temperature from -40C to +140C,unless otherwise noted											
Num	С	Rating	Symbol	Min	Тур	Max	Unit					
1	Р	Input High Voltage	V _{IH}	TBD	-	-	V					
	Т	Input High Voltage	V _{IH}	-	-	TBD	V					
2	Р	Input Low Voltage	V _{IL}	TBD	-	-	V					
	Т	Input Low Voltage	V _{IL}	-	-	TBD	V					
3	С	Input Hysteresis	V _{HYS}		TBD		mV					

A.1.10 Supply Currents

This section describes the current consumption characteristics of the device as well as the conditions for the measurements.

A.1.10.1 Measurement Conditions

All measurements are without output loads. Unless otherwise noted the currents are measured in single chip mode, internal voltage regulator enabled and at 40MHz bus frequency using a 4MHz oscillator in loop controlled Pierce mode. Production testing is performed using a square wave signal at the EXTAL input.

A.1.10.2 Additional Remarks

In expanded modes the currents flowing in the system are highly dependent on the load at the address, data and control signals as well as on the duty cycle of those signals. No generally applicable numbers can

Freescale Semiconductor Properties User Guide — V02.05

given. A very good estimate is to take the single chip currents and add the currents due to the external loads.

Table A-9 Supply Current Characteristics

Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Р	Run supply currents Single Chip, Internal regulator enabled	I _{DD35}		.,,,,	TBD	mA
2	P P	Wait Supply current All modules enabled, PLL on only RTI enabled ⁽¹⁾	I _{DDW}			TBD TBD	mA
3	CPCCPCPCP	Pseudo Stop Current (API, RTI and COP disabled) 1, 2 -40°C 27°C 70°C 85°C "C" Temp Option 100°C 105°C "V" Temp Option 120°C 125°C "M" Temp Option 140°C	I _{DDPS}		TBD	TBD TBD TBD TBD	μА
4	0000000	Pseudo Stop Current (API, RTI and COP enabled) (1), (2) -40°C 27°C 70°C 85°C 105°C 125°C 140°C	I _{DDPS}		TBD TBD TBD TBD TBD TBD TBD		μА
5	CPCCPCP	Stop Current ⁽²⁾ -40°C 27°C 70°C 85°C "C" Temp Option 100°C 105°C "V" Temp Option 120°C 125°C "M" Temp Option 140°C	I _{DDS}		TBD	TBD TBD TBD TBD	μА

- 1. PLL off
- 2. At those low power dissipation levels $T_J = T_A$ can be assumed

A.2 ATD Characteristics

This section describes the characteristics of the analog to digital converter.

A.2.1 ATD Operating Characteristics

The **Table A-10** and **Table A-11** show conditions under which the ATD operates.

The following constraints exist to obtain full-scale, full range results:

 $V_{SSA} \le V_{RL} \le V_{IN} \le V_{RH} \le V_{DDA}$. This constraint exists since the sample buffer amplifier can not drive beyond the power supply levels that it ties to. If the input level goes outside of this range it will effectively be clipped.

Table A-10 ATD Operating Characteristics 5V

Condit	ions	s are shown in Table A-4 unless otherwise noted, Supp	oly Voltage 4.	5V < VDDA <	< 5.5V		
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	D	Reference Potential Low High	V _{RL} V _{RH}	V _{SSA} V _{DDA} /2		V _{DDA} /2 V _{DDA}	V
2	С	Differential Reference Voltage ¹	$V_{RH}-V_{RL}$	4.50	5.00	5.5	V
3	D	ATD Clock Frequency	f _{ATDCLK}	0.5		TBD	MHz
4	D	ATD 10-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f _{ATDCLK}		14 7		28 14	Cycles μs
5	D	ATD 8-Bit Conversion Period Clock Cycles ⁽²⁾ Conv, Time at 2.0MHz ATD Clock f _{ATDCLK}	N _{CONV8} T _{CONV8}	12 6		26 13	Cycles μs
6	D	Recovery Time (V _{DDA} =5.0 Volts)	t _{REC}			20	μs
7	Р	Reference Supply current 2 ATD blocks on	I _{REF}			0.750	mA
8	Р	Reference Supply current 1 ATD block on	I _{REF}			0.375	mA

- 1. Full accuracy is not guaranteed when differential voltage is less than 4.50V
- 2. The minimum time assumes a final sample period of 2 ATD clocks cycles while the maximum time assumes a final sample period of 16 ATD clocks.

Table A-11 ATD Operating Characteristics 3.3V

Condit	ions	s are shown in Table A-4 unless otherwise noted, Supp	bly Voltage 3.	3V < VDDA <	< 3.6V		
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	D	Reference Potential Low High	V _{RL} V _{RH}	V _{SSA} V _{DDA} /2		V _{DDA} /2 V _{DDA}	V
2	С	Differential Reference Voltage ¹	$V_{RH}-V_{RL}$	3.0	3.3	3.6	V
3	D	ATD Clock Frequency	f _{ATDCLK}	0.5		TBD	MHz
4	D	ATD 10-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f _{ATDCLK}		14 7		28 14	Cycles μs
5	D	ATD 8-Bit Conversion Period Clock Cycles ⁽²⁾ Conv, Time at 2.0MHz ATD Clock f _{ATDCLK}	N _{CONV8} T _{CONV8}	12 6		26 13	Cycles μs
6	D	Recovery Time (V _{DDA} =5.0 Volts)	t _{REC}			20	μs
7	Р	Reference Supply current 2 ATD blocks on	I _{REF}			0.500	mA
8	Р	Reference Supply current 1 ATD block on	I _{REF}			0.250	mA

NOTES:

- 1. Full accuracy is not guaranteed when differential voltage is less than 4.50V
- 2. The minimum time assumes a final sample period of 2 ATD clocks cycles while the maximum time assumes a final sample period of 16 ATD clocks.

A.2.2 Factors influencing accuracy

Three factors - source resistance, source capacitance and current injection - have an influence on the accuracy of the ATD.

A.2.2.1 Source Resistance:

Due to the input pin leakage current as specified in **Table A-7** in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S specifies results in an error of less than 1/2 LSB (2.5 mV) at the maximum leakage current. If device or operating conditions are less than worst case or leakage-induced error is acceptable, larger values of source resistance is allowed.

A.2.2.2 Source Capacitance

When sampling an additional internal capacitor is switched to the input. This can cause a voltage drop due to charge sharing with the external and the pin capacitance. For a maximum sampling error of the input voltage \leq 1LSB, then the external filter capacitor, $C_f \geq 1024 * (C_{INS} - C_{INN})$.

A.2.2.3 Current Injection

There are two cases to consider.

(M) MOTOROLA

Freescale Semiconductor Photoevice User Guide — V02.05

- 1. A current is injected into the channel being converted. The channel being stressed has conversion values of \$3FF (\$FF in 8-bit mode) for analog inputs greater than V_{RH} and \$000 for values less than V_{RI} unless the current is higher than specified as disruptive condition.
- 2. Current is injected into pins in the neighborhood of the channel being converted. A portion of this current is picked up by the channel (coupling ratio K), This additional current impacts the accuracy of the conversion depending on the source resistance.

The additional input voltage error on the converted channel can be calculated as $V_{ERR} = K * R_S * I_{INJ}$, with I_{INJ} being the sum of the currents injected into the two pins adjacent to the converted channel.

Table A-12 ATD Electrical Characteristics

Condit	Conditions are shown in Table A-4 unless otherwise noted									
Num	С	Rating	Symbol	Min	Тур	Max	Unit			
1	С	Max input Source Resistance	R _S	-	-	1	ΚΩ			
2	Т	Total Input Capacitance Non Sampling Sampling	C _{INN} C _{INS}			10 22	pF			
3	С	Disruptive Analog Input Current	I _{NA}	-2.5		2.5	mA			
4	С	Coupling Ratio positive current injection	K _p			TBD	A/A			
5	С	Coupling Ratio negative current injection	K _n			TBD	A/A			

A.2.3 ATD accuracy

A.2.3.1 5V Range

Table A-13 specifies the ATD conversion performance excluding any errors due to current injection, input capacitance and source resistance.

Table A-13 ATD Conversion Performance 5V

Conditions are shown in **Table A-4** unless otherwise noted $V_{REF} = V_{RH} - V_{RL} = 5.12V$. Resulting to one 8 bit count = 20mV and one 10 bit count = 5mV $f_{ATDCLK} = 2.0MHz$

	202.								
Num	С	Rating	Symbol	Min	Тур	Max	Unit		
1	Р	10-Bit Resolution	LSB		5		mV		
2	Р	10-Bit Differential Nonlinearity	DNL	-1		1	Counts		
3	Р	10-Bit Integral Nonlinearity	INL	-2.5	±1.5	2.5	Counts		
4	Р	10-Bit Absolute Error ¹	AE	-3	±2.0	3	Counts		
5	Р	8-Bit Resolution	LSB		20		mV		
6	Р	8-Bit Differential Nonlinearity	DNL	-0.5		0.5	Counts		
7	Р	8-Bit Integral Nonlinearity	INL	-1.0	±0.5	1.0	Counts		
8	Р	8-Bit Absolute Error ⁽¹⁾	AE	-1.5	±1.0	1.5	Counts		



NOTES:

1. These values include the quantization error which is inherently 1/2 count for any A/D converter.

A.2.3.2 3.3V Range

Table A-14 specifies the ATD conversion performance excluding any errors due to current injection, input capacitance and source resistance.

Table A-14 ATD Conversion Performance 3.3V

Conditions are shown in **Table A-4** unless otherwise noted

V_{REF} = V_{RH} - V_{RL} = 3.328V. Resulting to one 8 bit count = 13mV and one 10 bit count = 3.25mV

 $f_{ATDCIK} = 2.0MHz$

Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Р	10-Bit Resolution	LSB		3.25		mV
2	Р	10-Bit Differential Nonlinearity	DNL	-1.5		1.5	Counts
3	Р	10-Bit Integral Nonlinearity	INL	-3.5	±1.5	3.5	Counts
4	Р	10-Bit Absolute Error ¹	AE	-5	±2.5	5	Counts
5	Р	8-Bit Resolution	LSB		13		mV
6	Р	8-Bit Differential Nonlinearity	DNL	-0.5		0.5	Counts
7	Р	8-Bit Integral Nonlinearity	INL	-1.5	±1.0	1.5	Counts
8	Р	8-Bit Absolute Error ⁽¹⁾	AE	-2.0	±1.5	2.0	Counts

NOTES:

A.2.3.3 ATD Accuracy Definitions

For the following definitions see also **Figure A-1**.

Differential Non-Linearity (DNL) is defined as the difference between two adjacent switching steps.

$$DNL(i) = \frac{V_i - V_{i-1}}{1LSB} - 1$$

The Integral Non-Linearity (INL) is defined as the sum of all DNLs:

$$INL(n) = \sum_{i=1}^{n} DNL(i) = \frac{V_n - V_0}{1LSB} - n$$

^{1.} These values include the quantization error which is inherently 1/2 count for any A/D converter.

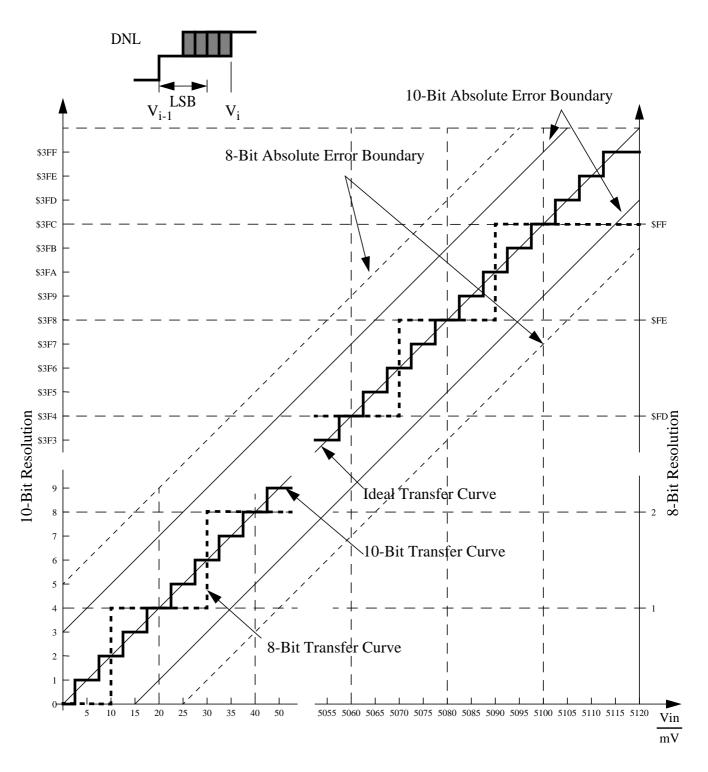


Figure A-1 ATD Accuracy Definitions

NOTE: Figure A-1 shows only definitions, for specification values refer to Table A-13.

A.3 NVM, Flash and EEPROM

NOTE: Unless otherwise noted the abbreviation NVM (Non Volatile Memory) is used for both Flash and EEPROM.

A.3.1 NVM timing

The time base for all NVM program or erase operations is derived from the oscillator. A minimum oscillator frequency f_{NVMOSC} is required for performing program or erase operations. The NVM modules do not have any means to monitor the frequency and will not prevent program or erase operation at frequencies above or below the specified minimum. Attempting to program or erase the NVM modules at a lower frequency a full program or erase transition is not assured.

The Flash and EEPROM program and erase operations are timed using a clock derived from the oscillator using the FCLKDIV and ECLKDIV registers respectively. The frequency of this clock must be set within the limits specified as f_{NVMOP}.

The minimum program and erase times shown in **Table A-15** are calculated for maximum f_{NVMOP} and maximum f_{bus} . The maximum times are calculated for minimum f_{NVMOP} and a f_{bus} of 2MHz.

A.3.1.1 Single Word Programming

The programming time for single word programming is dependant on the bus frequency as a well as on the frequency f_{NVMOP} and can be calculated according to the following formula.

$$t_{swpgm} = 9 \cdot \frac{1}{f_{NVMOP}} + 25 \cdot \frac{1}{f_{bus}}$$

A.3.1.2 Burst Programming

This applies only to the Flash where up to 64 words in a row can be programmed consecutively using burst programming by keeping the command pipeline filled. The time to program a consecutive word can be calculated as:

$$t_{bwpgm} = 4 \cdot \frac{1}{f_{NVMOP}} + 9 \cdot \frac{1}{f_{bus}}$$

The time to program a whole row is:

$$t_{brpgm} = t_{swpgm} + 63 \cdot t_{bwpgm}$$

Burst programming is more than 2 times faster than single word programming.

A.3.1.3 Sector Erase

Erasing a 1024 byte Flash sector or a 4 byte EEPROM sector takes:

$$t_{era} \approx 4000 \cdot \frac{1}{f_{NVMOP}}$$

The setup time can be ignored for this operation.

A.3.1.4 Mass Erase

Erasing a NVM block takes:

$$t_{mass} \approx 20000 \cdot \frac{1}{f_{NVMOP}}$$

The setup time can be ignored for this operation.

A.3.1.5 Blank Check

The time it takes to perform a blank check on the Flash or EEPROM is dependant on the location of the first non-blank word starting at relative address zero. It takes one bus cycle per word to verify plus a setup of the command.

$$t_{check} \approx location \cdot t_{cyc} + 10 \cdot t_{cyc}$$

Table A-15 NVM Timing Characteristics

Condit	ions	s are shown in Table A-4 unless otherwise noted					
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	D	External Oscillator Clock	f _{NVMOSC}	0.5		80 ¹	MHz
2	D	Bus frequency for Programming or Erase Operations	f _{NVMBUS}	1			MHz
3	D	Operating Frequency	f _{NVMOP}	150		200	kHz
4	Р	Single Word Programming Time	t _{swpgm}	46 ²		74.5 ³	μs
5	D	Flash Burst Programming consecutive word ⁴	t _{bwpgm}	20.4 (2)		31 ⁽³⁾	μs
6	D	Flash Burst Programming Time for 64 Words ⁽⁴⁾	t _{brpgm}	1331.2 ⁽²⁾		2027.5 ⁽³⁾	μs
7	Р	Sector Erase Time	t _{era}	20 ⁵		26.7 ⁽³⁾	ms
8	Р	Mass Erase Time	t _{mass}	100 ⁽⁵⁾		133 ⁽³⁾	ms
9	D	Blank Check Time Flash per block	t _{check}	11 ⁶		65546 ⁷	t _{cyc}
10	D	Blank Check Time EEPROM per block	t _{check}	11 ⁽⁶⁾		2058 ⁽⁷⁾	t _{cyc}

- 1. Restrictions for oscillator in crystal mode apply!
- 2. Minimum Programming times are achieved under maximum NVM operating frequency f_{NVMOP} and maximum bus frequency f_{bus} .

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- 3. Maximum Erase and Programming times are achieved under particular combinations of f_{NVMOP} and bus frequency f_{bus}. Refer to formulae in Sections Section A.3.1.1 Single Word Programming- Section A.3.1.4 Mass Erasefor guidance.
- 4. Burst Programming operations are not applicable to EEPROM
- 5. Minimum Erase times are achieved under maximum NVM operating frequency f_{NVMOP}.
- 6. Minimum time, if first word in the array is not blank
- 7. Maximum time to complete check on an erased block

A.3.2 NVM Reliability

The reliability of the NVM blocks is guaranteed by stress test during qualification, constant process monitors and burn-in to screen early life failures.

The failure rates for data retention and program/erase cycling are specified at the operating conditions noted.

The program/erase cycle count on the sector is incremented every time a sector or mass erase event is executed.

NOTE: All values shown in **Table A-16** are target values and subject to further extensive characterization.

Table A-16 NVM Reliability Characteristics

Condit	Conditions are shown in Table A-4 unless otherwise noted									
Num	С	Rating	Symbol	Min	Тур	Max	Unit			
1	С	Data Retention at an average junction temperature of $T_{Javg} = 70^{\circ}C$	t _{NVMRET}	15			Years			
2	С	Flash number of Program/Erase cycles	n _{FLPE}	1000	10,000		Cycles			
3	С	EEPROM number of Program/Erase cycles (–40°C \leq T _J \leq 0°C)	n _{EEPE}	10,000			Cycles			
4	С	EEPROM number of Program/Erase cycles $(0^{\circ}\text{C} < \text{T}_{\text{J}} \le 140^{\circ}\text{C})$	n _{EEPE}	100,000			Cycles			

A.4 Voltage Regulator

Table 27-2 Voltage Regulator Electrical Characteristics

Num	С	Characteristic	Symbol	Min	Typical	Max	Unit
1	Р	Input Voltages	V _{VDDR,A}	3.15	_	5.5	V
2	Р	Regulator Current Reduced Power Mode Shutdown Mode	I _{REG}	_ _	20 12	50 40	μ Α μ Α
3	Р	Output Voltage Core Full Performance Mode Reduced Power Mode Shutdown Mode	V _{DD}	2.35 1.6 —	2.5 2.5 1	2.75 2.75 —	< < <
4	Р	Output Voltage PLL Full Performance Mode Reduced Power Mode ² Reduced Power Mode ³ Shutdown Mode	V _{DDPLL}	2.35 2.0 1.6 —	2.5 2.5 2.5 4	2.75 2.75 2.75 —	> > >
7	Р	Low Voltage Interrupt ⁵ Assert Level Deassert Level	V _{LVIA} V _{LVID}	4.1 4.25	4.37 4.52	4.66 4.77	V V
8	Р	Low Voltage Reset ⁶ Assert Level	V _{LVRA}	2.25	_	_	V
9	С	Power-on Reset ⁷ Assert Level Deassert Level	V _{PORA} V _{PORD}	0.97 —	_	 2.05	V V
12	С	Trimmed API internal clock Δf / f _{nominal}	df _{API}	- 10%	_	+ 10%	_

NOTES:

- 1. High Impedance Output
- 2. Current IDDPLL = 1mA (loop controlled Pierce Oscillator)
- 3. Current IDDPLL = 3mA (loop controlled Pierce Oscillator)
- 4. High Impedance Output
- Monitors V_{DDA}, active only in Full Performance Mode. Indicates I/O & ADC performance degradation due to low supply voltage.
- 6. Monitors V_{DD}, active only in Full Performance Mode. MCU is monitored by the POR in RPM (see Figure A-1)
- 7. Monitors V_{DD}. Active in all modes.

NOTE: The electrical characteristics given in this section are preliminary and should be used as a guide only. Values in this section cannot be guaranteed by Motorola and are subject to change without notice.

A.5 Reset, Oscillator and PLL

This section summarizes the electrical characteristics of the various startup scenarios for Oscillator and Phase-Locked-Loop (PLL).

A.5.1 Startup

Table A-17 summarizes several startup characteristics explained in this section. Detailed description of the startup behavior can be found in the Clock and Reset Generator (CRG) Block Guide.

Table A-17 Startup Characteristics

Condit	Conditions are shown in Table A-4 unless otherwise noted									
Num	С	Rating	Symbol	Min	Тур	Max	Unit			
1	D	Reset input pulse width, minimum input time	PW _{RSTL}	2			t _{osc}			
2	D	Startup from Reset	n _{RST}	192		196	n _{osc}			
3	D	Interrupt pulse width, IRQ edge-sensitive mode	PW _{IRQ}	20			ns			
4	D	Wait recovery startup time	t _{WRS}			14	t _{cyc}			

A.5.1.1 POR

The release level V_{PORR} and the assert level V_{PORA} are derived from the V_{DD} Supply. They are also valid if the device is powered externally. After releasing the POR reset the oscillator and the clock quality check are started. If after a time t_{CQOUT} no valid oscillation is detected, the MCU will start using the internal self clock. The fastest startup time possible is given by n_{uposc} .

A.5.1.2 SRAM Data Retention

Provided an appropriate external reset signal is applied to the MCU, preventing the CPU from executing code when VDD35 is out of specification limits, the SRAM contents integrity is guaranteed if after the reset the PORF bit in the CRG Flags Register has not been set.

A.5.1.3 External Reset

When external reset is asserted for a time greater than PW_{RSTL} the CRG module generates an internal reset, and the CPU starts fetching the reset vector without doing a clock quality check, if there was an oscillation before reset.

A.5.1.4 Stop Recovery

Out of STOP the controller can be woken up by an external interrupt. A clock quality check as after POR is performed before releasing the clocks to the system.

A.5.1.5 Pseudo Stop and Wait Recovery

The recovery from Pseudo STOP and Wait are essentially the same since the oscillator was not stopped in both modes. The controller can be woken up by internal or external interrupts. After t_{wrs} the CPU starts fetching the interrupt vector.

A.5.2 Oscillator

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The device features an internal low-power loop controlled Pierce oscillator and a full swing Pierce oscillator/external clock mode. The selection of loop controlled Pierce oscillator or full swing Pierce oscillator/external clock depends on the \overline{XCLKS} signal which is sampled during reset. Before asserting the oscillator to the internal system clocks the quality of the oscillation is checked for each start from either power-on, STOP or oscillator fail. t_{CQOUT} specifies the maximum time before switching to the internal self clock mode after POR or STOP if a proper oscillation is not detected. The quality check also determines the minimum oscillator start-up time t_{UPOSC} . The device also features a clock monitor. A Clock Monitor Failure is asserted if the frequency of the incoming clock signal is below the Assert Frequency f_{CMFA} .

Table A-18 Oscillator Characteristics

Conditio	ns a	are shown in Table A-1 unless otherwise noted					
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1a	С	Crystal oscillator range (loop controlled Pierce)	fosc	4.0		16	MHz
1b	С	Crystal oscillator range (full swing Pierce) 12	fosc	0.5		40	MHz
2	Р	Startup Current	iosc	100			μΑ
3	С	Oscillator start-up time (loop controlled Pierce)	t _{UPOSC}		TBD ³	50 ⁴	ms
4	D	Clock Quality check time-out	t _{CQOUT}	0.45		2.5	s
5	Р	Clock Monitor Failure Assert Frequency	f _{CMFA}	50	100	200	KHz
6	Р	External square wave input frequency	f _{EXT}	0.5		TBD	MHz
7	D	External square wave pulse width low	t _{EXTL}	TBD			ns
8	D	External square wave pulse width high	t _{EXTH}	TBD			ns
9	D	External square wave rise time	t _{EXTR}			TBD	ns
10	D	External square wave fall time	t _{EXTF}			TBD	ns
11	D	Input Capacitance (EXTAL, XTAL inputs)	C _{IN}		TBD		pF
12	Р	EXTAL Pin Input High Voltage ⁵	V _{IH,EXTAL}	0.75* V _{DDPLL}			V
12	Т	EXTAL Pin Input High Voltage ⁵	V _{IH,EXTAL}			V _{DDPLL} + 0.3	V
13	Р	EXTAL Pin Input Low Voltage ⁵	V _{IL,EXTAL}			0.25* V _{DDPLL}	V
	Т	EXTAL Pin Input Low Voltage ⁵	V _{IL,EXTAL}	V _{SSPLL} -0.3			V
14	С	EXTAL Pin Input Hysteresis ⁵	V _{HYS,EXTAL}		250		mV

- 1. Depending on the crystal a damping series resistor might be necessary
- 2. XCLKS =0
- 3. $f_{osc} = 4MHz$, C = 22pF.
- 4. Maximum value is for extreme cases using high Q, low frequency crystals
- 5. If full swing Pierce oscillator/external clock circuitry is used. (XCLKS=0)



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A.5.3 Phase Locked Loop

The oscillator provides the reference clock for the PLL. The PLL's Voltage Controlled Oscillator (VCO) is also the system clock source in self clock mode.

A.5.3.1 XFC Component Selection

This section describes the selection of the XFC components to achieve a good filter characteristics.

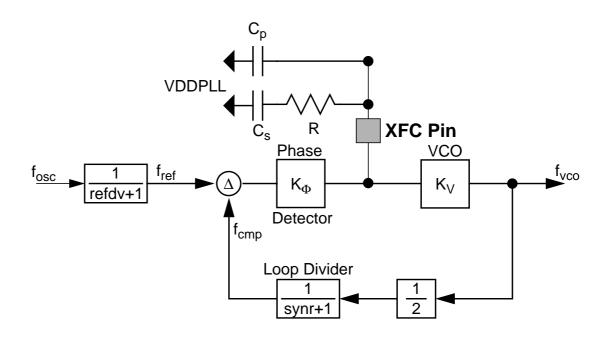


Figure A-2 Basic PLL functional diagram

The following procedure can be used to calculate the resistance and capacitance values using typical values for K_1 , f_1 and i_{ch} from **Table A-19**.

The grey boxes show the calculation for $f_{VCO} = 80 MHz$ and $f_{ref} = 4 MHz$. E.g., these frequencies are used for $f_{OSC} = 4 MHz$ and a 40MHz bus clock.

The VCO gain at the desired VCO frequency is approximated by:

$$K_V = K_1 \cdot e^{\frac{(f_1 - f_{vco})}{K_1 \cdot 1V}} = -195MHz/V \cdot e^{\frac{126 - 80}{-195}} = -154.0MHz/V$$

The phase detector relationship is given by:

$$K_{\Phi} = -|i_{ch}| \cdot K_{V} = -3.5 \mu A \cdot (-154 MHz/V) = 539.1 Hz/\Omega$$

ich is the current in tracking mode.

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The loop bandwidth f_C should be chosen to fulfill the Gardner's stability criteria by <u>at least</u> a factor of 10, typical values are 50. $\zeta = 0.9$ ensures a good transient response.

$$f_{C} < \frac{2 \cdot \zeta \cdot f_{ref}}{\pi \cdot \left(\zeta + \sqrt{1 + \zeta^{2}}\right)} \frac{1}{10} \rightarrow f_{C} < \frac{f_{ref}}{4 \cdot 10}; (\zeta = 0.9)$$

$$f_{C} < 100 \text{kHz}$$

And finally the frequency relationship is defined as

$$n = \frac{f_{VCO}}{f_{ref}} = 2 \cdot (synr + 1) = 20$$

With the above values the resistance can be calculated. The example is shown for a loop bandwidth $f_C=20kHz$:

$$R = \frac{2 \cdot \pi \cdot n \cdot f_C}{K_{\Phi}} = \frac{2 \cdot \pi \cdot 20 \cdot 20 kHz}{(539.1 Hz)/\Omega} = 4.7 k\Omega$$

The capacitance C_s can now be calculated as:

$$C_s = \frac{2 \cdot \zeta^2}{\pi \cdot f_C \cdot R} = \frac{0.516}{f_C \cdot R}; (\zeta = 0.9)$$
 = 5.5nF = ~ 4.7nF

The capacitance C_p should be chosen in the range of:

$$\frac{C_s}{20} \le C_p \le \frac{C_s}{10}$$

$$C_P = 470pF$$

A.5.3.2 Jitter Information

The basic functionality of the PLL is shown in **Figure A-2**. With each transition of the clock f_{cmp} , the deviation from the reference clock f_{ref} is measured and input voltage to the VCO is adjusted accordingly. The adjustment is done continuously with no abrupt changes in the clock output frequency. Noise, voltage, temperature and other factors cause slight variations in the control loop resulting in a clock jitter. This jitter affects the real minimum and maximum clock periods as illustrated in **Figure A-3**.

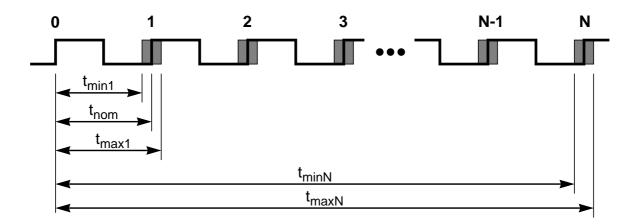


Figure A-3 Jitter Definitions

The relative deviation of t_{nom} is at its maximum for one clock period, and decreases towards zero for larger number of clock periods (N).

Defining the jitter as:

$$J(N) = \max \left(\left| 1 - \frac{t_{max}(N)}{N \cdot t_{nom}} \right|, \left| 1 - \frac{t_{min}(N)}{N \cdot t_{nom}} \right| \right)$$

For N < 1000, the following equation is a good fit for the maximum jitter:

$$J(N) = \frac{j_1}{\sqrt{N}} + j_2$$

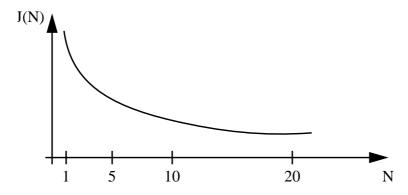


Figure A-4 Maximum bus clock jitter approximation

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This is very important to notice with respect to timers, serial modules where a pre-scaler will eliminate the effect of the jitter to a large extent.

Table A-19 PLL Characteristics

Condit	ions	s are shown in Table A-4 unless otherwise noted					
Num	С	Rating	Symbol	Min	Тур	Max	Unit
1	Р	Self Clock Mode frequency	f _{SCM}	1		5.5	MHz
2	D	VCO locking range	f _{VCO}	8		80	MHz
3	D	Lock Detector transition from Acquisition to Tracking mode	$ \Delta_{trk} $	3		4	% ¹
4	D	Lock Detection	Δ _{Lock}	0		1.5	% ⁽¹⁾
5	D	Un-Lock Detection	Δ _{unl}	0.5		2.5	% ⁽¹⁾
6	D	Lock Detector transition from Tracking to Acquisition mode	Δ _{unt}	6		8	% ⁽¹⁾
7	С	PLLON Total Stabilization delay (Auto Mode) ²	t _{stab}		0.24		ms
8	D	PLLON Acquisition mode stabilization delay (2)	t _{acq}		0.09		ms
9	D	PLLON Tracking mode stabilization delay (2)	t _{al}		0.16		ms
10	D	Fitting parameter VCO loop gain	K ₁		-195		MHz/V
11	D	Fitting parameter VCO loop frequency	f ₁		126		MHz
12	D	Charge pump current acquisition mode	i _{ch}		38.5		μА
13	D	Charge pump current tracking mode	i _{ch}		3.5		μА
14	С	Jitter fit parameter 1 ⁽²⁾	j ₁		0.9	1.3	%
15	С	Jitter fit parameter 2 ⁽²⁾	j ₂		0.02	0.12	%

- 1. % deviation from target frequency
- $2.~f_{osc} = 4 \text{MHz}, f_{BUS} = 40 \text{MHz} \text{ equivalent } f_{VCO} = 80 \text{MHz} \text{: REFDV} = \#\$00, \text{SYNR} = \#\$09, \text{Cs} = 4.7 \text{nF}, \text{Cp} = 470 \text{pF}, \text{Rs} = 4.7 \text{k}\Omega = 4.7 \text{nF}, \text{Cp} = 4.7 \text{nF},$

A.6 MSCAN

Table A-20 MSCAN Wake-up Pulse Characteristics

Condit	Conditions are shown in Table A-4 unless otherwise noted									
Num	С	Rating	Symbol	Min	Тур	Max	Unit			
1	Р	MSCAN Wake-up dominant pulse filtered	t _{WUP}			2	μs			
2	Р	MSCAN Wake-up dominant pulse pass	t _{WUP}	5			μs			

Appendix B Electrical Specifications

B.1 SPI Timing

This section provides electrical parametrics and ratings for the SPI.

In Table B-1 the measurement conditions are listed.

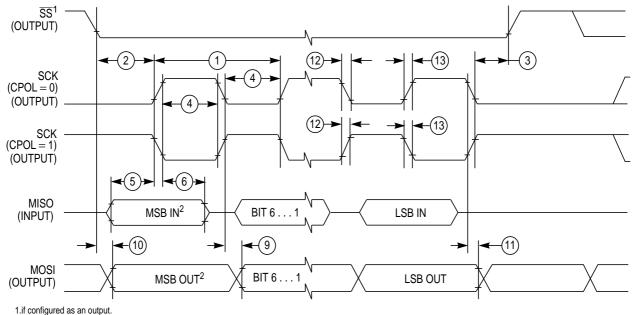
Table B-1 Measurement Conditions

Description	Value	Unit
Drive mode	full drive mode	_
Load capacitance C _{LOAD} ¹ , on all outputs	50	pF
Thresholds for delay measurement points	(20% / 80%) VDDX	V

NOTES:

B.1.1 Master Mode

In **Figure B-1** the timing diagram for master mode with transmission format CPHA=0 is depicted.



2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure B-1 SPI Master Timing (CPHA=0)

In Figure B-2 the timing diagram for master mode with transmission format CPHA=1 is depicted.

^{1.} Timing specified for equal load on all SPI output pins. Avoid asymmetric load.

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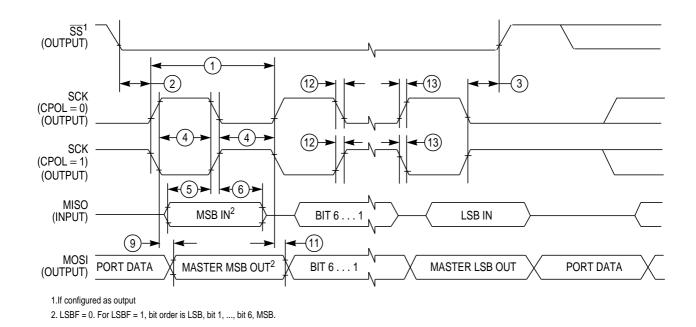


Figure B-2 SPI Master Timing (CPHA=1)

In **Table B-2** the timing characteristics for master mode are listed.

Table B-2 SPI Master Mode Timing Characteristics

Num	Characteristic	Symbol				Unit
Italii	Onaracteristic	Cymbol	Min	Тур	Max	Oilit
1	SCK Frequency	f _{sck}	1/2048	_	1/2	f _{bus}
1	SCK Period	t _{sck}	2	_	2048	t _{bus}
2	Enable Lead Time	t _{lead}	_	1/2	-	t _{sck}
3	Enable Lag Time	t _{lag}	_	1/2	_	t _{sck}
4	Clock (SCK) High or Low Time	t _{wsck}	_	1/2	-	t _{sck}
5	Data Setup Time (Inputs)	t _{su}	8	_	_	ns
6	Data Hold Time (Inputs)	t _{hi}	8	_	_	ns
9	Data Valid after SCK Edge	t _{vsck}	_	_	29	ns
10	Data Valid after SS fall (CPHA=0)	t _{vss}	_	_	15	ns
11	Data Hold Time (Outputs)	t _{ho}	20	_	-	ns
12	Rise and Fall Time Inputs	t _{rfi}	_	_	8	ns
13	Rise and Fall Time Outputs	t _{rfo}	_	_	8	ns

B.1.2 Slave Mode

In Figure B-3 the timing diagram for slave mode with transmission format CPHA=0 is depicted.

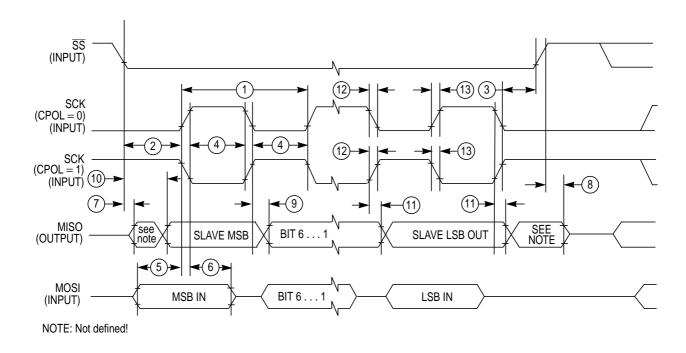


Figure B-3 SPI Slave Timing (CPHA=0)

In Figure A-4 the timing diagram for slave mode with transmission format CPHA=1 is depicted.

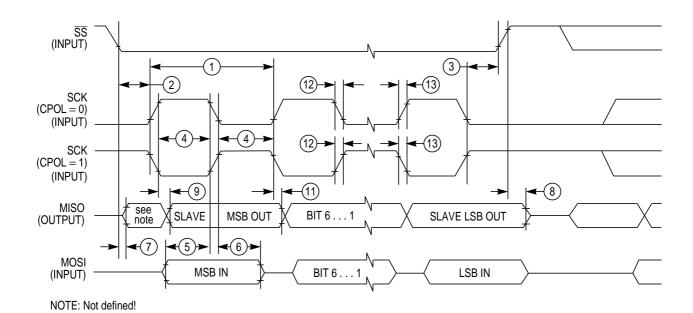


Figure B-4 SPI Slave Timing (CPHA=1)

In Table B-3 the timing characteristics for slave mode are listed.

Table B-3 SPI Slave Mode Timing Characteristics

Num	Characteristic	Symbol				Unit
Num	Onaracteristic	Symbol	Min	Тур	Max	Offic
1	SCK Frequency	f _{sck}	DC	_	1/4	f _{bus}
1	SCK Period	t _{sck}	4	_	∞	t _{bus}
2	Enable Lead Time	t _{lead}	4	_	_	t _{bus}
3	Enable Lag Time	t _{lag}	4	_	_	t _{bus}
4	Clock (SCK) High or Low Time	t _{wsck}	4	_	_	t _{bus}
5	Data Setup Time (Inputs)	t _{su}	8	_	_	ns
6	Data Hold Time (Inputs)	t _{hi}	8	_	_	ns
7	Slave Access Time (time to data active)	t _a	_	_	20	ns
8	Slave MISO Disable Time	t _{dis}	_	_	22	ns
9	Data Valid after SCK Edge	t _{vsck}	_	_	$29 + 0.5 \cdot t_{bus}^{1}$	ns
10	Data Valid after SS fall	t _{vss}	_	_	$29 + 0.5 \cdot t_{bus}^{1}$	ns
11	Data Hold Time (Outputs)	t _{ho}	20	_	_	ns
12	Rise and Fall Time Inputs	t _{rfi}	_	_	8	ns
13	Rise and Fall Time Outputs	t _{rfo}	_	_	8	ns

NOTES:

1. 0.5t_{bus} added due to internal synchronization delay

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B.2 External Bus Timing

The following conditions are assumed for all following external bus timing values:

- Crystal input within 45% to 55% duty
- Equal loads of pins
- Pad full drive (reduced drive must be off)

B.2.1 Normal Expanded Mode (external wait feature disabled)

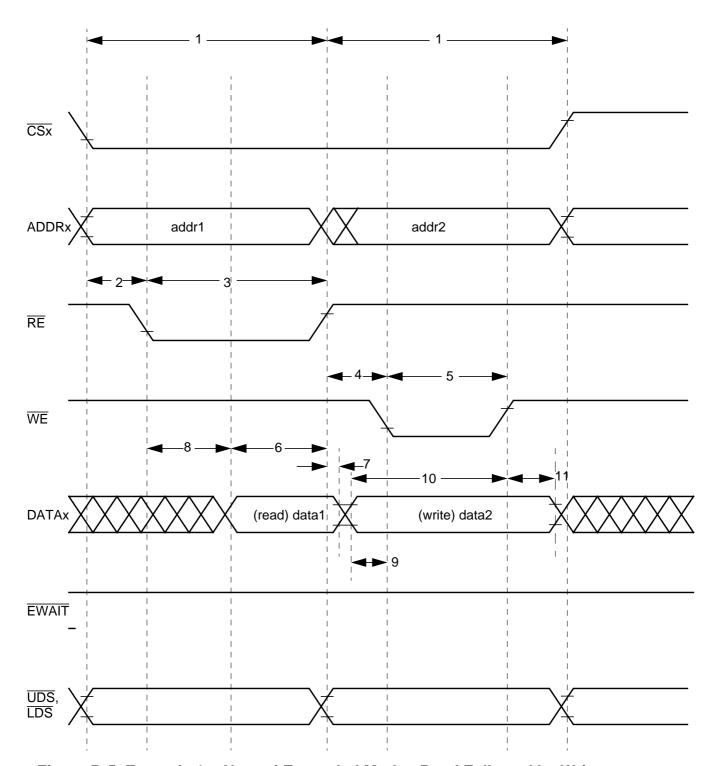


Figure B-5 Example 1a: Normal Expanded Mode - Read Followed by Write { statement }

Table B-4 Example 1a: Normal Expanded Mode Timing V_{DD35} =5.0V (EWAITE = 0)

No.	С	Characteristic	Symbol	Min	Max	Unit
-	-	Frequency of internal bus	f _i	D.C.	40.0	MHz
-	-	Internal cycle time	t _{cyc}	25	8	ns
-	-	Frequency of external bus	f _o	D.C.	20.0	MHz
1	-	External cycle time (selected by EXSTR)	t _{cyce}	50	8	ns
2	D	Address ¹ valid to RE fall	t _{ADRE}	5	-	ns
3	D	Pulse width, RE	PW _{RE}	35	-	ns
4	D	Address ¹ valid to WE fall	t _{ADWE}	5	-	ns
5	D	Pulse width, WE	PW _{WE}	23	-	ns
6	D	Read data setup time (if ITHRS = 0)	t _{DSR}	24	-	ns
0	С	Read data setup time (if ITHRS = 1)	t _{DSR}		-	ns
7	D	Read data hold time	t _{DHR}	0	-	ns
8	D	Read enable access time	t _{ACCR}	11	-	ns
9	D	Write data valid to WE fall	t _{WDWE}	7	-	ns
10	D	Write data setup time	t _{DSW}	31	-	ns
11	D	Write data hold time	t _{DHW}	8	-	ns

NOTES:

Table B-5 Example 1a: Normal Expanded Mode Timing V_{DD35}=3.0V (EWAITE = 0)
All values: To Be Defined!

No.	С	Characteristic	Symbol	Min	Max	Unit
-	-	Frequency of internal bus	f _i	D.C.	40.0	MHz
-	-	Internal cycle time	t _{cyc}	25	8	ns
-	-	Frequency of external bus	f _o	D.C.	20.0	MHz
1	-	External cycle time (selected by EXSTR)	t _{cyce}	50	8	ns
2	С	Address ¹ valid to RE fall	t _{ADRE}		-	ns
3	С	Pulse width, RE	PW _{RE}		-	ns
4	С	Address ¹ valid to WE fall	t _{ADWE}		-	ns
5	С	Pulse width, WE	PW _{WE}		-	ns
6	С	Read data setup time (if ITHRS = 0)	t _{DSR}		-	ns
"	С	Read data setup time (if ITHRS = 1)	t _{DSR}	N	/A	ns
7	С	Read data hold time	t _{DHR}		-	ns
8	С	Read enable access time	t _{ACCR}		-	ns
9	С	Write data valid to WE fall	t _{WDWE}		-	ns
10	С	Write data setup time	t _{DSW}		-	ns
11	С	Write data hold time	t _{DHW}		-	ns

^{1.} Includes the following signals: ADDRx, $\overline{\text{UDS}}$, $\overline{\text{LDS}}$, and $\overline{\text{CSx}}$.

^{1.} Includes the following signals: ADDRx, $\overline{\text{UDS}}$, $\overline{\text{LDS}}$, and $\overline{\text{CSx}}$.

B.2.2 Normal Expanded Mode (external wait feature enabled)

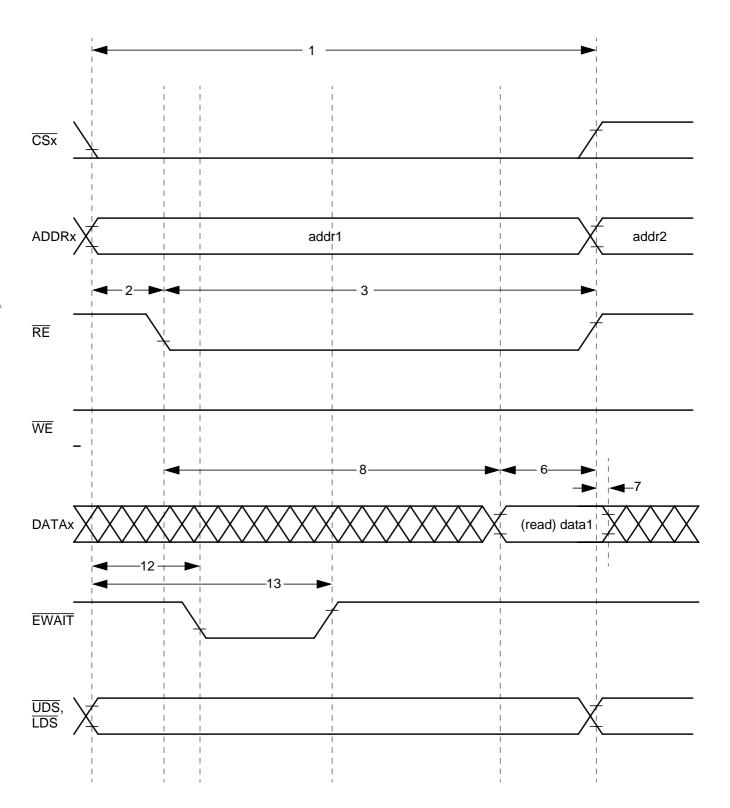


Figure B-6 Example 1b: Normal Expanded Mode - Stretched Read Access

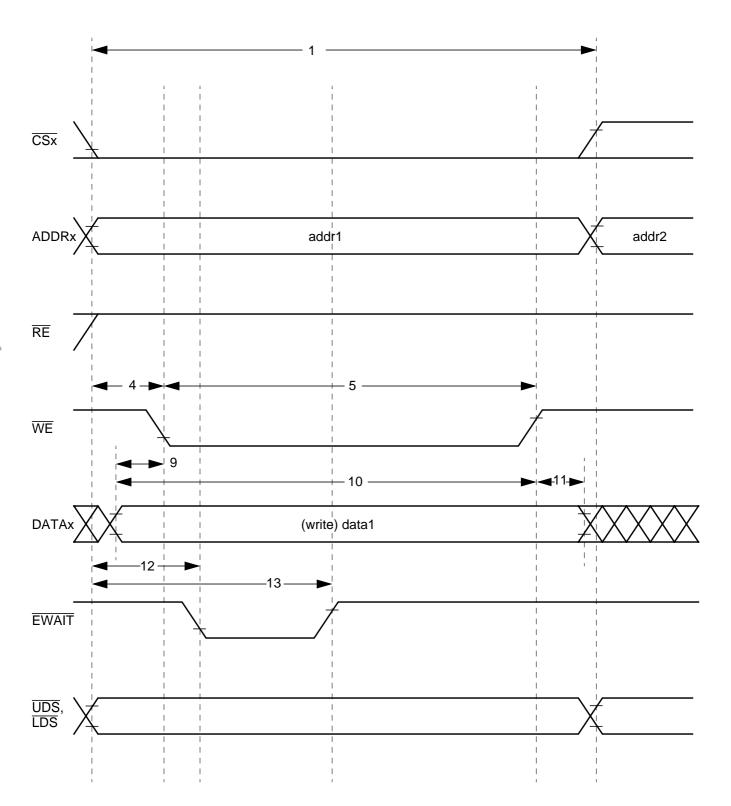


Figure B-7 Example 1b: Normal Expanded Mode - Stretched Write Access

Table B-6 Example 1b: Normal Expanded Mode Timing V_{DD35} =5.0V (EWAITE = 1)

No.	С	Characteristic	Symbol	2 stretch cycles		3 stretch cycles		Unit	
				Min	Max	Min	Max		
-	-	Frequency of internal bus	f _i	D.C.	40.0	D.C.	40.0	MHz	
-	-	Internal cycle time	t _{cyc}	25	8	25	∞	ns	
-	-	Frequency of external bus	f _o	D.C.	13.3	D.C.	10.0	MHz	
-	-	External cycle time (selected by EXSTR)	t _{cyce}	75	8	100	∞	ns	
1	-	External cycle time (EXSTR+1EWAIT)	t _{cycew}	100	8	125	∞	ns	
2	D	Address ¹ valid to RE fall	t _{ADRE}	5	-	5	-	ns	
3	D	Pulse width, RE ²	PW _{RE}	85	-	110	-	ns	
4	D	Address ¹ valid to WE fall	t _{ADWE}	5	-	5	-	ns	
5	D	Pulse width, WE ²	PW _{WE}	73	-	98	-	ns	
	D	Read data setup time (if ITHRS = 0)	t _{DSR}	24	-	24	-	ns	
6	С	Read data setup time (if ITHRS = 1)	t _{DSR}		-		-	ns	
7	D	Read data hold time	t _{DHR}	0	-	0	-	ns	
8	D	Read enable access time ²	t _{ACCR}	71	-	86	-	ns	
9	D	Write data valid to WE fall	t _{WDWE}	7	-	7	-	ns	
10	D	Write data setup time ²	t _{DSW}	81	-	106	-	ns	
11	D	Write data hold time	t _{DHW}	8	-	8	-	ns	
12	D	Address to EWAIT fall	t _{ADWF}	0	20	0	45	ns	
13	D	Address to EWAIT rise	t _{ADWR}	37	47	62	72	ns	
	•	•					•		

- 1. Includes the following signals: ADDRx, \overline{UDS}, \overline{LDS}, and \overline{CSx}.
- 2. Affected by $\overline{\mathsf{EWAIT}}$.

Table B-7 Example 1b: Normal Expanded Mode Timing V_{DD35}=3.0V (EWAITE = 1)
All values: To Be Defined!

No.	С	Characteristic	Symbol	2 stretch cycles		3 stretch cycles		Unit
				Min	Max	Min	Max	
-	-	Frequency of internal bus	f _i	D.C.	40.0	D.C.	40.0	MHz
-	-	Internal cycle time	t _{cyc}	25	∞	25	∞	ns
-	-	Frequency of external bus	f _o	D.C.	13.3	D.C.	10.0	MHz
-	-	External cycle time (selected by EXSTR)	t _{cyce}	75	∞	100	∞	ns
1	-	External cycle time (EXSTR+1EWAIT)	t _{cycew}	100	∞	125	∞	ns
2	С	Address ¹ valid to RE fall	t _{ADRE}		-		-	ns
3	С	Pulse width, RE ²	PW _{RE}		-		-	ns
4	С	Address ¹ valid to WE fall	t _{ADWE}		-		-	ns
5	С	Pulse width, WE ²	PW _{WE}		-		-	ns

Table B-7 Example 1b: Normal Expanded Mode Timing V_{DD35}=3.0V (EWAITE = 1) All values: To Be Defined!

No.	С	Characteristic	Symbol	2 stretch cycles		3 stretch cycles		Unit
				Min	Max	Min	Max	
6	С	Read data setup time (if ITHRS = 0)	t _{DSR}		-		-	ns
"	С	Read data setup time (if ITHRS = 1)	t _{DSR}	N/A				ns
7	С	Read data hold time	t _{DHR}		-		-	ns
8	С	Read enable access time ²	t _{ACCR}		-		-	ns
9	С	Write data valid to WE fall	t _{WDWE}		-		-	ns
10	С	Write data setup time ²	t _{DSW}		-		-	ns
11	С	Write data hold time	t _{DHW}		-		-	ns
12	С	Address to EWAIT fall	t _{ADWF}					ns
13	С	Address to EWAIT rise	t _{ADWR}					ns

- 1. Includes the following signals: ADDRx, $\overline{\text{UDS}}$, $\overline{\text{LDS}}$, and $\overline{\text{CSx}}$.
- 2. Affected by $\overline{\mathsf{EWAIT}}$.

B.2.3 Emulation Single-Chip Mode (without wait states)

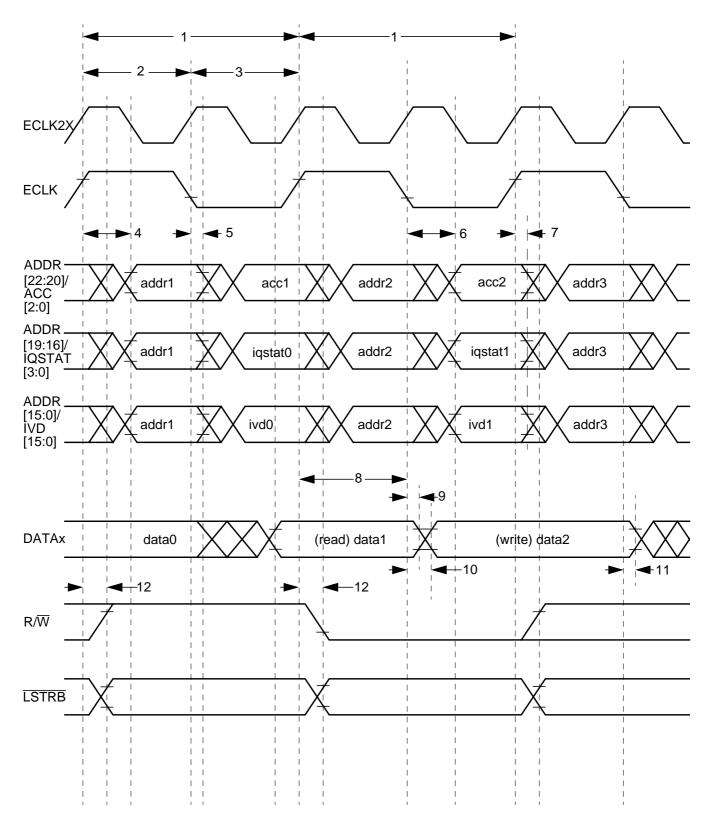


Figure B-8 Example 2a: Emulation Single-Chip Mode - Read Followed by Write

Table B-8 Example 2a: Emulation Single-Chip Mode Timing V_{DD35} =5.0V (EWAITE = 0)

No.	С	Characteristic ¹	Symbol	Min	Max	Unit
-	-	Frequency of internal bus	f _i	D.C.	40.0	MHz
1	-	Cycle time	t _{cyc}	25	∞	ns
2	D	Pulse width, E high	PW _{EH}	11.5	-	ns
3	D	Pulse width, E low	PW _{EL}	11.5	-	ns
4	D	Address delay time	t _{AD}	-	5	ns
5	D	Address hold time	t _{AH}	0	-	ns
6	D	IVDx delay time ²	t _{IVDD}	-	4.5	ns
7	D	IVDx hold time ²	t _{IVDH}	0	-	ns
8	D	Read data setup time (ITHRS = 1 only)	t _{DSR}	12	-	ns
9	D	Read data hold time	t _{DHR}	0	-	ns
10	D	Write data delay time	t _{DDW}	-	5	ns
11	D	Write data hold time	t _{DHW}	0	-	ns
12	D	Read/write data delay time ³	t _{RWD}	-1	5	ns

- 1. Typical Supply and Silicon, Room Temperature Only
- Includes also ACCx, IQSTATx
 Includes LSTRB

B.2.4 Emulation Expanded Mode (with optional access stretching)

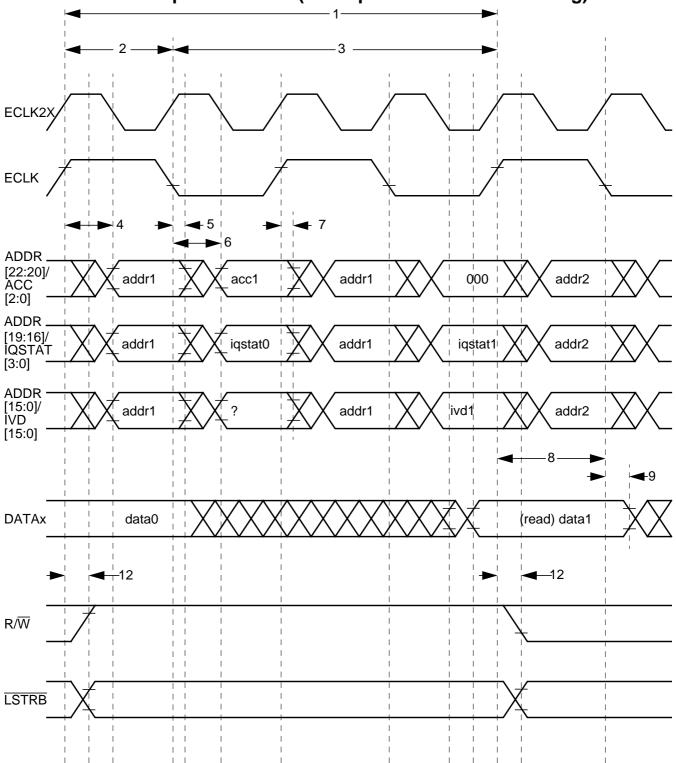


Figure B-9 Example 2b: Emulation Expanded Mode - Read with 1 Stretch Cycle

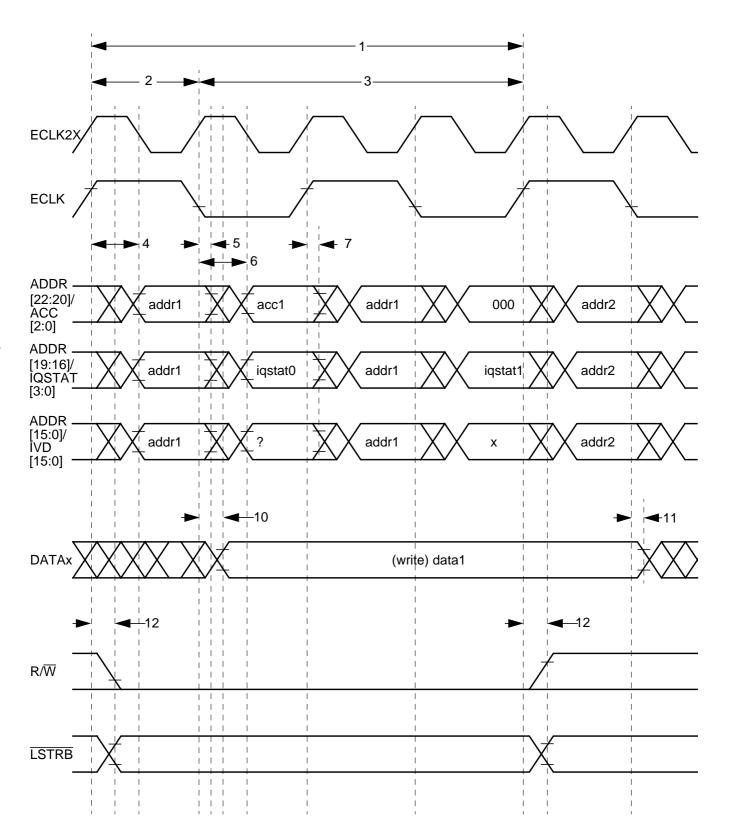


Figure B-10 Example 2b: Emulation Expanded Mode - Write with 1 Stretch Cycle

Table B-9 Example 2b: Emulation Expanded Mode Timing V_{DD35} =5.0V (EWAITE = 0)

No.	С	Characteristic ¹	Symbol	1 stretch cycle		2 stretch cycles		3 stretch cycles		Unit
				Min	Max	Min	Max	Min	Max	1
-	-	Internal cycle time	t _{cyc}	25	25	25	25	25	25	ns
1	-	Cycle time	t _{cyce}	50	∞	75	∞	100	∞	ns
2	D	Pulse width, E high	PW _{EH}	11.5	14	11.5	14	11.5	14	ns
3	D	E falling to sampling E rising	t _{EFSR}	35	39.5	60	64.5	85	89.5	ns
4	D	Address delay time	t _{AD}	-	5	-	5	-	5	ns
5	D	Address hold time	t _{AH}	0	-	0	-	0	-	ns
6	D	IVD delay time ²	t _{IVDD}	-	4.5	-	4.5	-	4.5	ns
7	D	IVD hold time ²	t _{IVDH}	0	-	0	-	0	-	ns
8	D	Read data setup time	t _{DSR}	12	-	12	-	12	-	ns
9	D	Read data hold time	t _{DHR}	0	-	0	-	0	-	ns
10	D	Write data delay time	t _{DDW}	-	5	-	5	-	5	ns
11	D	Write data hold time	t _{DHW}	0	-	0	-	0	-	ns
12	D	Read/write data delay time ³	t _{RWD}	-1	5	-1	5	-1	5	ns

- 1. Typical Supply and Silicon, Room Temperature Only 2. Includes also ACCx, IQSTATx
- 3. Includes LSTRB

B.3 External Tag Trigger Timing

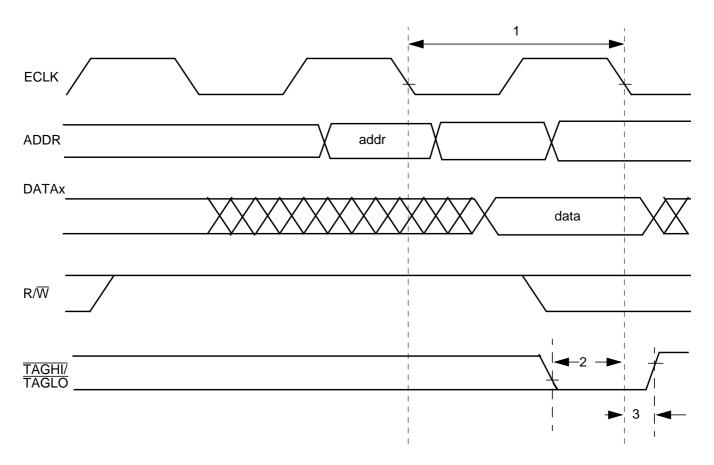


Figure B-11 External Trigger Timing

Table B-10 External Tag Trigger Timing VDD35=5.0V

No.	С	Characteristic ¹	Symbol	Min	Max	Unit
-	-	Frequency of internal bus	f _i	D.C.	40.0	MHz
1	-	Cycle time	t _{cyc}	25	∞	ns
2	D	TAGHI/LO setup time	t _{TS}	11.5	-	ns
3	D	TAGHI/LO hold time	t _{TH}	0	-	ns

NOTES:

1. Typical Supply and Silicon, Room Temperature Only

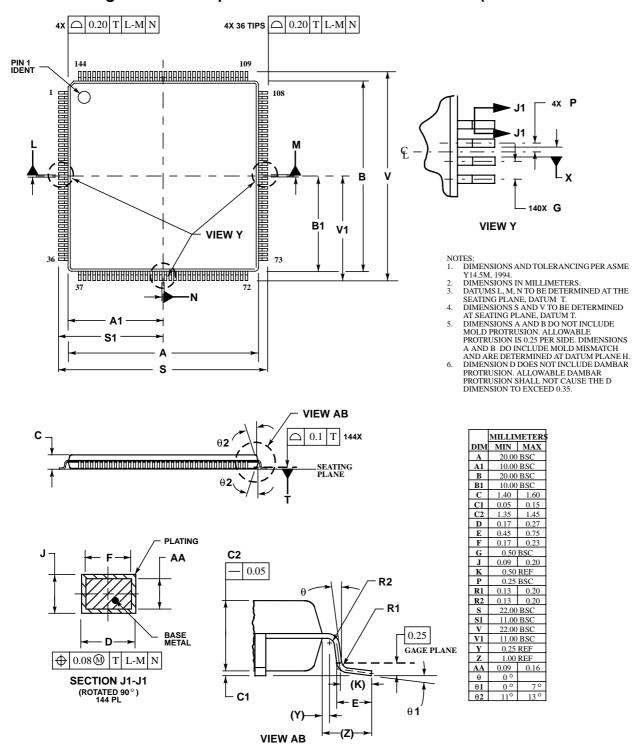
Appendix C Package Information

C.1 General

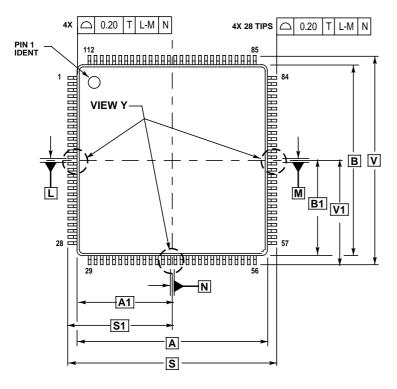
This section provides the physical dimensions of the MC9S12XDP512 packages.

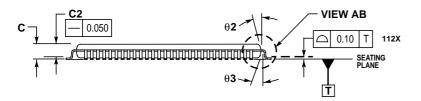
C.2 144-pin LQFP

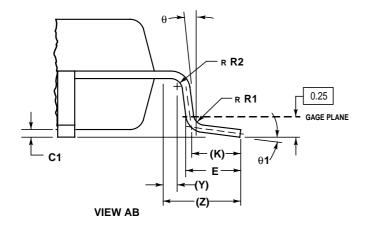
Figure 27-4 144-pin LQFP Mechanical Dimensions (case no. 918-03

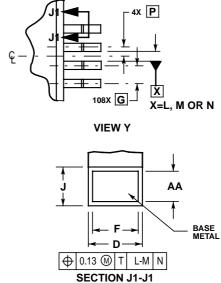


C.3 112-pin LQFP package









NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 DIMENSIONS IN MILLIMETERS.

ROTATED 90 ° COUNTERCLOCKWISE

- 2. DATUMS L, M AND N TO BE DETERMINED AT SEATING PLANE, DATUM T. 4. DIMENSIONS S AND V TO BE DETERMINED AT
- SEATING PLANE, DATUM T.

 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS A AND B INCLUDE MOLD MISMATCH.
- AND B INCLUDE MISSIAL CH.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.46.

	MILLIMETERS				
DIM	MIN	MAX			
Α	20.000 BSC				
A1	10.000 BSC				
В	20.000 BSC				
B1	10.000 BSC				
С		1.600			
C1	0.050	0.150			
C2	1.350	1.450			
D	0.270	0.370			
Е	0.450	0.750			
F	0.270	0.330			
G	0.650	BSC			
J	0.090	0.170			
K	0.500 REF				
P	0.325 BSC				
R1	0.100	0.200			
R2	0.100	0.200			
S	22.000 BSC				
S1	11.000 BSC				
٧	22.000 BSC				
V1	11.000 BSC				
Υ	0.250 REF				
Z	1.000 REF				
AA	0.090	0.160			
θ	0°	8 °			
θ1	3 °	7 °			
θ2	11 °	13 °			
θ3	11 °	13 °			

Figure C-1 112-pin LQFP mechanical dimensions (case no. 987)

C.4 80-pin QFP package

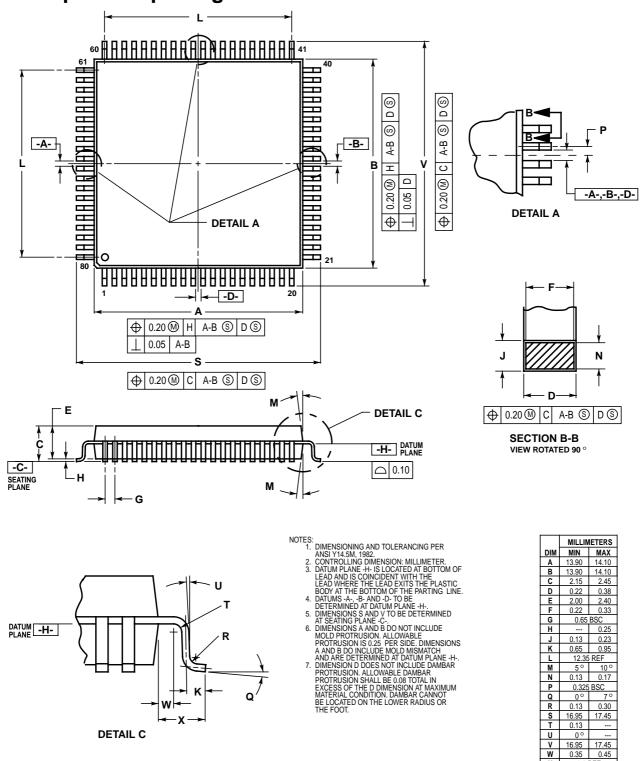


Figure C-2 80-pin QFP Mechanical Dimensions (case no. 841B)

User Guide End Sheet

FINAL PAGE OF 176 PAGES